

First results from the Timepix4 Telescope

Kevin Heijhoff — on behalf of the Timepix4 Telescope group
HSTD13 — 4 December 2023

People involved

Testbeam crew

Nikhef: Kazu Akiba, Martin van Beuzekom, Tjip Bischoff, Robbert Geertsema, Kevin Heijhoff, Daan Oppenhuis, Ganrong Wang

CERN: Federico De Benedetti, Wiktor Byczynski, Victor Coco, Raphael Dumps, Mohammadtaghi Hajheidari

IGFAE: Edgar Lemos Cid, Efrén Rodríguez Rodríguez

TU Dortmund: Elena Dall'Occo, David Rolf

University of Manchester/CERN: Tim Evans

University of Oxford: David Bacher, Rui Gao, Fernanda Goncalves Abrantes, Tommaso Pajero,

University of Birmingham: Dan Johnson, Marcus Jonathan Madurai

University of Glasgow: Naomi Cooke, Aleksandrina Docheva

And acknowledgements to everyone making this possible, including

Richard Bates, Vincent van Beveren, Henk Boterenbrood, Paula Collins, Maarten van Dijk, Martin Fransen, Abraham Gallas Torreira, Vladimir Gromov, Bas van der Heijden, Malcolm John, Xavi Llopart, Loris Martinazolli, and Heinrich Schindler

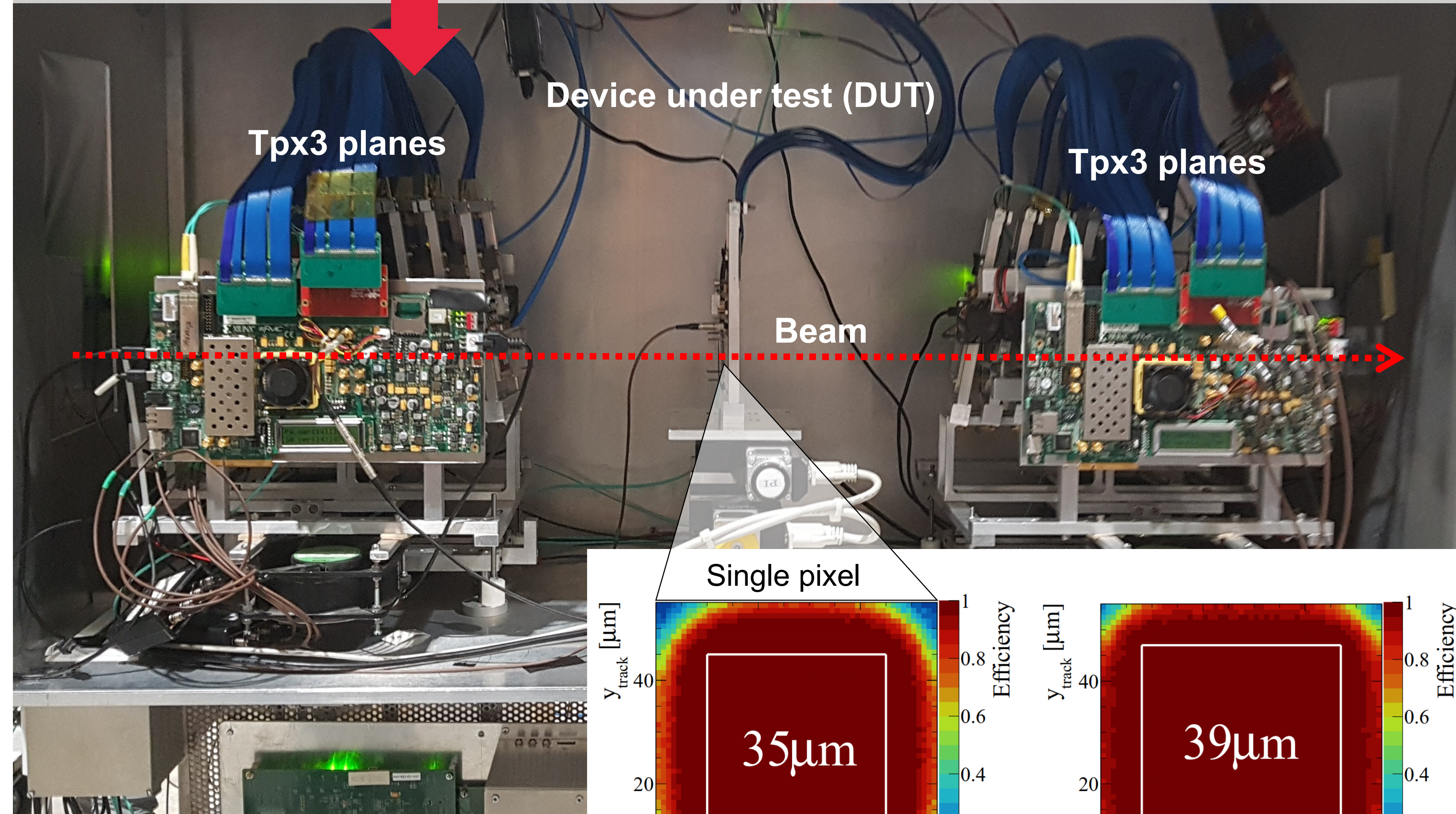
Successor to the LHCb VELO Timepix3 Telescope (2013–2019)

Timepix3 telescope:

- 1.6 μm pointing resolution

Timepix4 telescope goal:

- Study prototype sensors for 4D trackers at high rate
- < 50 ps track-time resolution at high rate



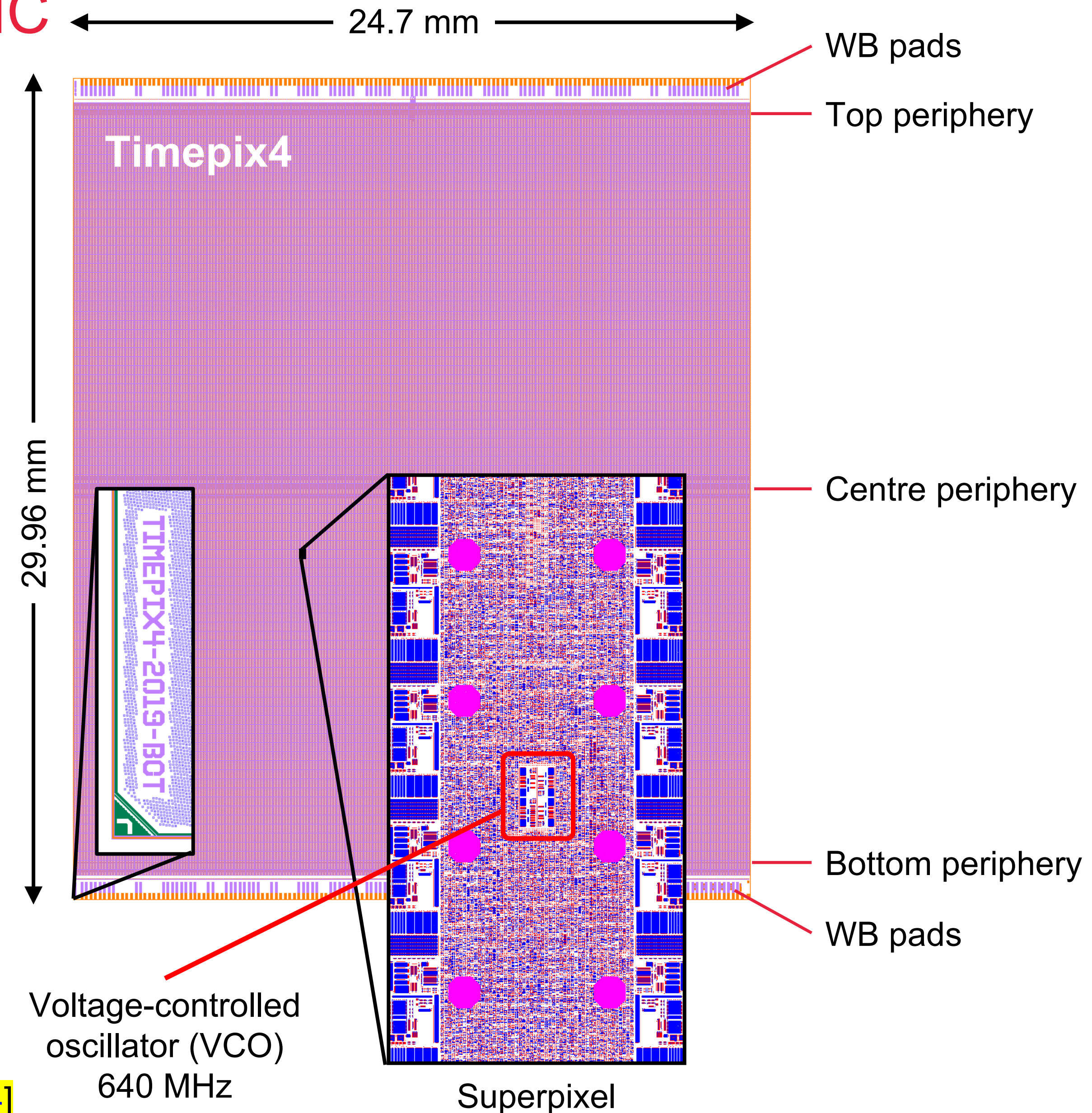
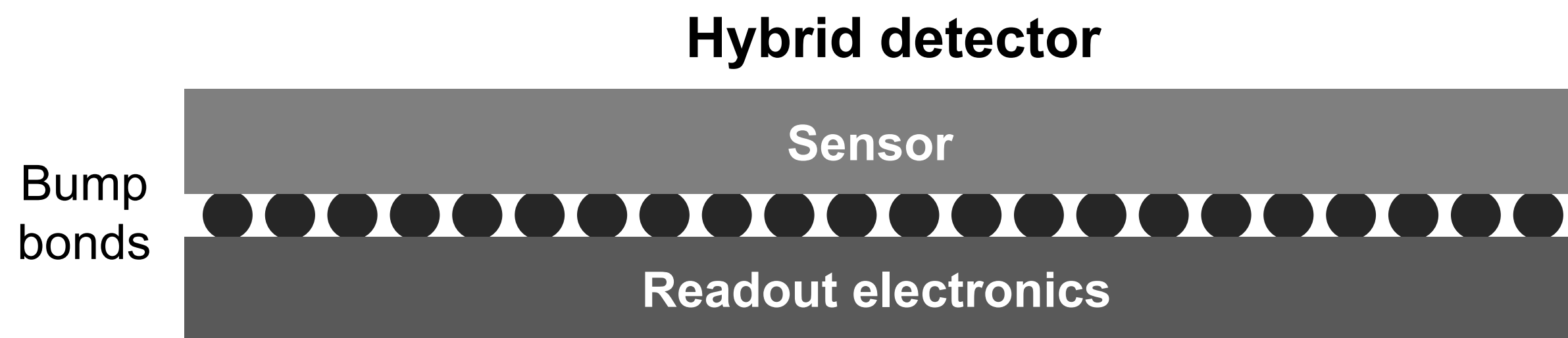
K. Akiba *et al* 2019 *JINST* 14 P05026
[DOI: [10.1088/1748-0221/14/05/P05026](https://doi.org/10.1088/1748-0221/14/05/P05026)]

K. Heijhoff *et al* 2020 *JINST* 15 P09035
[DOI: [10.1088/1748-0221/15/09/P09035](https://doi.org/10.1088/1748-0221/15/09/P09035)]

E. Buchanan *et al* 2022 *JINST* 17 P06038
[DOI: [10.1088/1748-0221/17/06/P06038](https://doi.org/10.1088/1748-0221/17/06/P06038)]

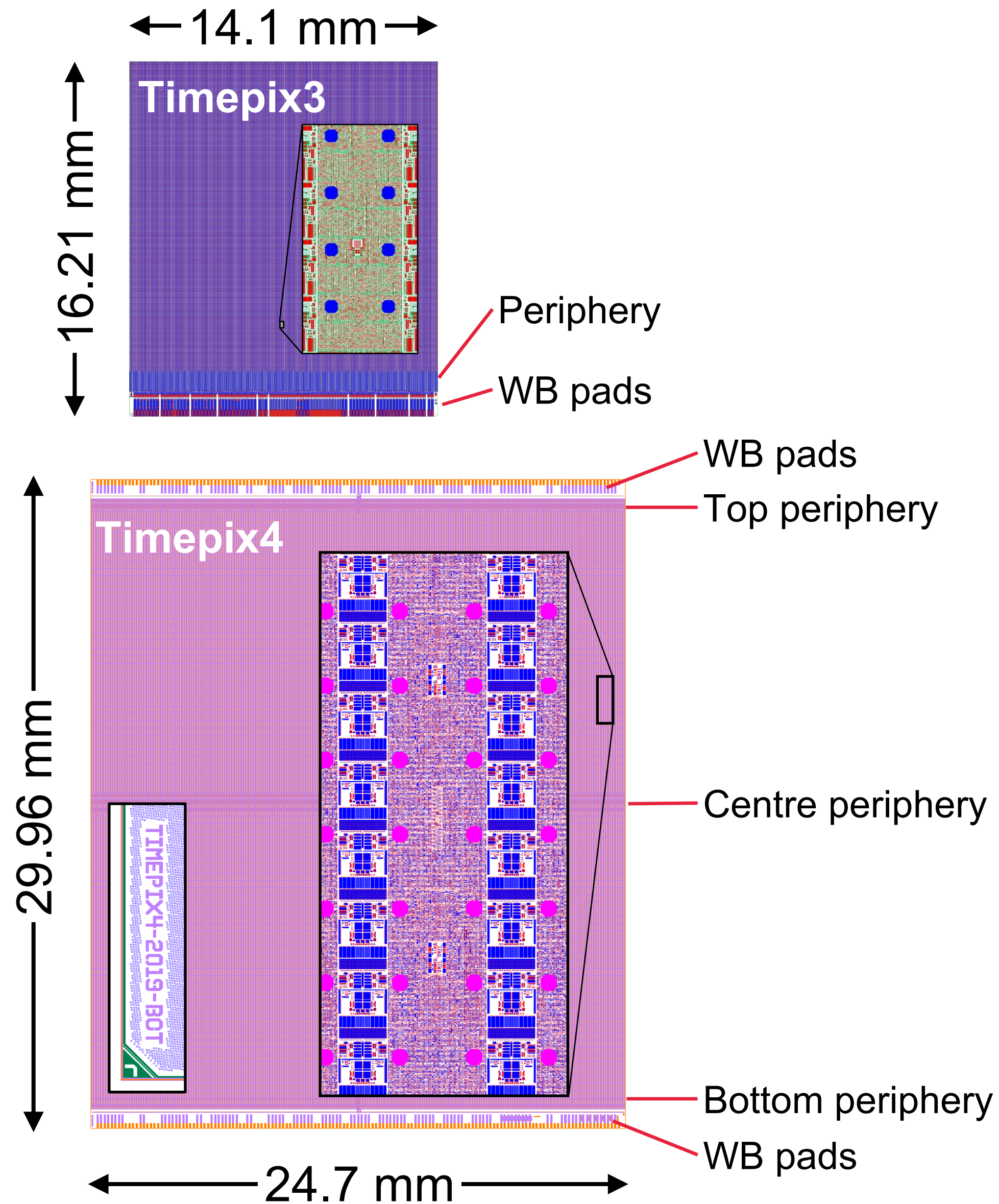
Timepix4: Hybrid pixel detector readout ASIC

- Developed by CERN, Nikhef, and IFAE
- 65 nm CMOS
- 448×512 pixels, 55×55 μm^2 pitch
- Simultaneous measurement of time and charge deposition (by measuring time over threshold)
- Time-bin size of 25 ns/128 = **195 ps** (Timepix3: 1.56 ns)
- Max rate: 360×10^6 hits/cm²/s (160 Gb/s for single chip)



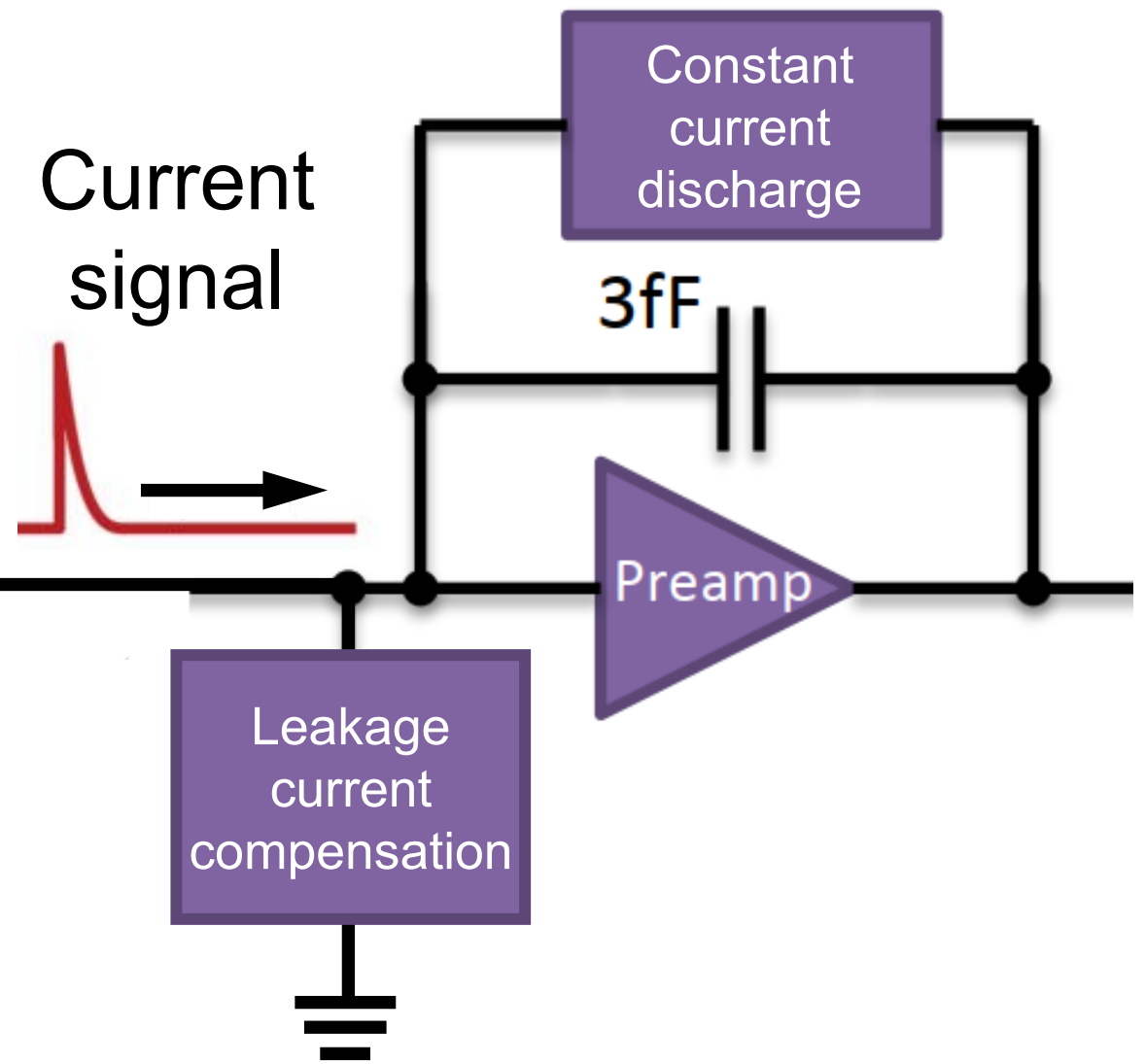
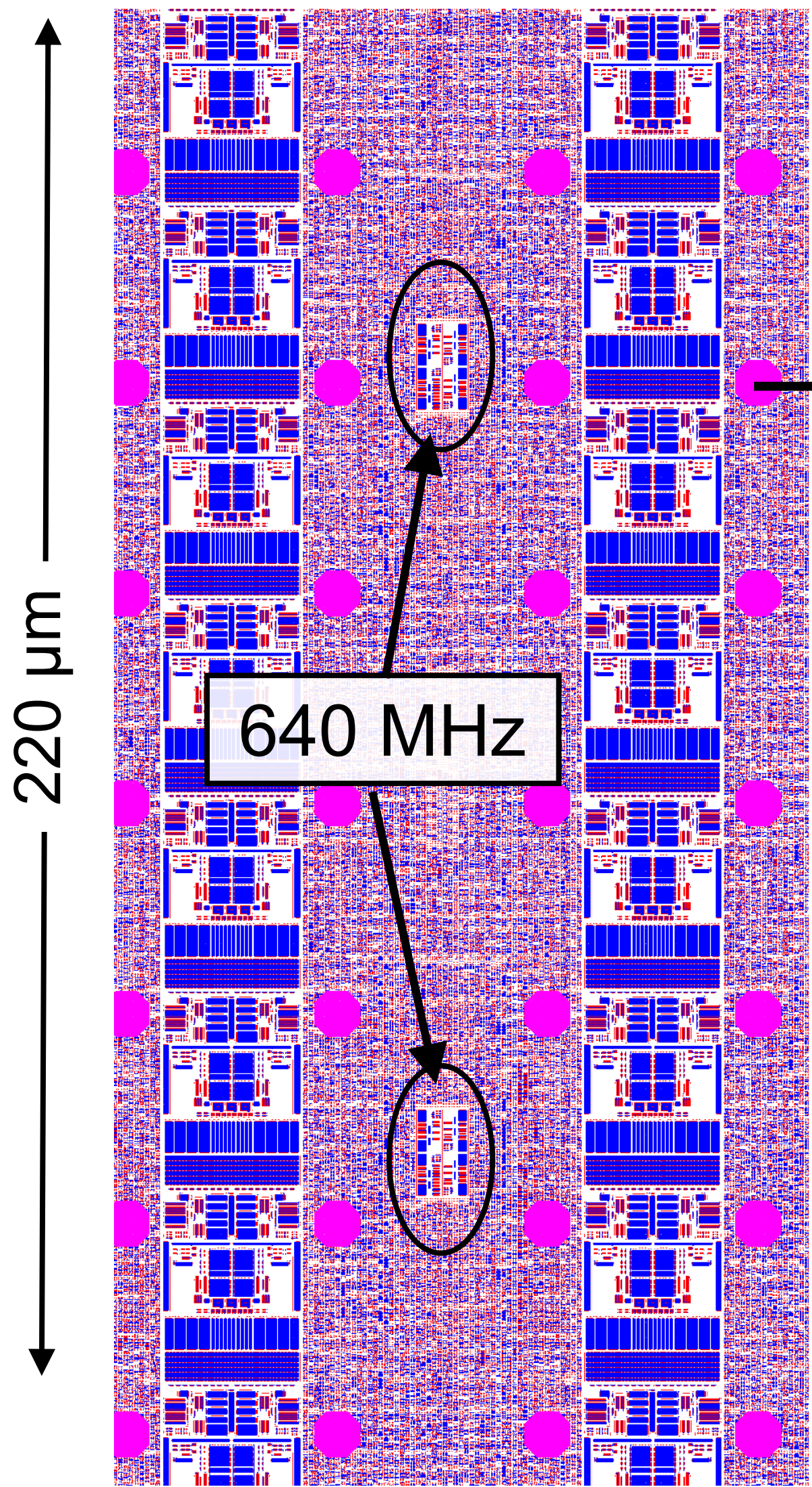
X. Llopart *et al* 2022 *JINST* 17 C01044 [DOI: [10.1088/1748-0221/17/01/C01044](https://doi.org/10.1088/1748-0221/17/01/C01044)]

Timepix3 → Timepix4



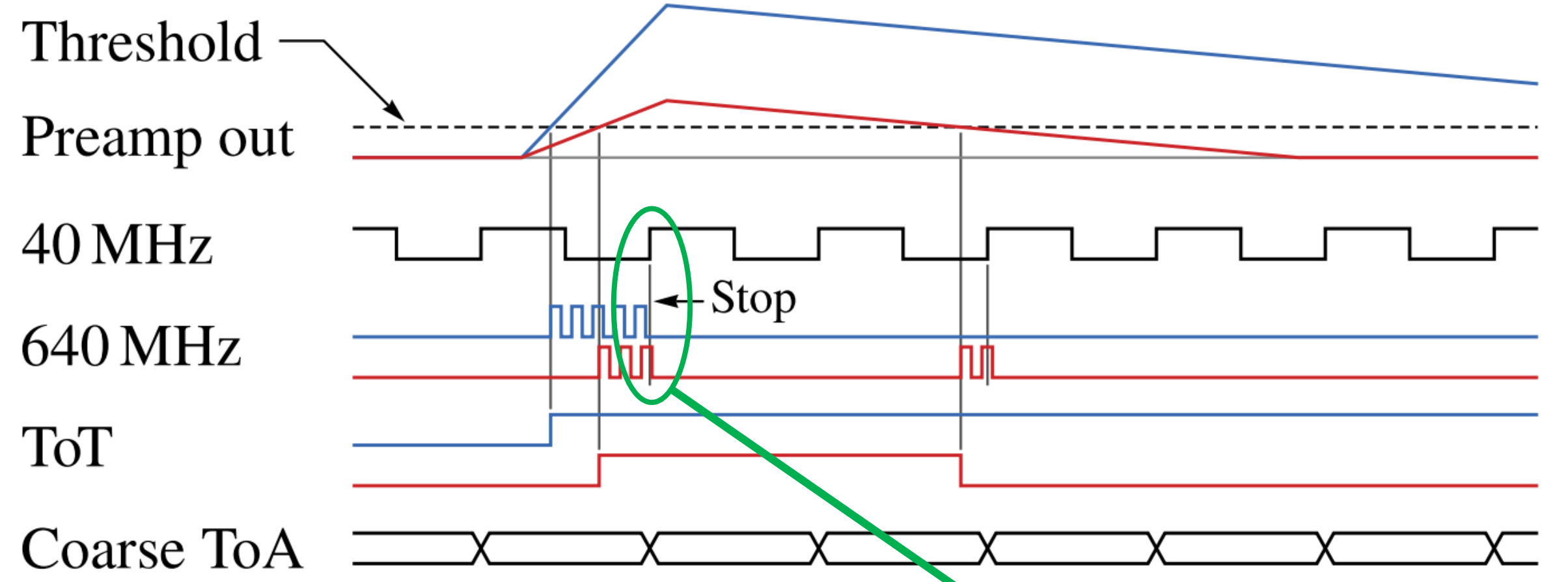
			Timepix3 (2013)	Timepix4 (2019)
Technology			130nm – 8 metal	65nm – 10 metal
Pixel Size			55 x 55 μm	55 x 55 μm
Pixel arrangement			3-side buttable 256 x 256	4-side buttable 512 x 448
Sensitive area			1.98 cm^2	6.94 cm^2 3.5x
Readout Modes	Data driven (Tracking)	Mode	TOT and TOA	
		Event Packet	48-bit	64-bit
		Max rate	0.43x10 ⁶ hits/mm ² /s	3.58x10⁶ hits/mm²/s 8x
	Frame based (Imaging)	Max Pix rate	1.3 KHz/pixel	10.8 KHz/pixel
		Mode	PC (10-bit) and iTOT (14-bit)	CRW: PC (8 or 16-bit)
		Frame	Zero-suppressed (with pixel addr)	Full Frame (without pixel addr)
	Max count rate	~0.82 x 10 ⁹ hits/mm ² /s	~5 x 10 ⁹ hits/mm ² /s	
TOT energy resolution			< 2KeV	< 1Kev
TOA binning resolution			1.56ns	195ps 8x
TOA dynamic range			409.6 μs (14-bits @ 40MHz)	1.6384 ms (16-bits @ 40MHz)
Readout bandwidth			≤5.12Gb (8x SLVS@640 Mbps)	≤163.84 Gbps (16x @10.24 Gbps) 32x
Target minimum threshold			<500 e ⁻	<500 e ⁻

Time measurement in Timepix4

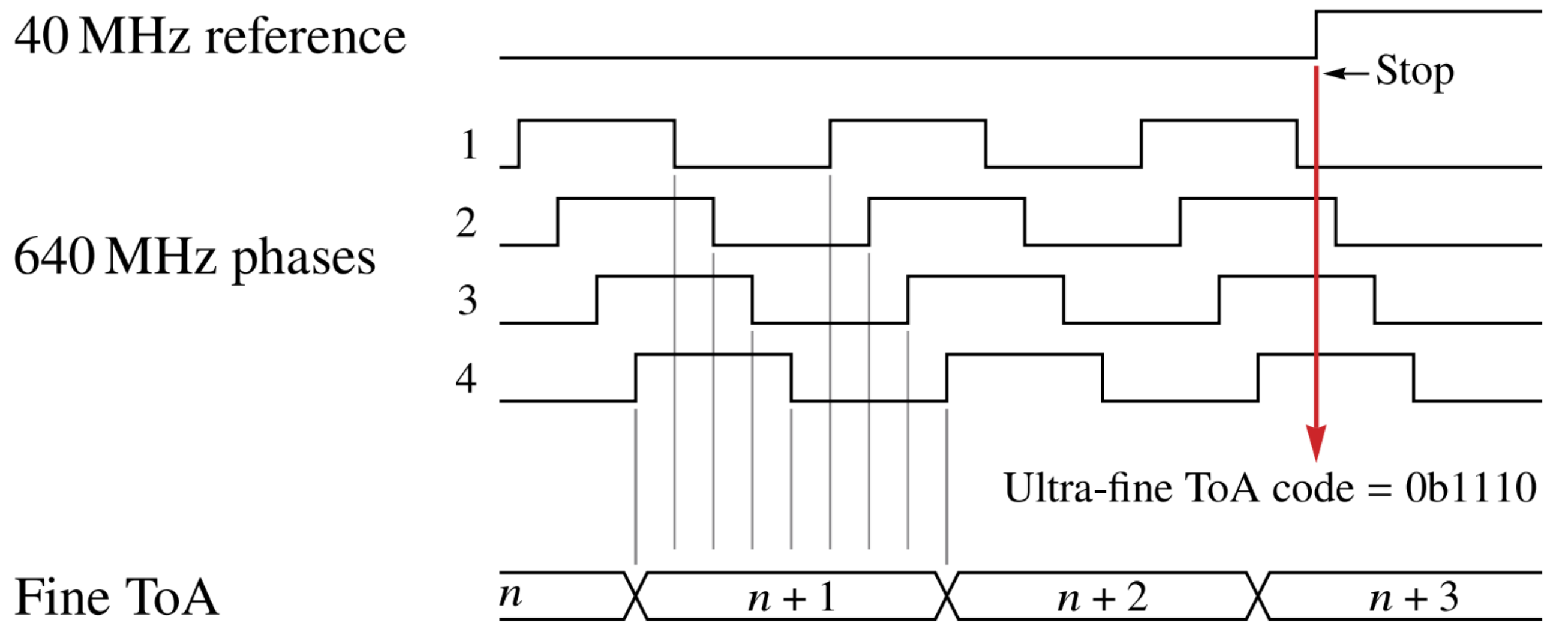


- Nominal TDC resolution:
 $195 \text{ ps} / \sqrt{12} = 56 \text{ ps}$
- Time over threshold (ToT) measures signal charge

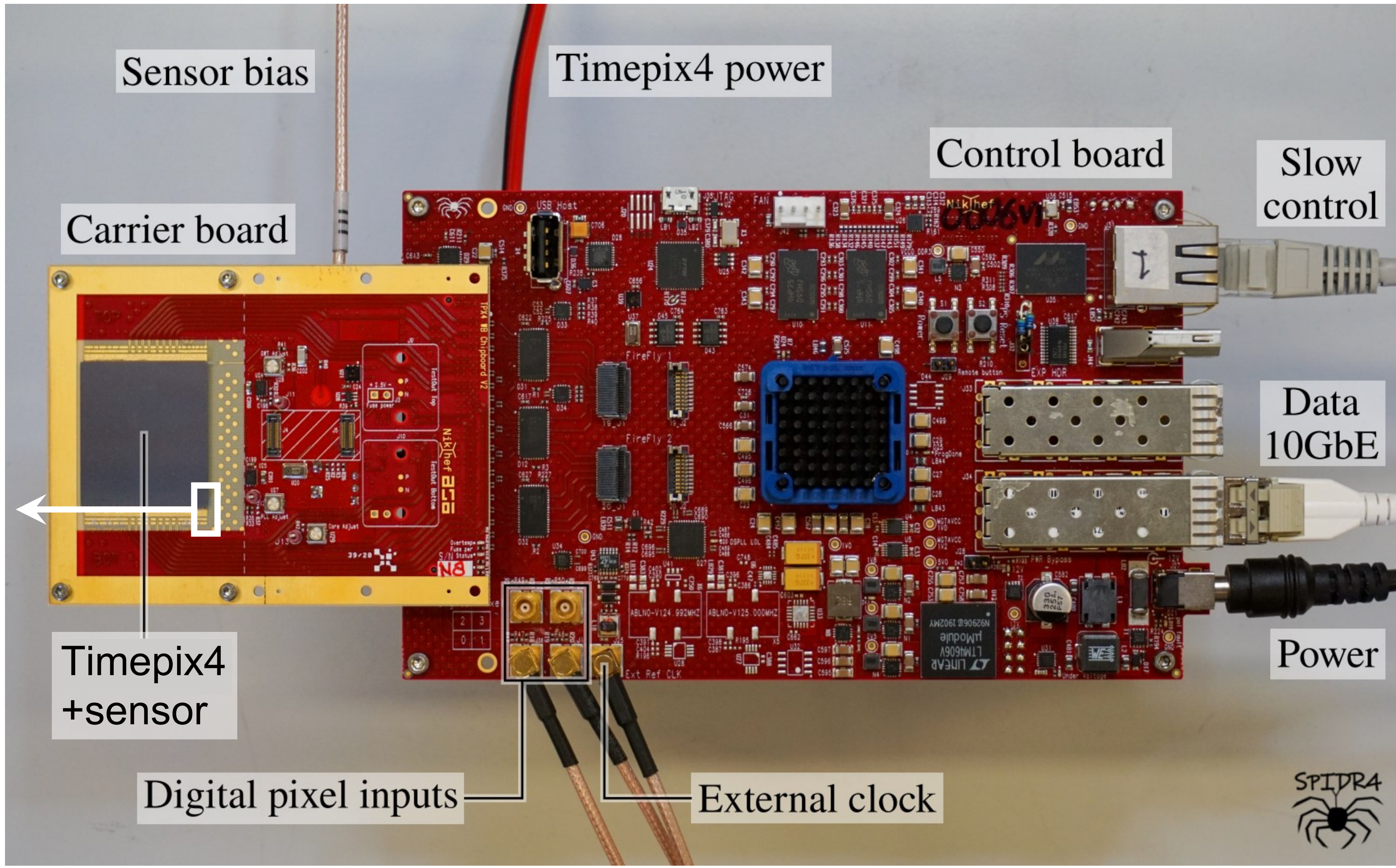
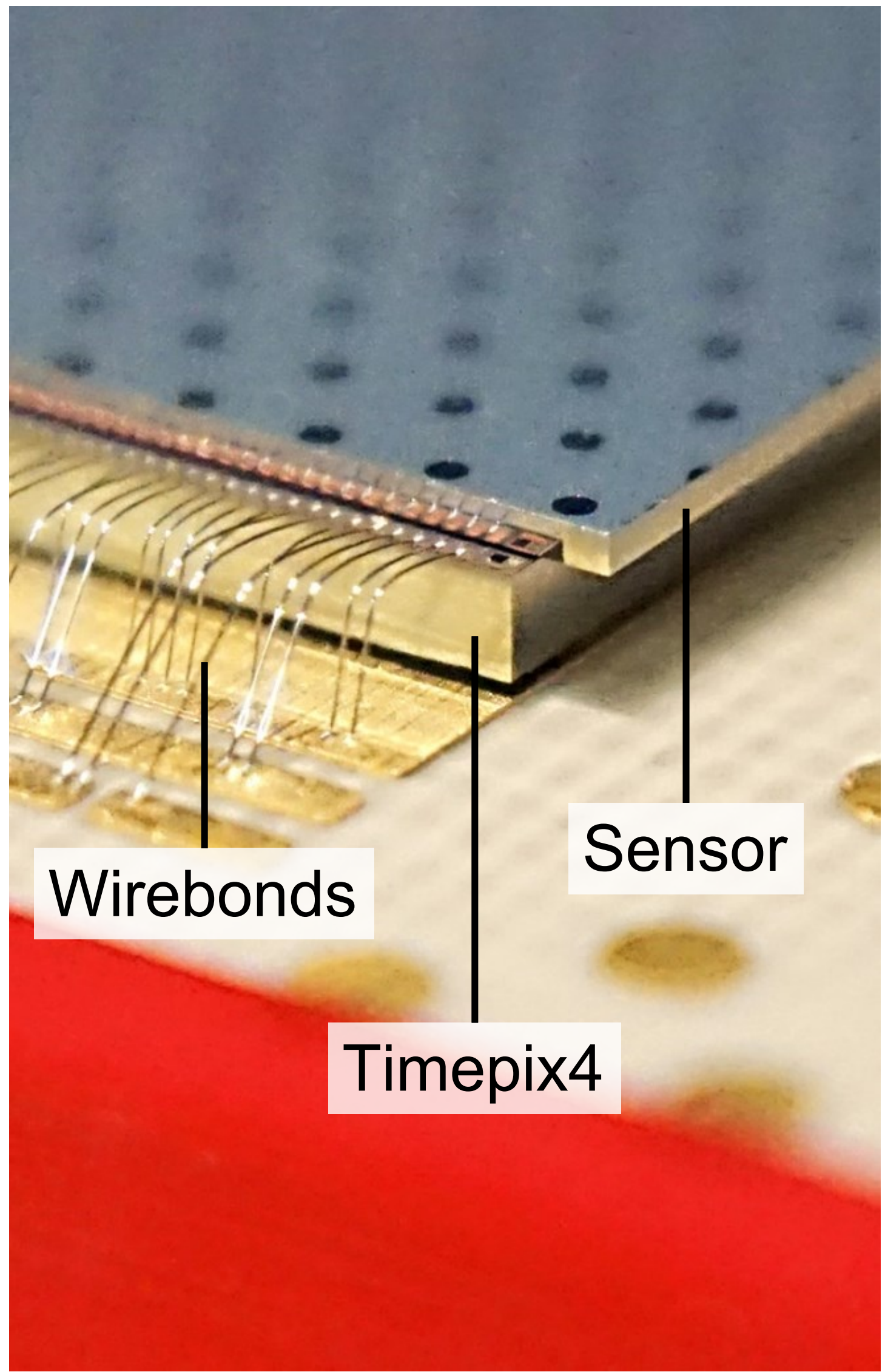
Coarse and fine time measurement – 40 MHz and 640 MHz



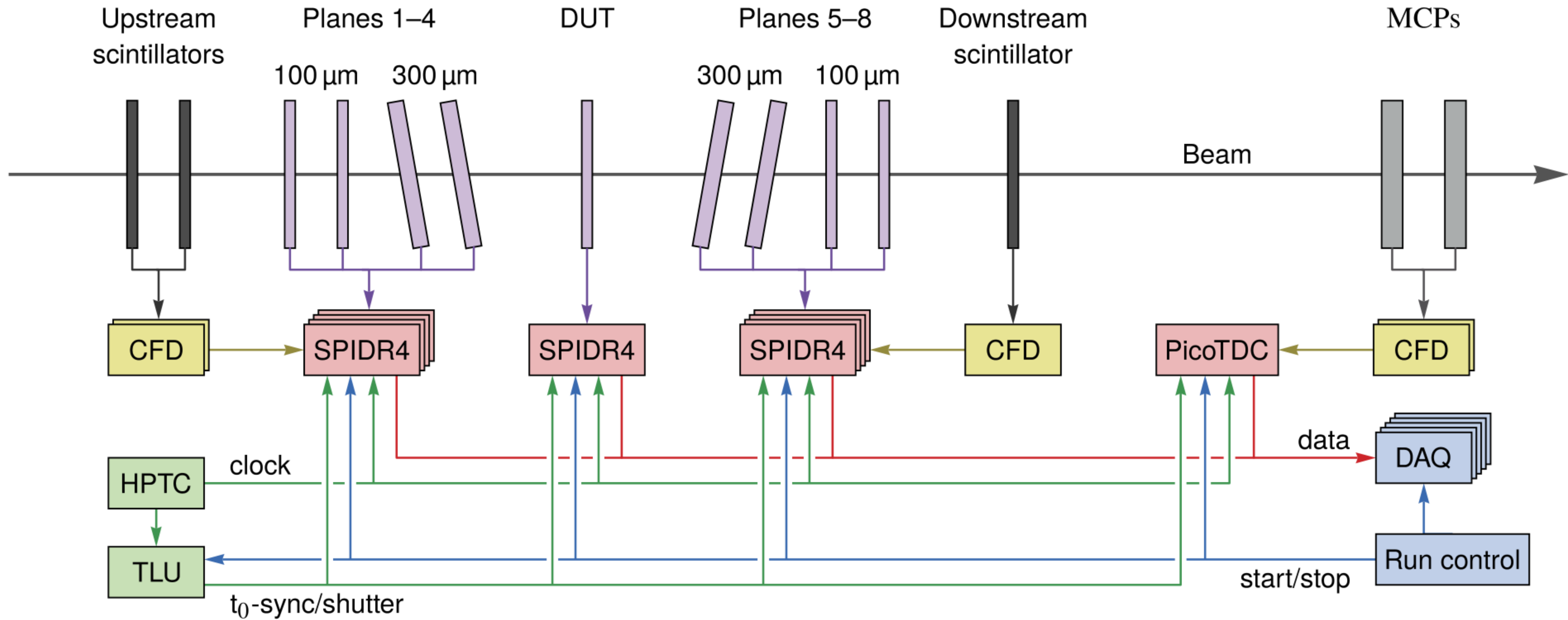
Ultrafine time measurement – 195 ps



Speedy Pixel Detector Readout 4 (SPIDR4)

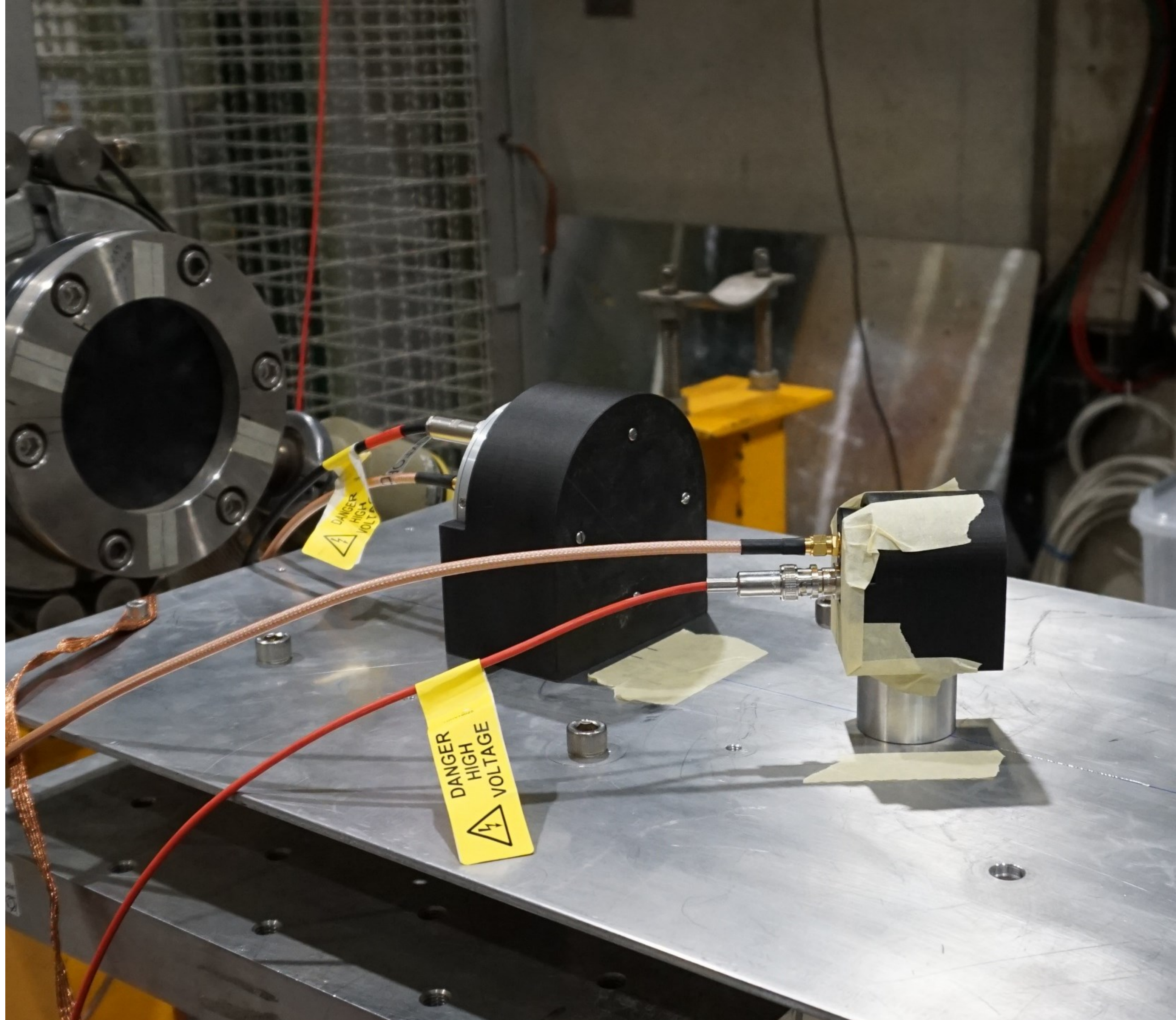
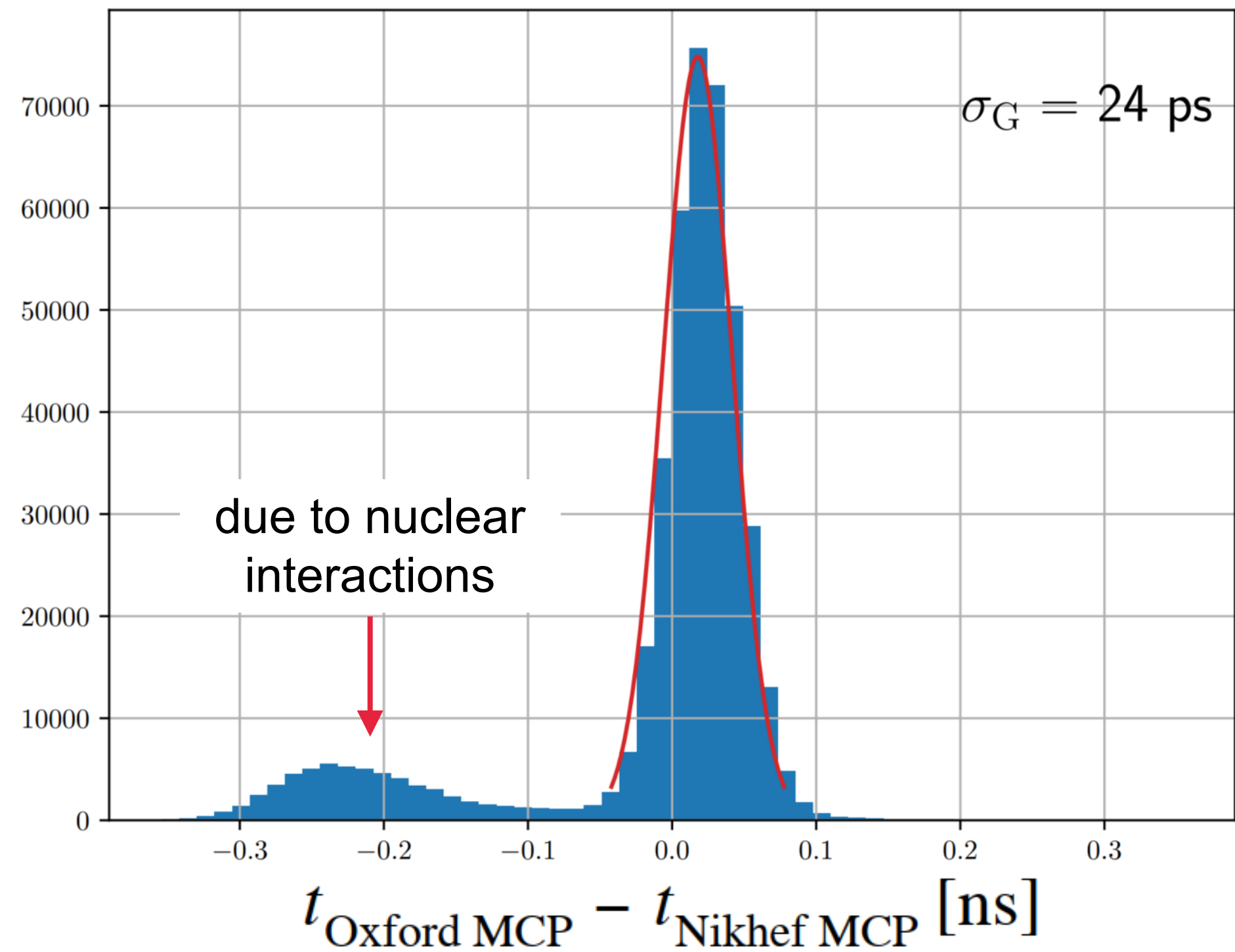


Telescope configuration



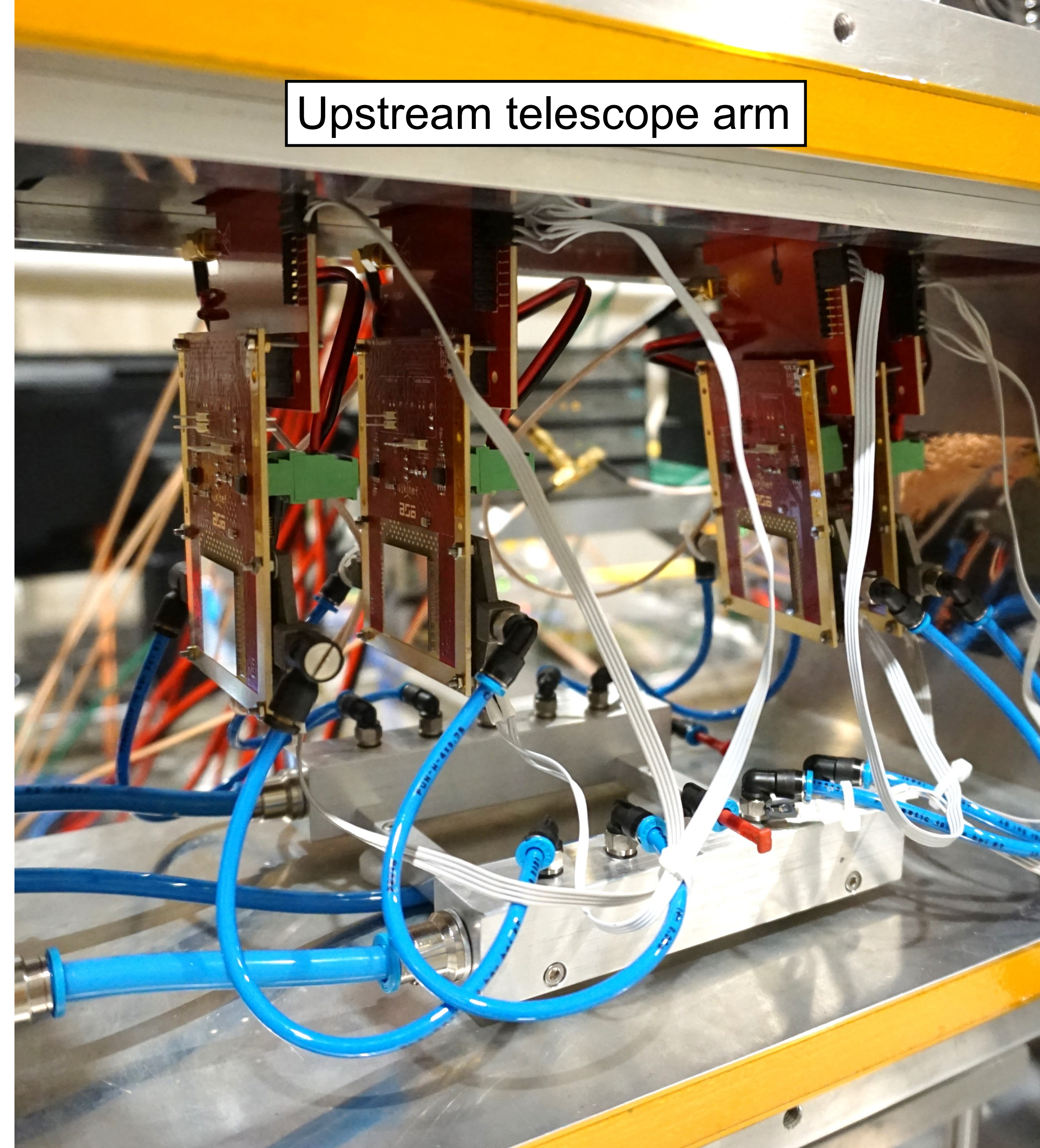
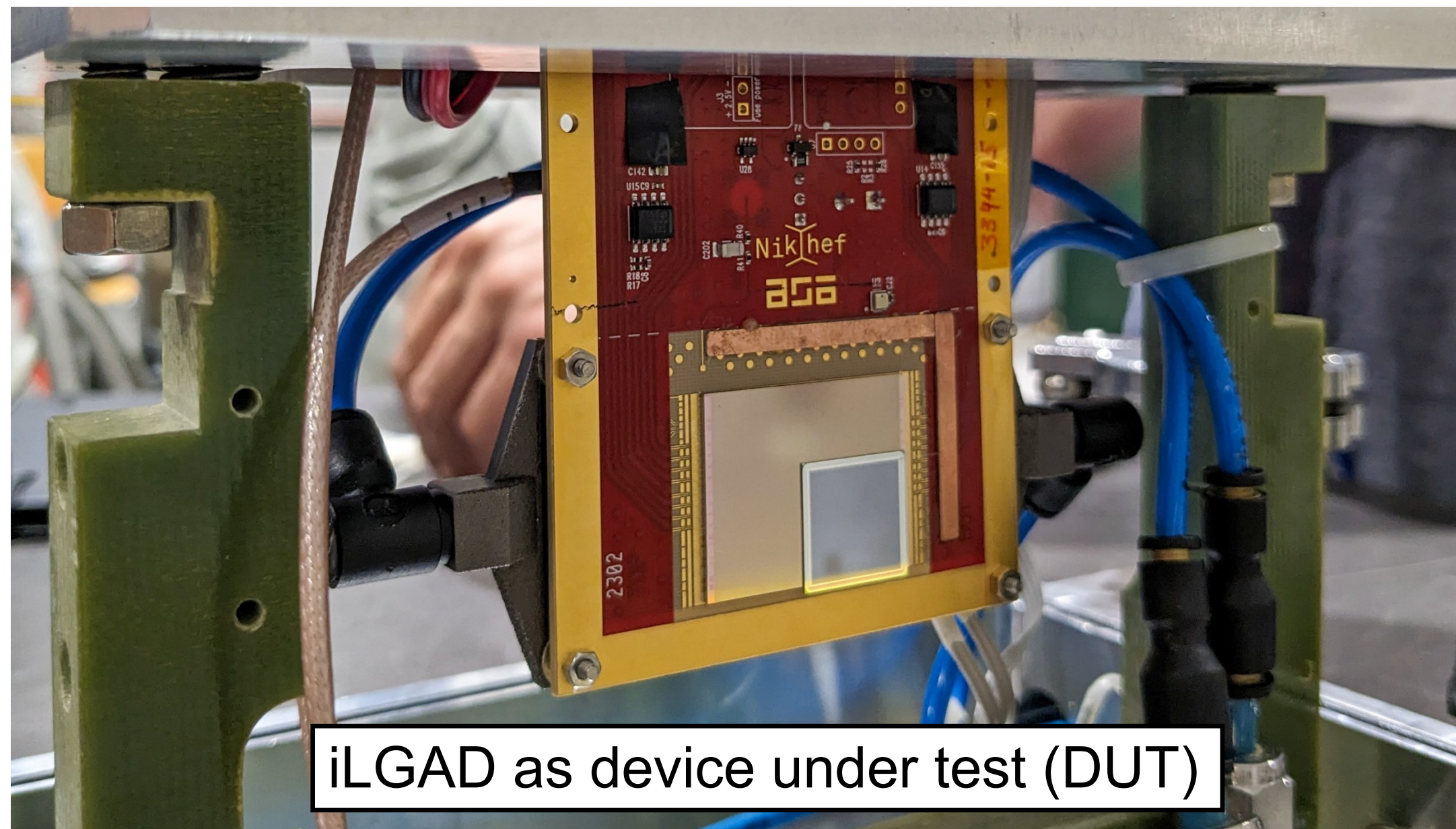
Micro channel plate detectors

- Time reference to study telescope timing
- Considering installing Timpix4 plane to VETO events with nuclear interactions
- Current time resolution: 17 ps (single MCP)
- Combined MCP resolution: 12 ps



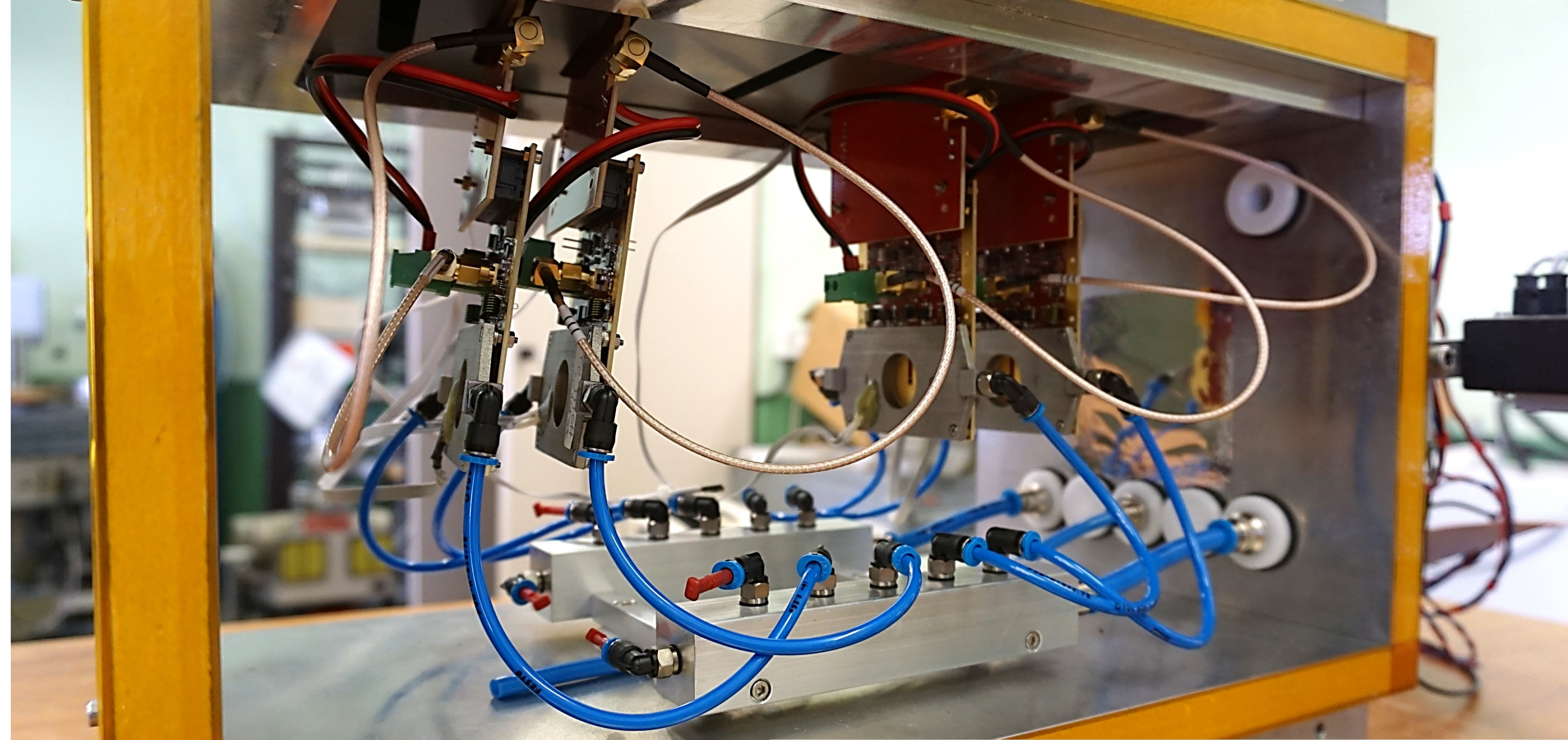
Plane assemblies (all Timepix4v2)

- Eight telescope planes with n-on-p planar silicon sensors:
 - 4 x 300 μm sensors for spatial resolution (angled)
 - 4 x 100 μm sensors for time resolution (perpendicular)
 - Sensor upgrades are anticipated (LGAD, 3D, ...)
- Several DUT assemblies:
 - 50 μm , 100 μm , and 200 μm n-on-p planar silicon
 - 300 μm p-on-n
 - 2 x 250 μm iLGAD sensor 55 and 110 μm pitch (Tpx3 sized)

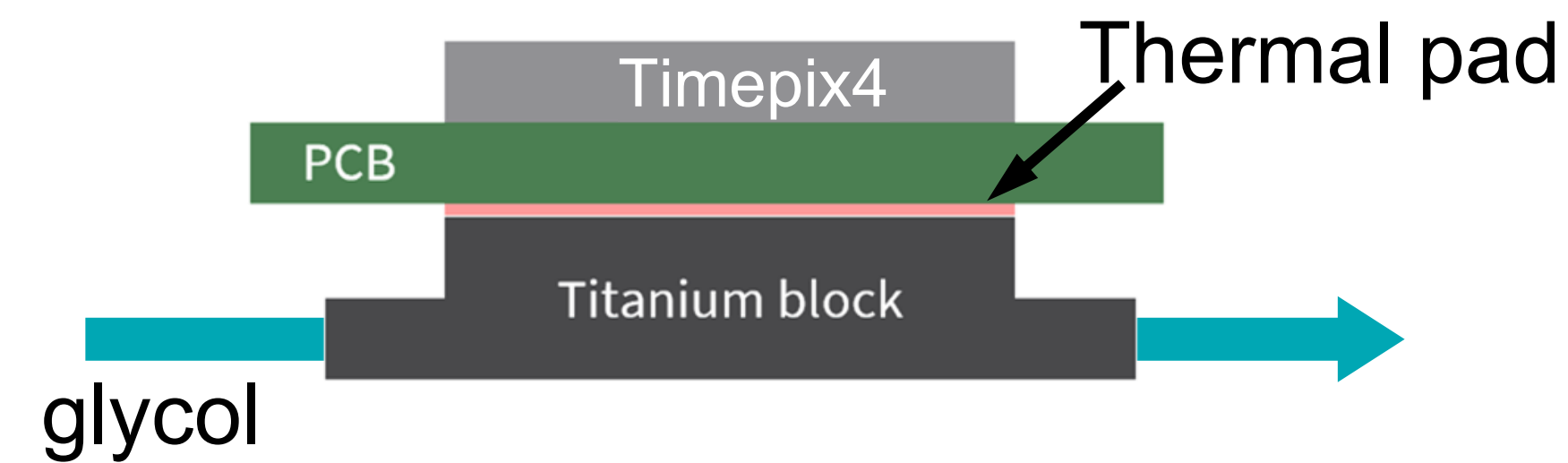


Assembly cooling

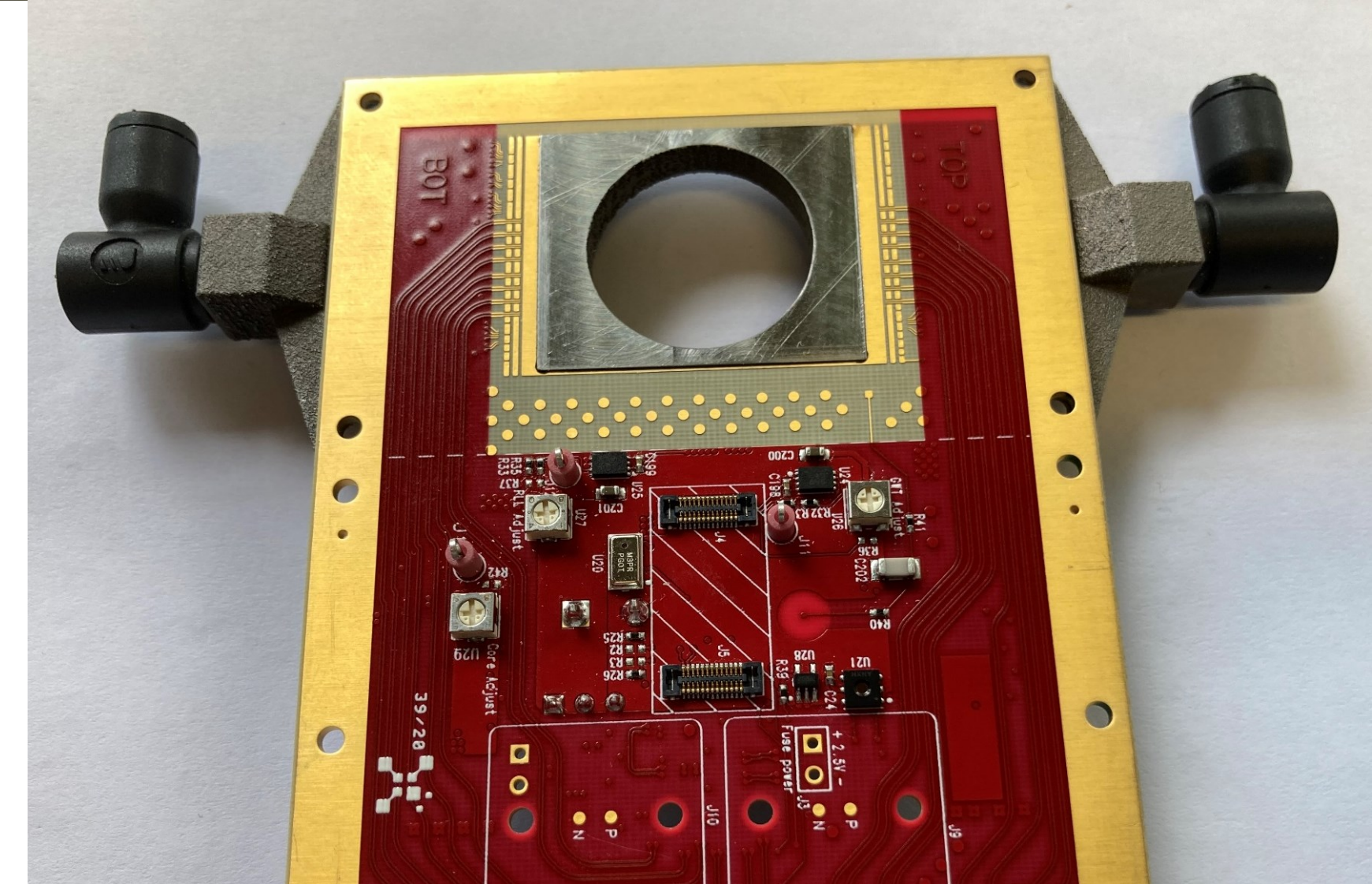
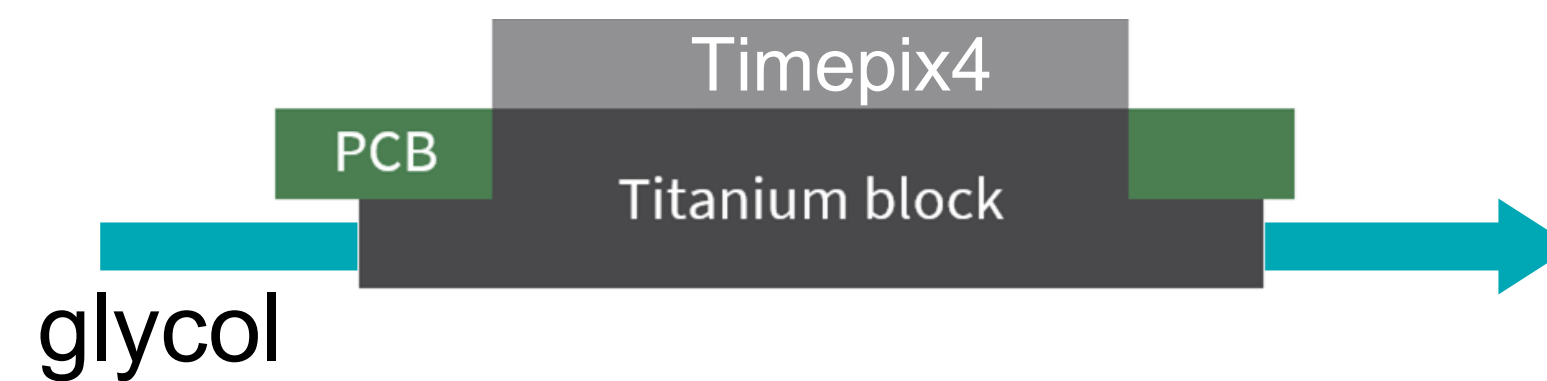
- All assemblies have a 3D-printed titanium cooling block
- Cooled using glycol at 20 °C
- Could go to -20 °C in the future
- Plan to mill PCB to have direct thermal contact with Timepix4



Current thermal interface

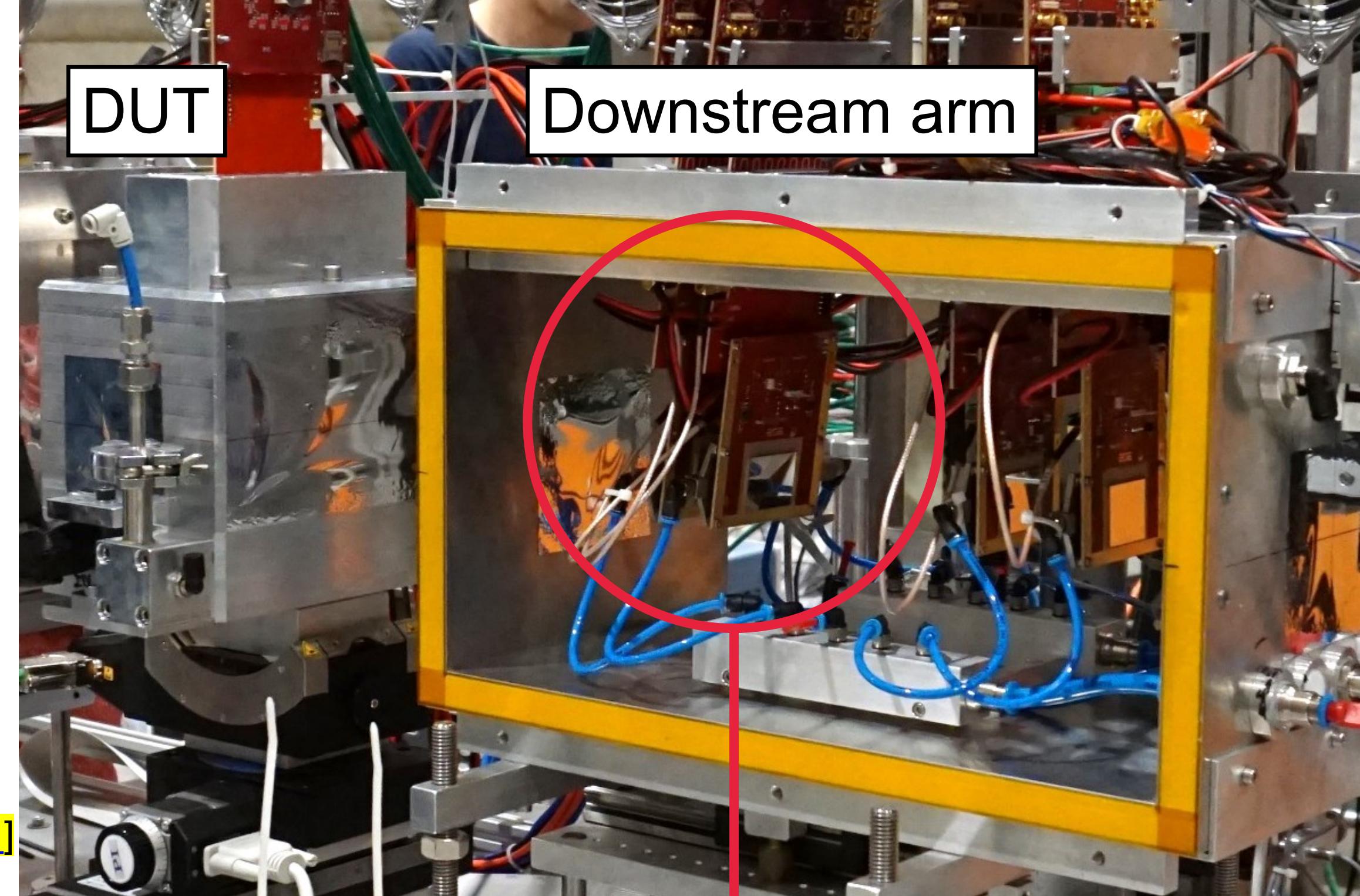


Future thermal interface



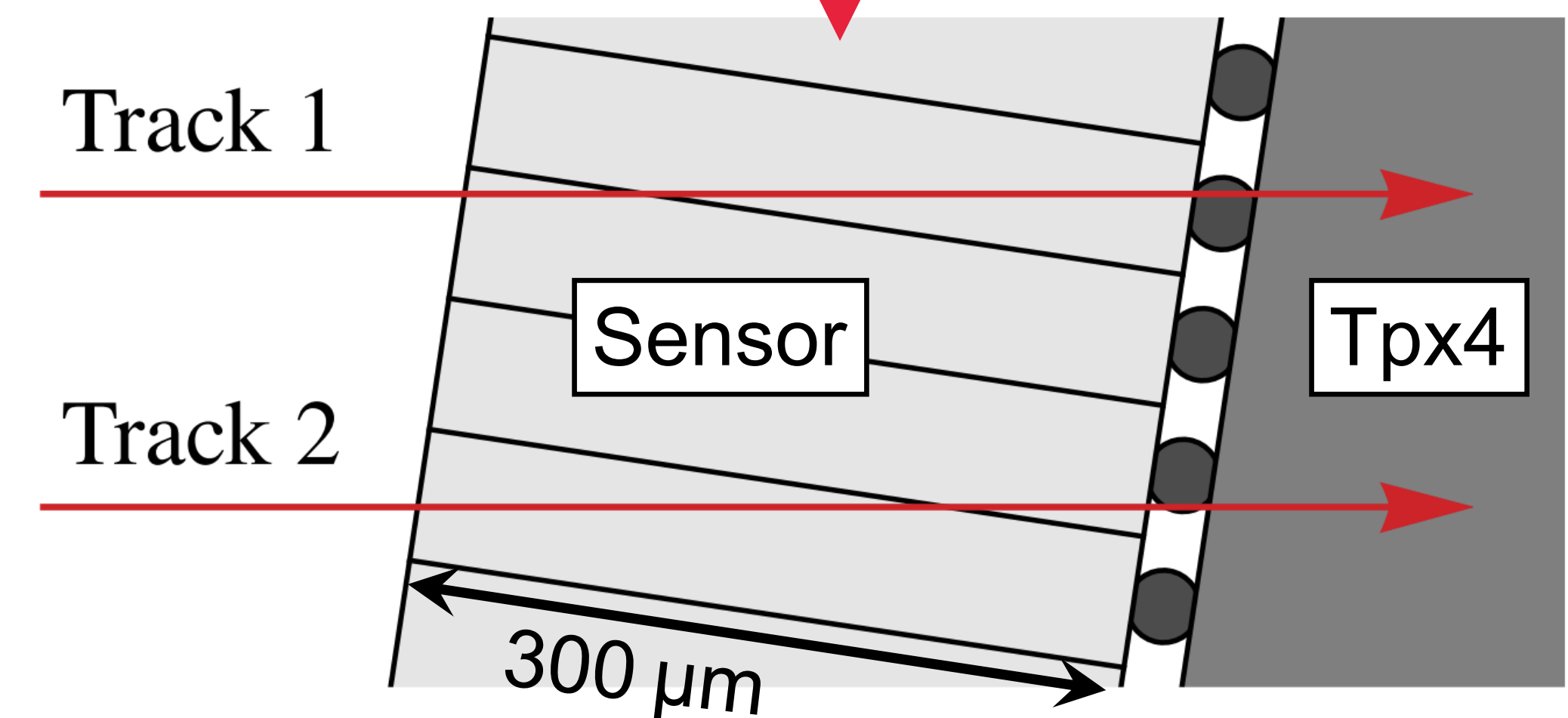
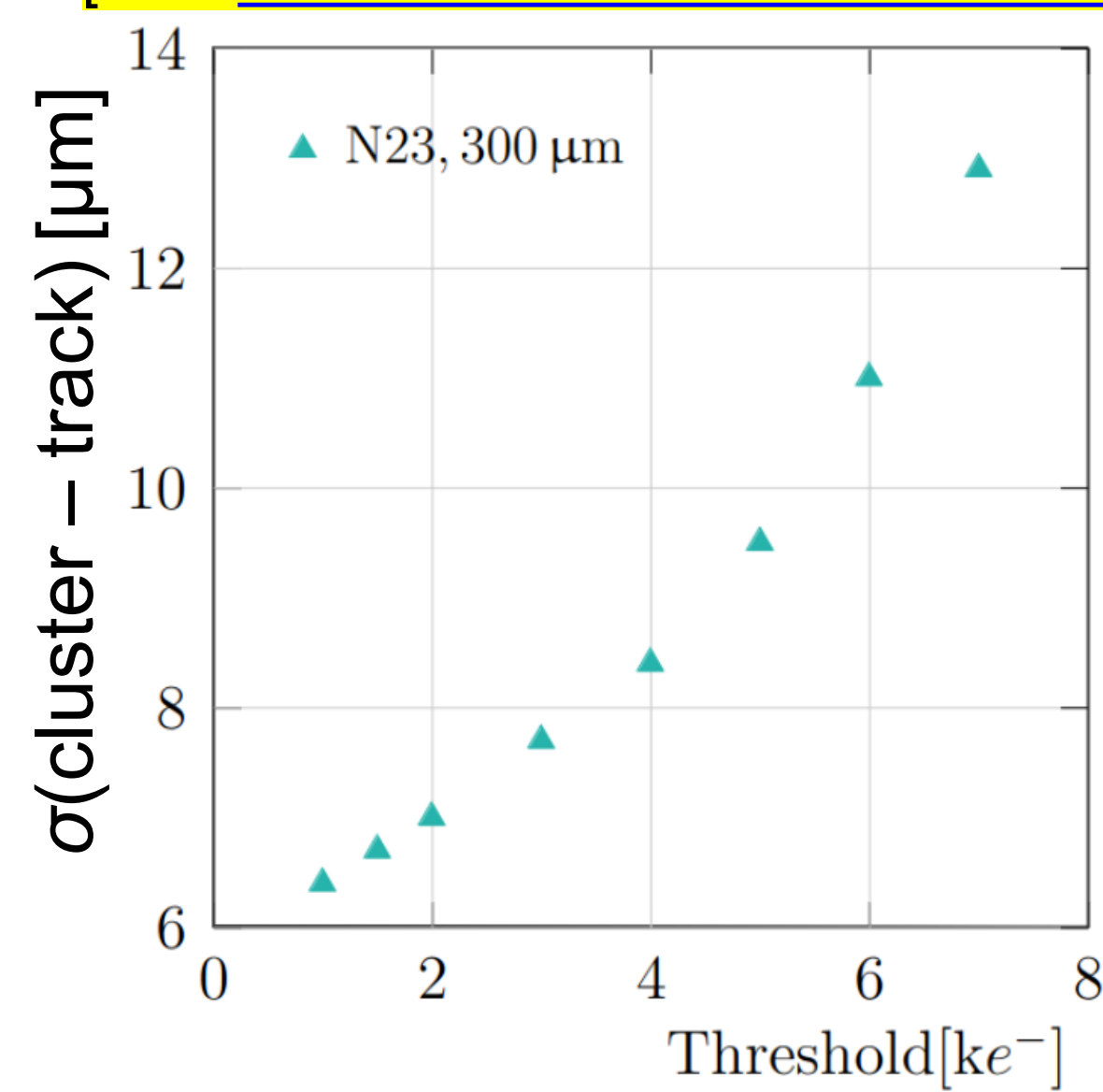
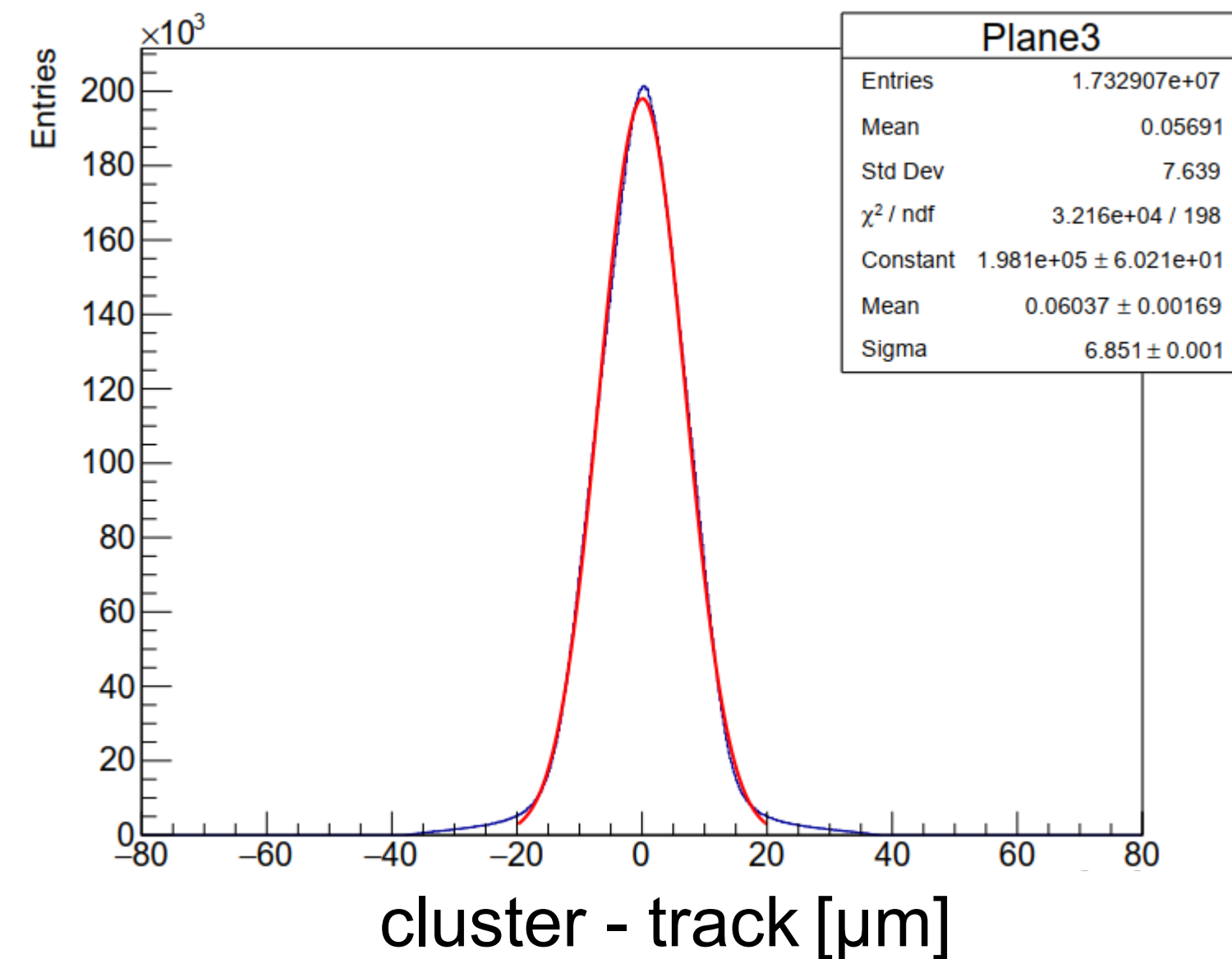
Spatial resolution

- Pixel size $55 \mu\text{m} \times 55 \mu\text{m}$
- Four innermost planes rotated 9° around x and y to induce charge sharing between pixels
- Charge-weighted mean gives cluster position
- Single plane resolution: **$4.3 \mu\text{m}$**
- Resolution depends on detection threshold



K. Akiba *et al* 2023 *JINST* 18 P02011

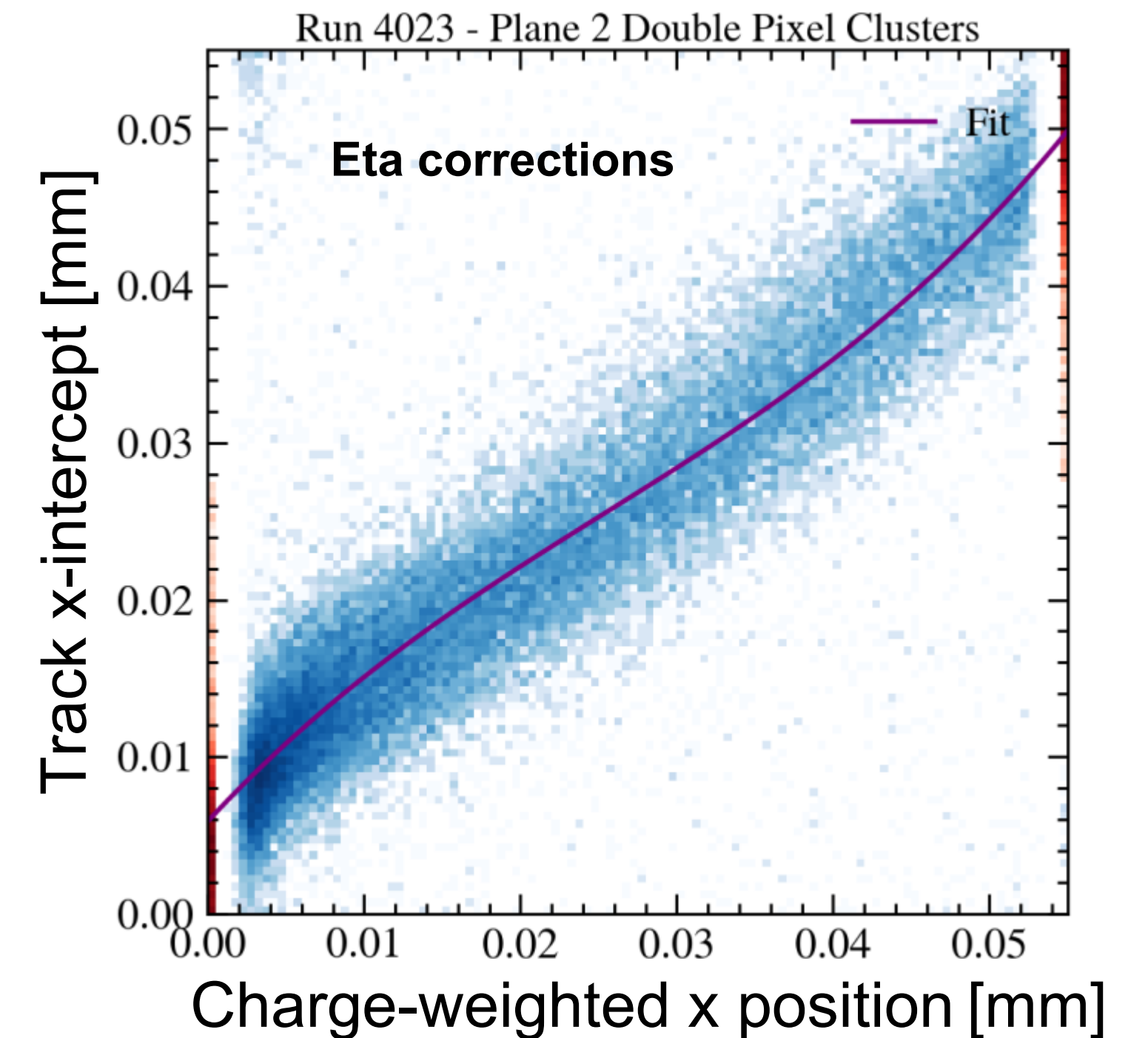
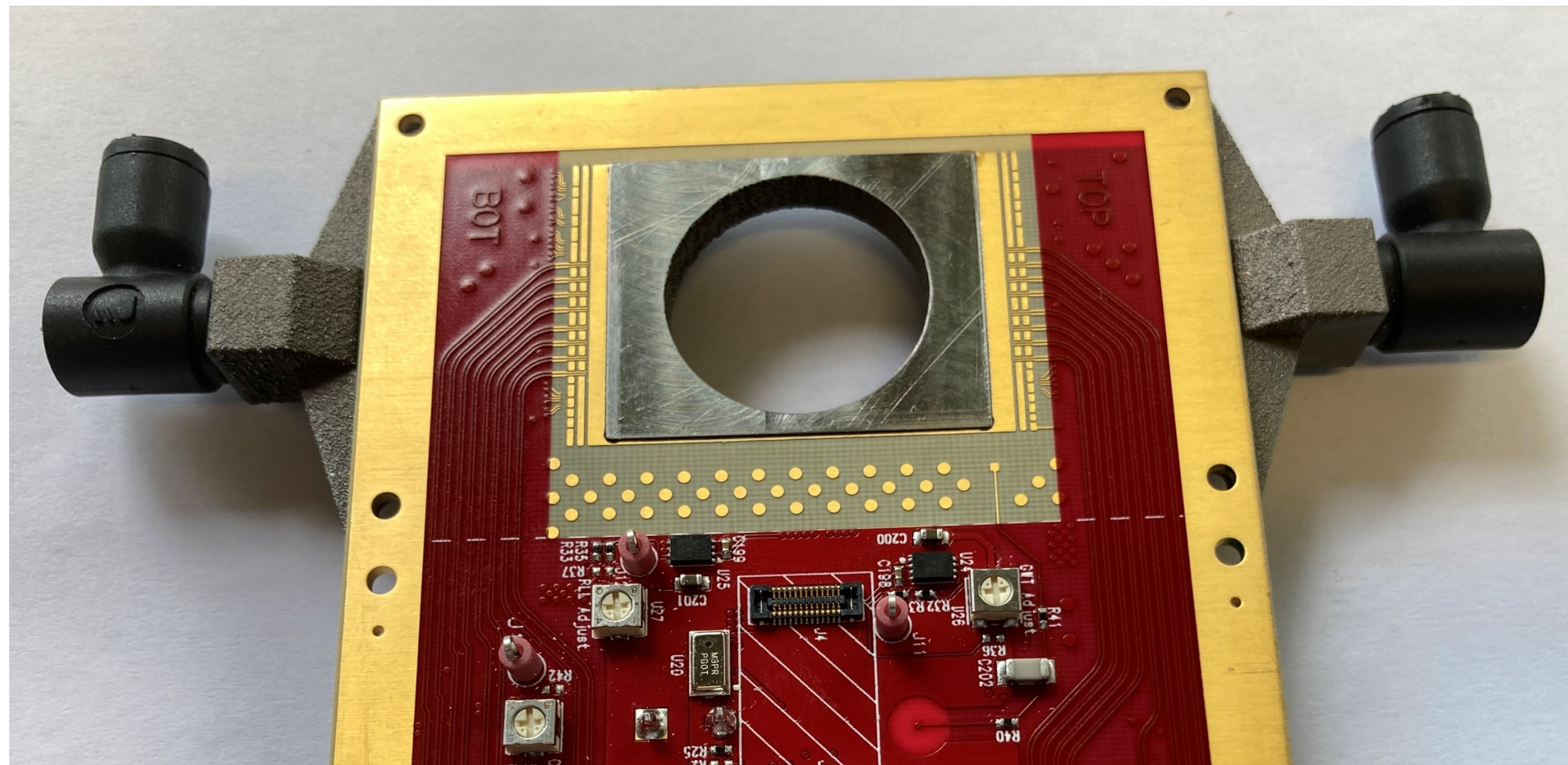
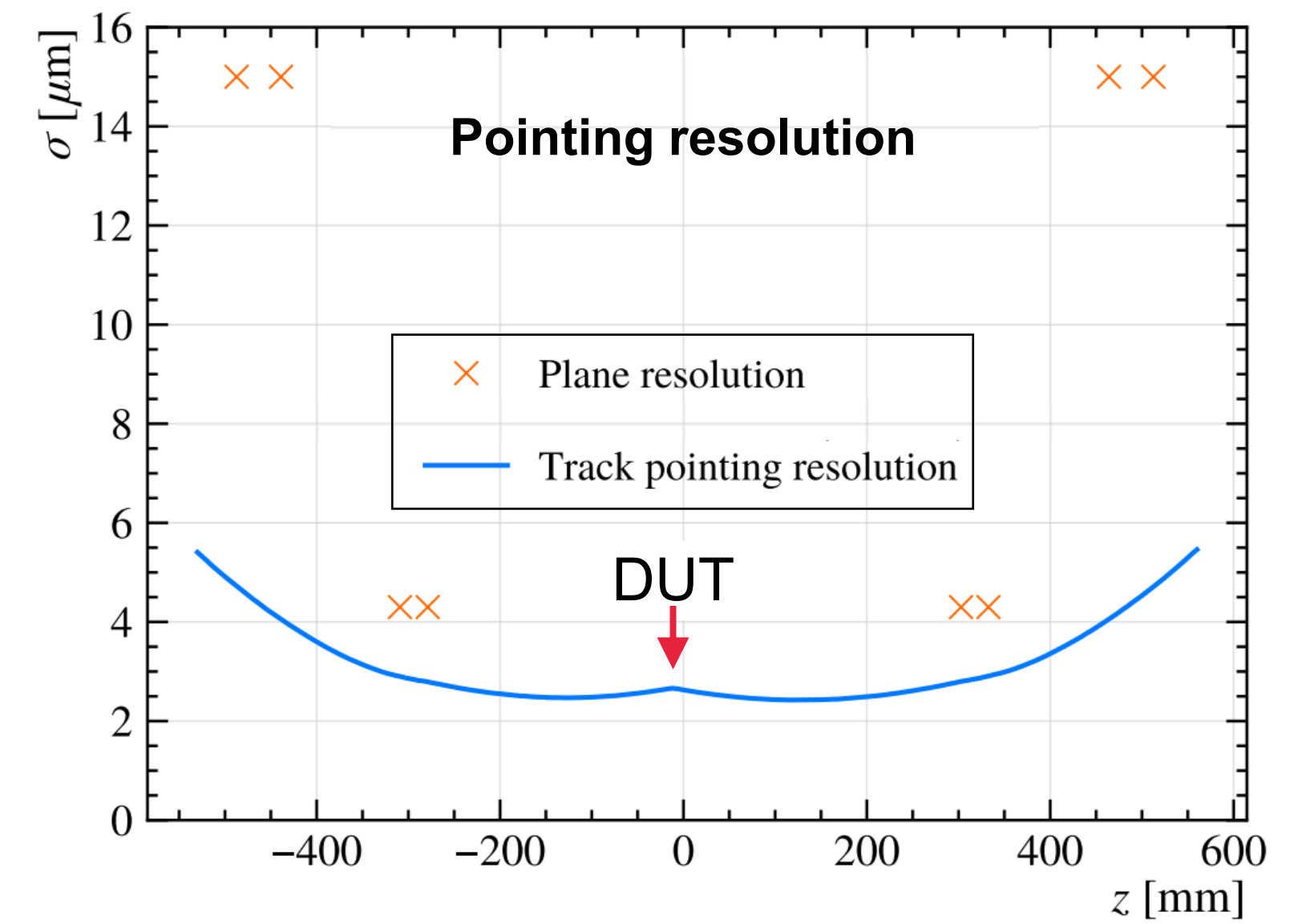
[DOI: [10.1088/1748-0221/18/02/P02011](https://doi.org/10.1088/1748-0221/18/02/P02011)]



Track pointing resolution

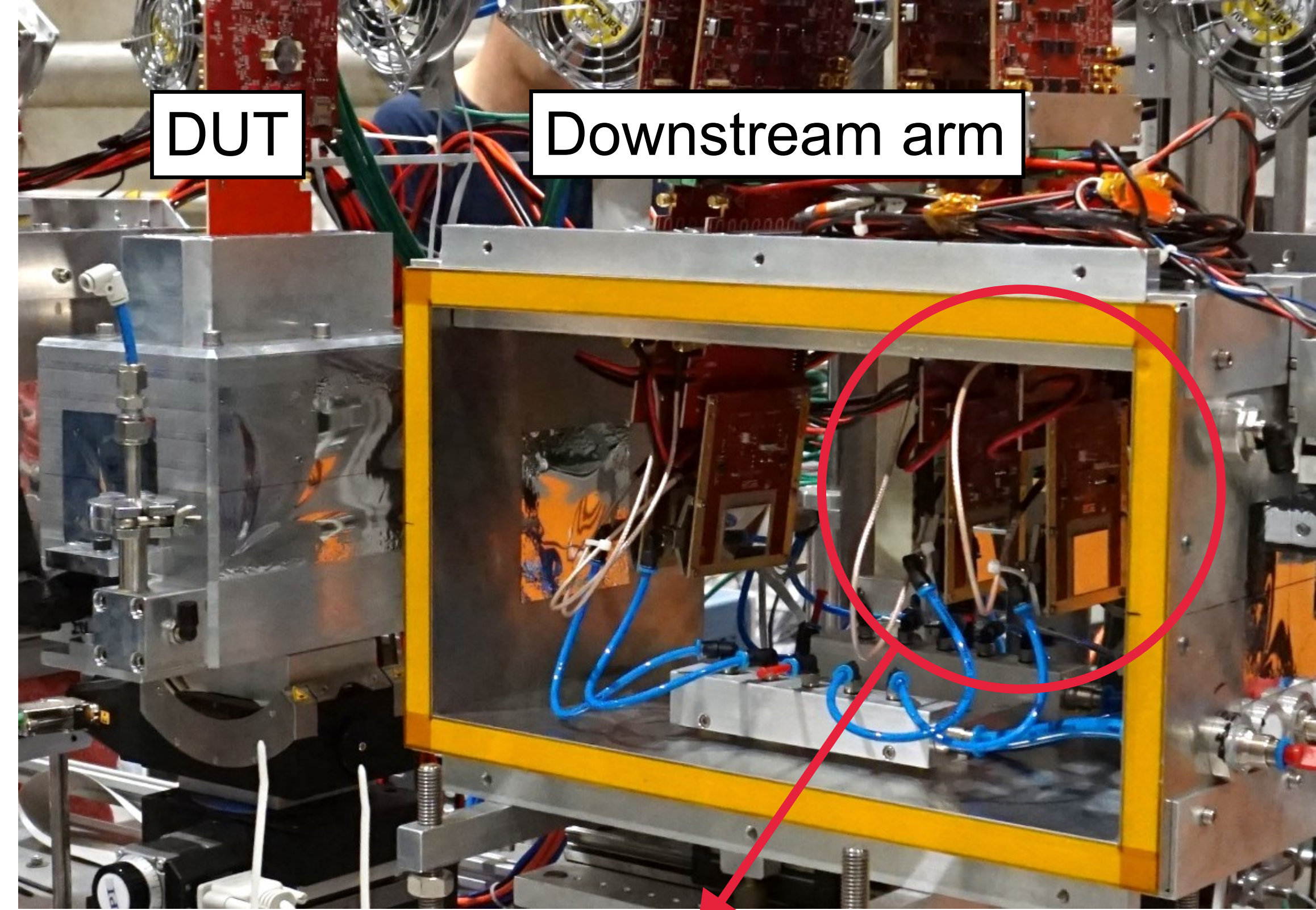
- Pointing resolution at DUT: **2.7 μm** (Mixed hadron beam 180 GeV/c)
- PCB adds 1.8 % X_0 (ASIC + sensor adds 0.8–1.0 % X_0)
- Milling out PCB would improve resolution to **2.2 μm**
- Investigating “eta corrections” for nonlinear charge sharing
- Other possible improvements:
 - Move telescope arms further inward when possible
 - Operate 300 μm planes at lower detection threshold
 - Add additional planes

$$\text{Scattering proportional to } \sqrt{x/X_0} [1 + 0.038 \log x/X_0]$$

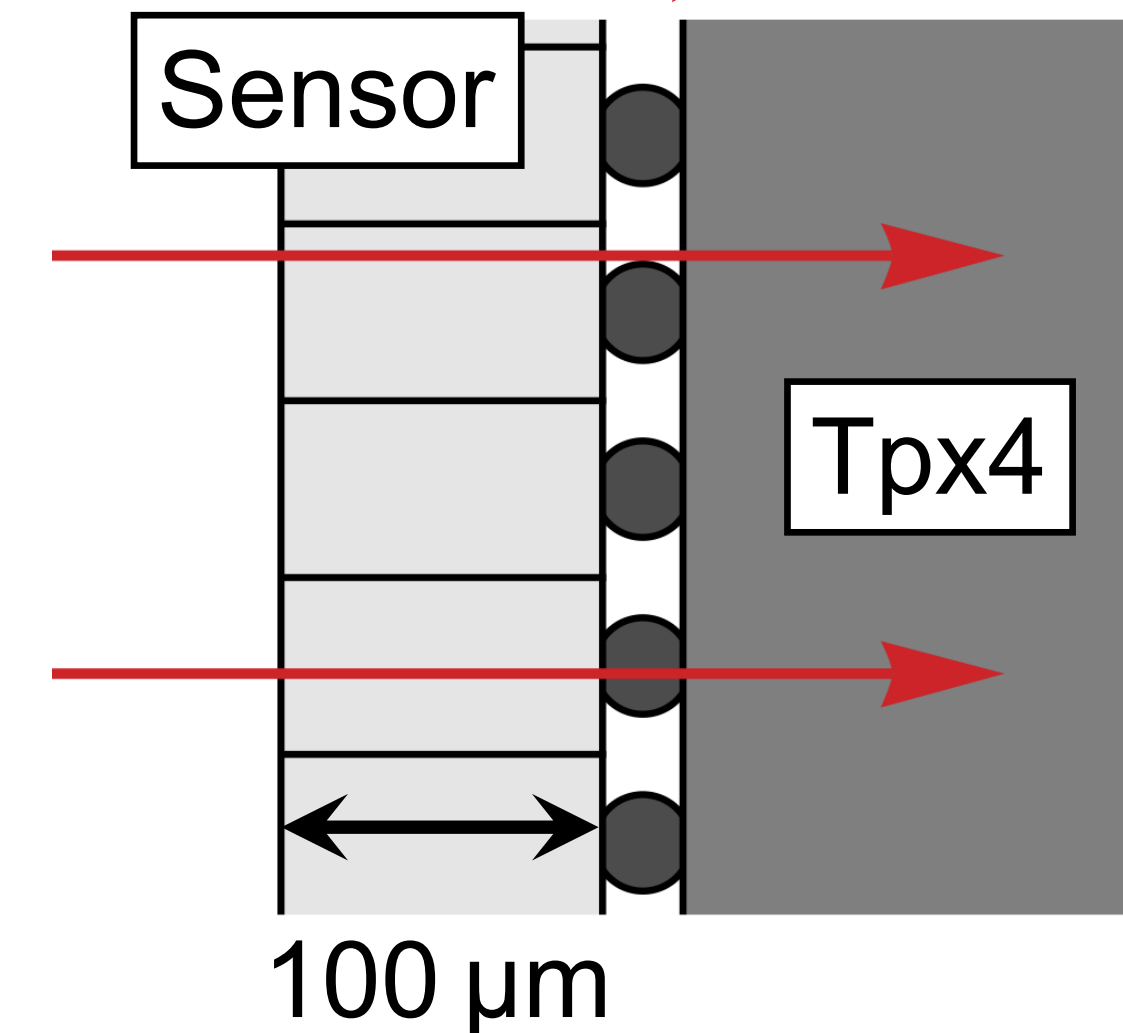
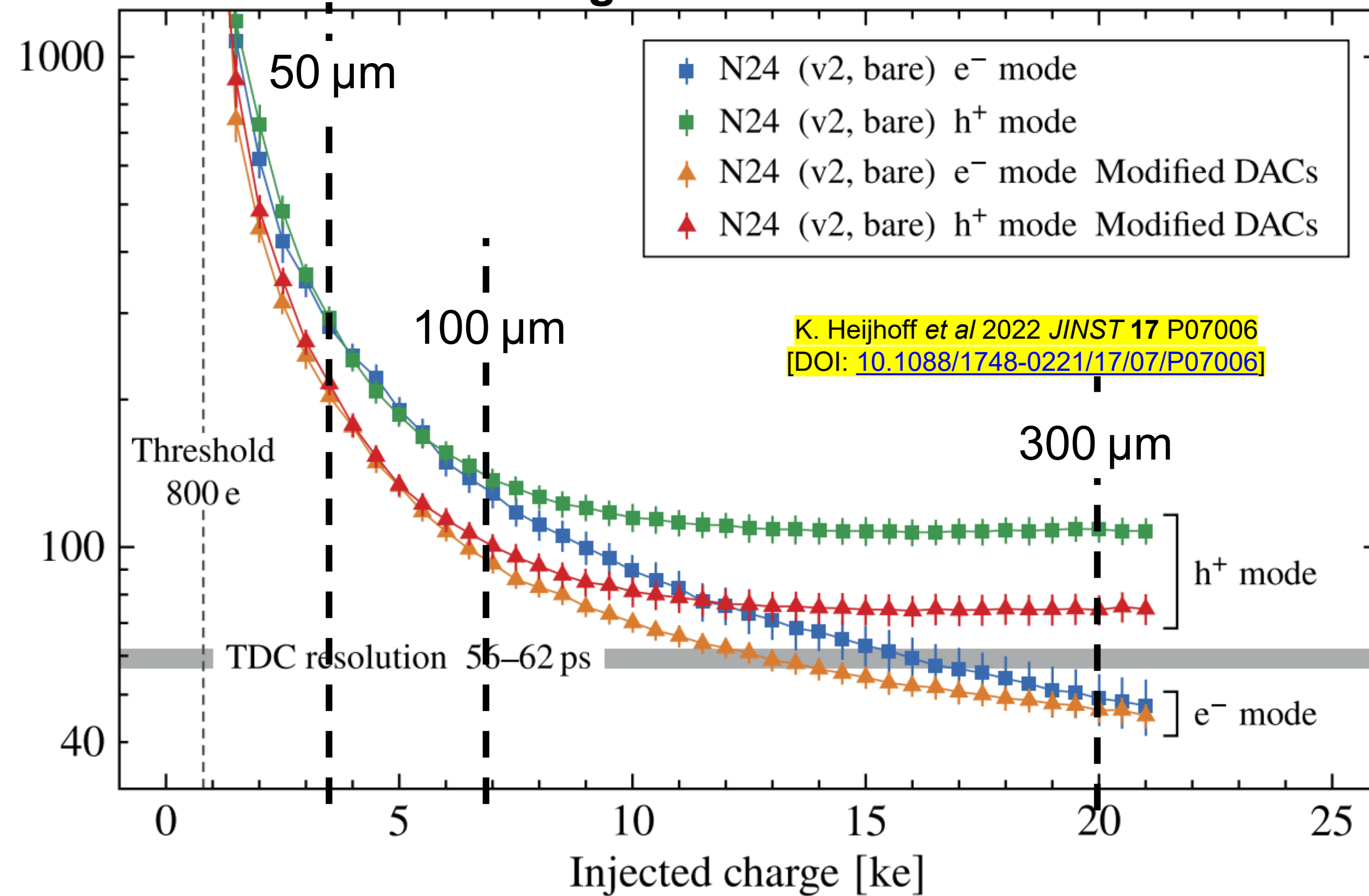


Time resolution

- Thin sensors reduce time errors due to Landau fluctuations
- Perpendicular to beam to maximise signal charge in single pixel
- Reduced signal size reduces analog front-end performance

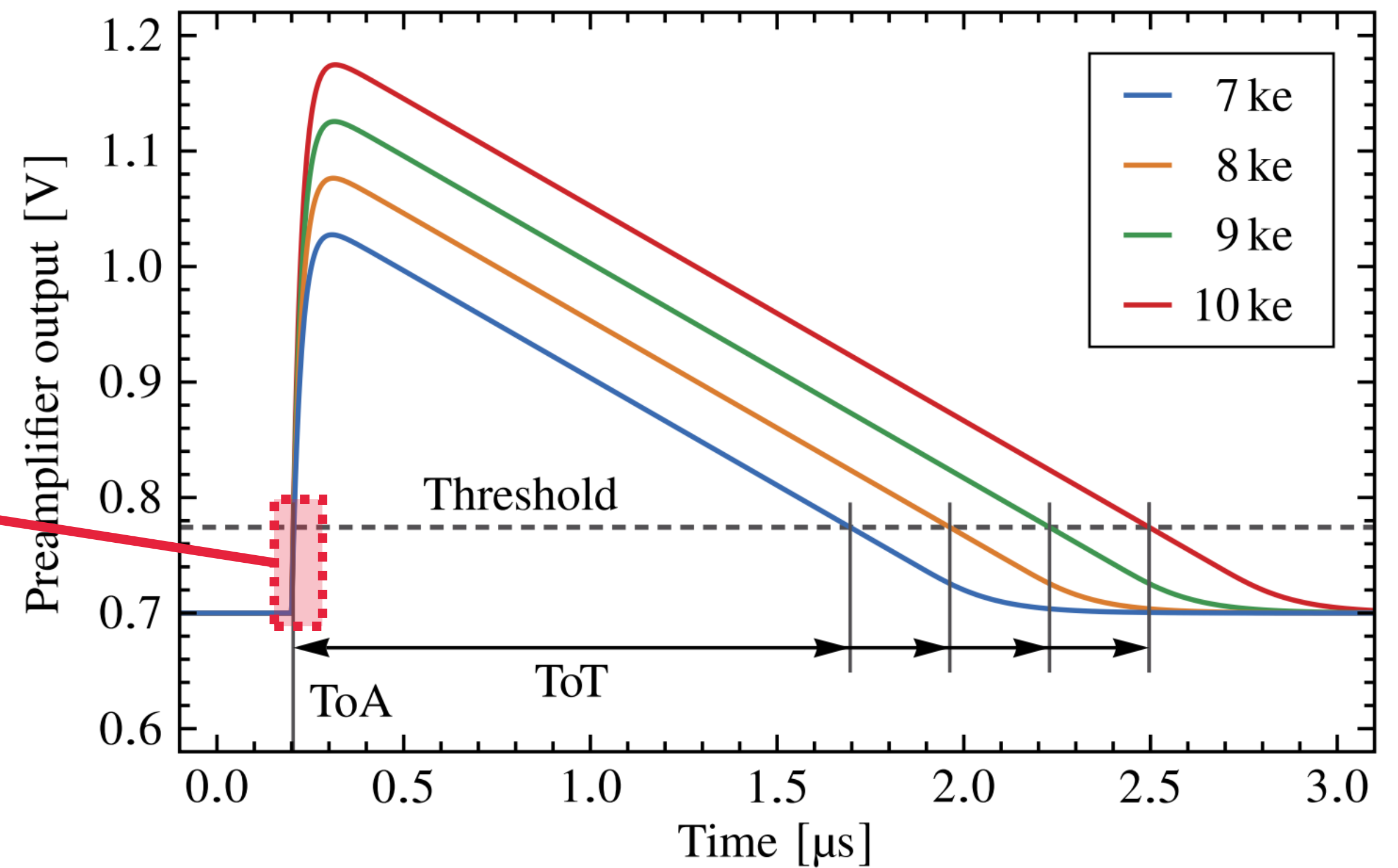
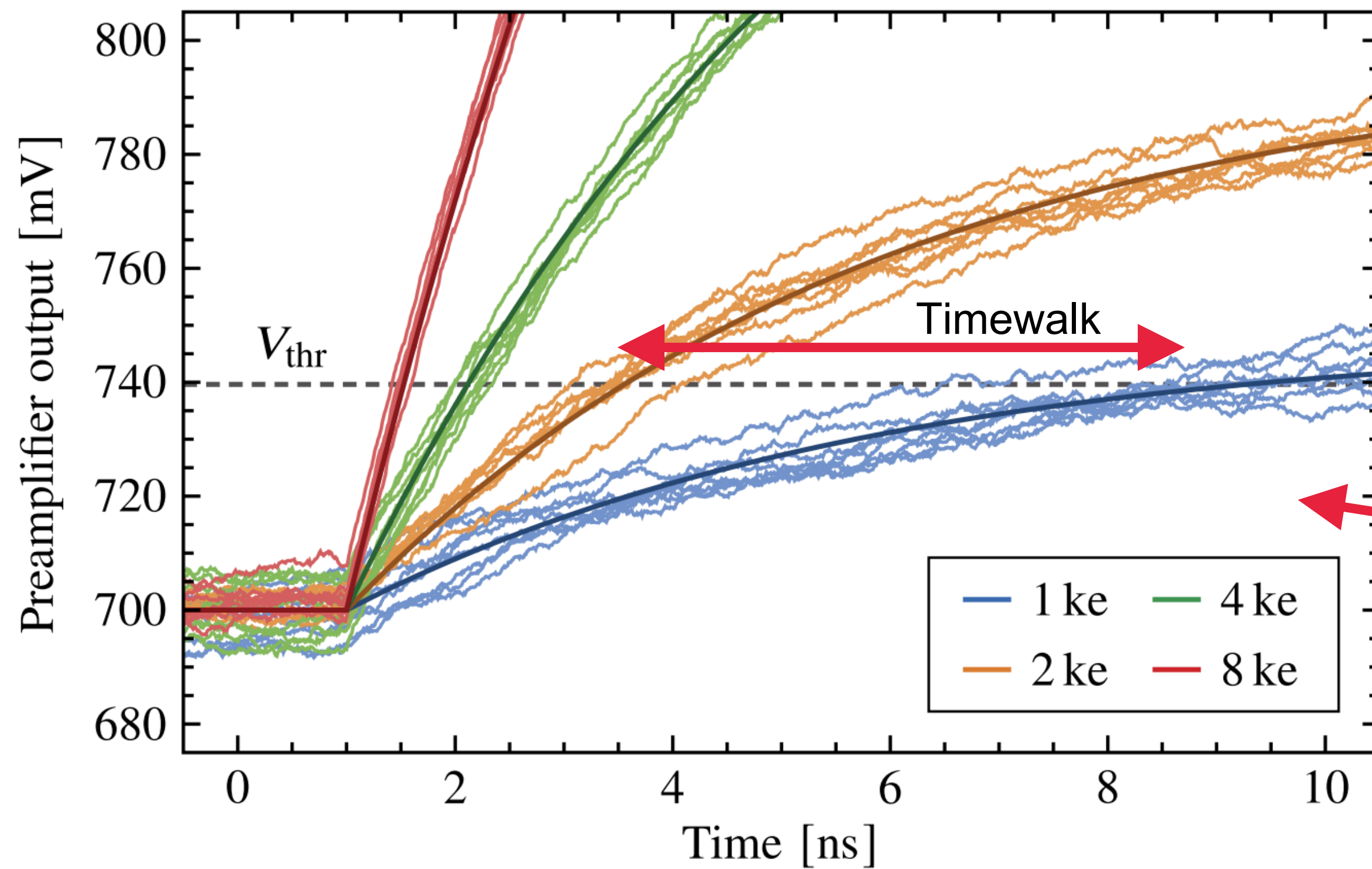
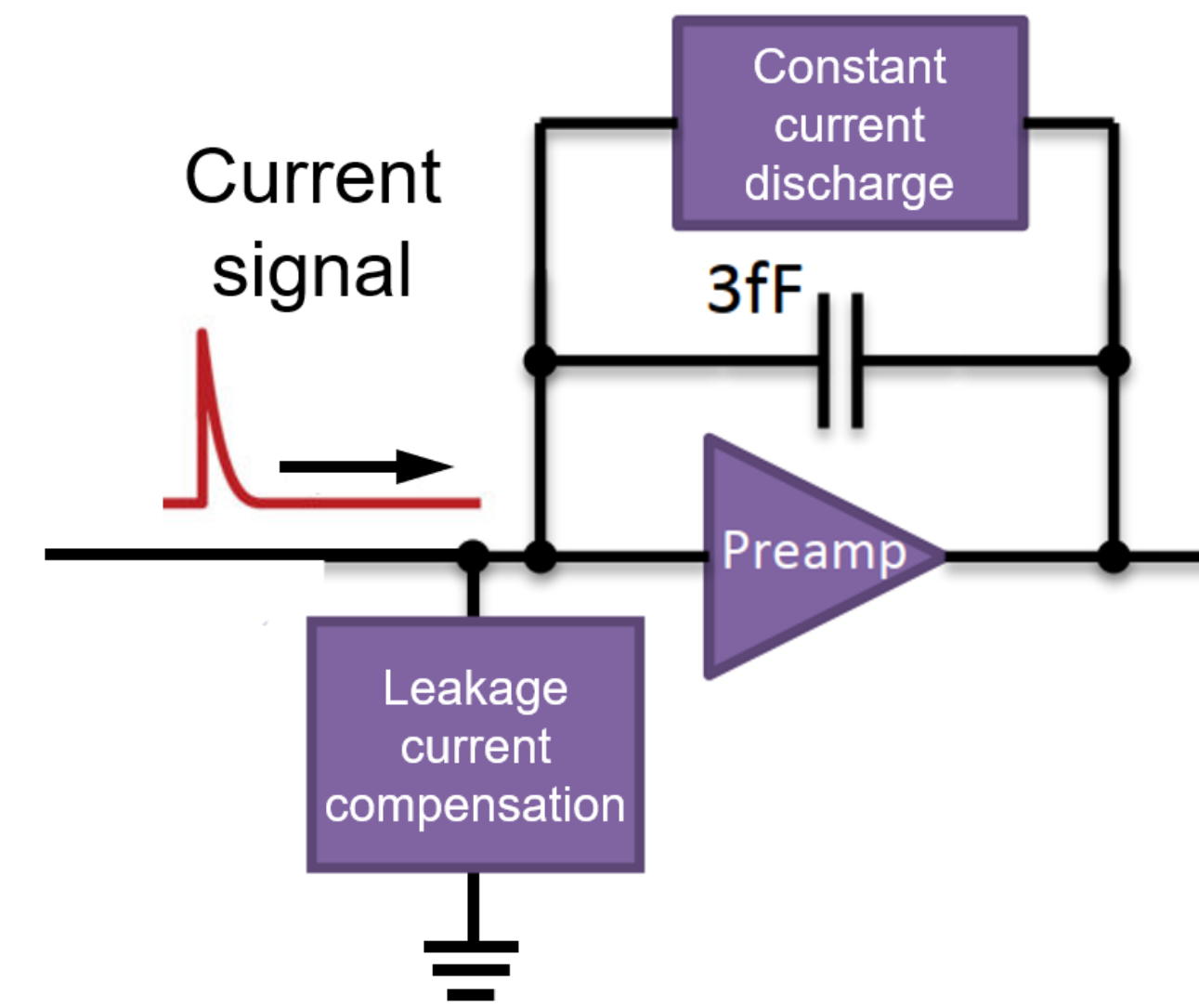


Analog front-end resolution



Timewalk

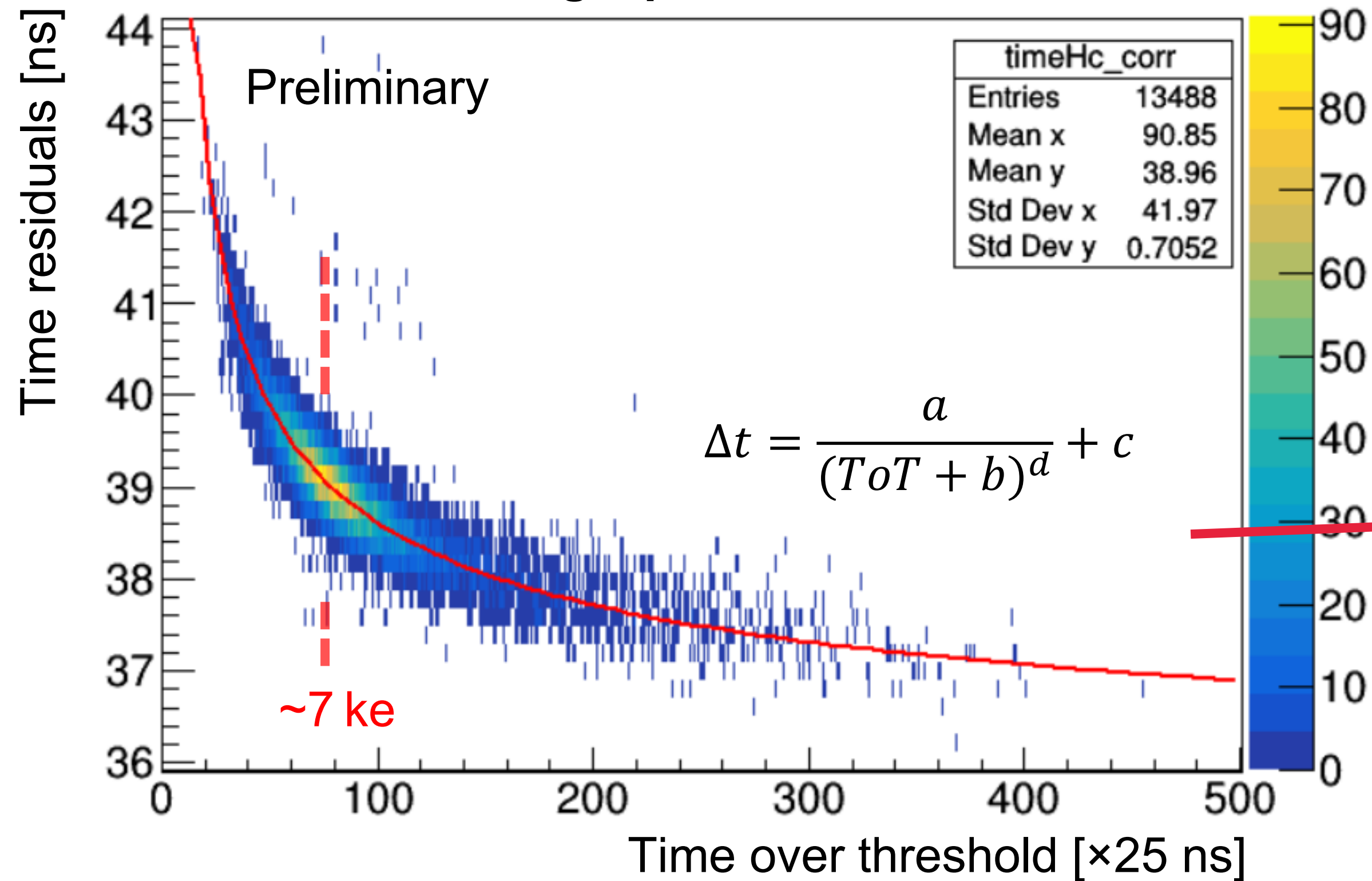
- Time measurement depends on signal size
- Preamplifier output has a fixed risetime
- Reduced signal size makes timewalk corrections crucial



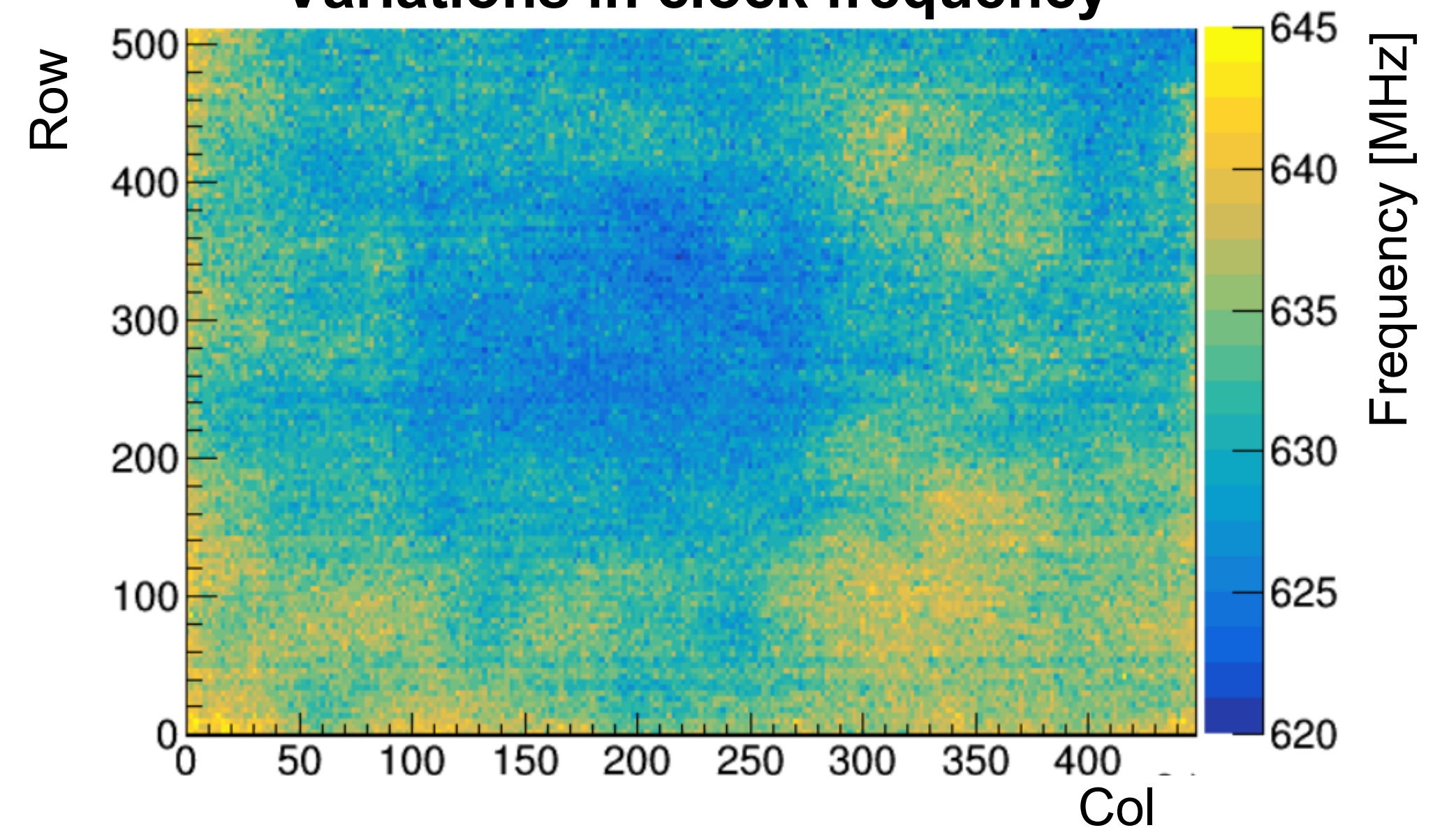
Time resolution

- Working on per-pixel timewalk corrections
- Current cluster-time resolution: ~250 ps
- Expected track-time resolution with 4 planes: ~130 ps
- Working on clock corrections to improve further

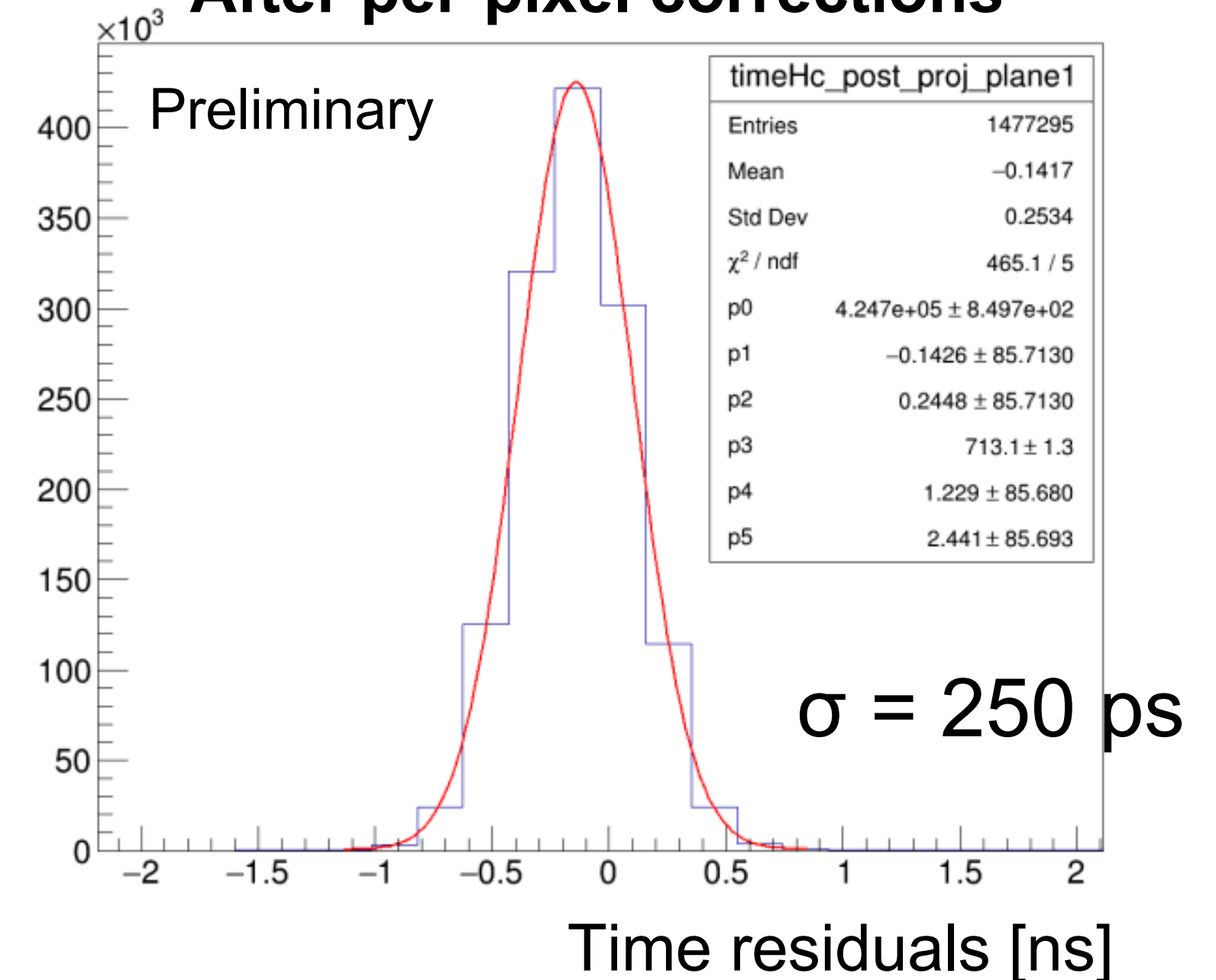
Single pixel timewalk



Variations in clock frequency

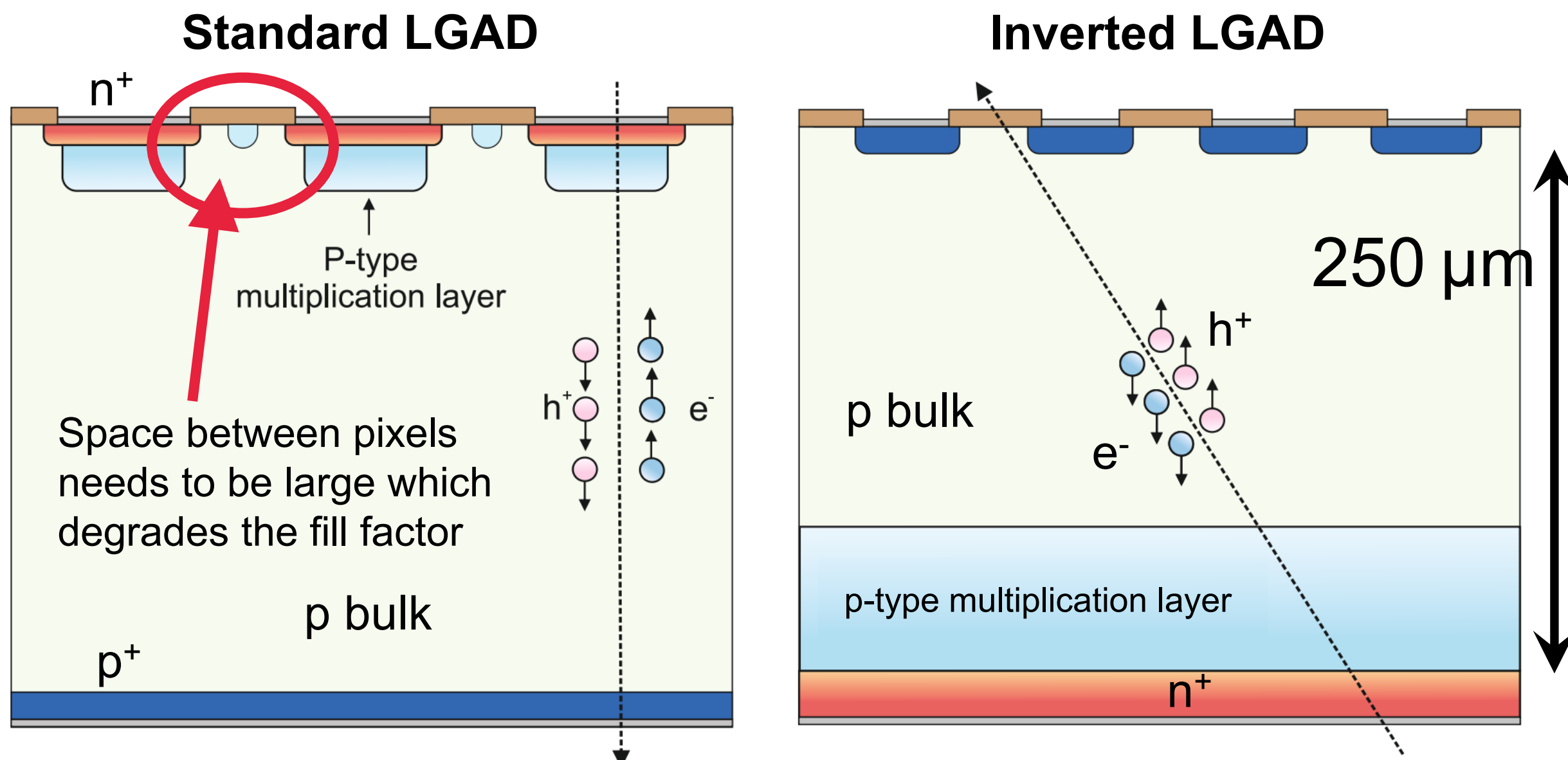


After per-pixel corrections

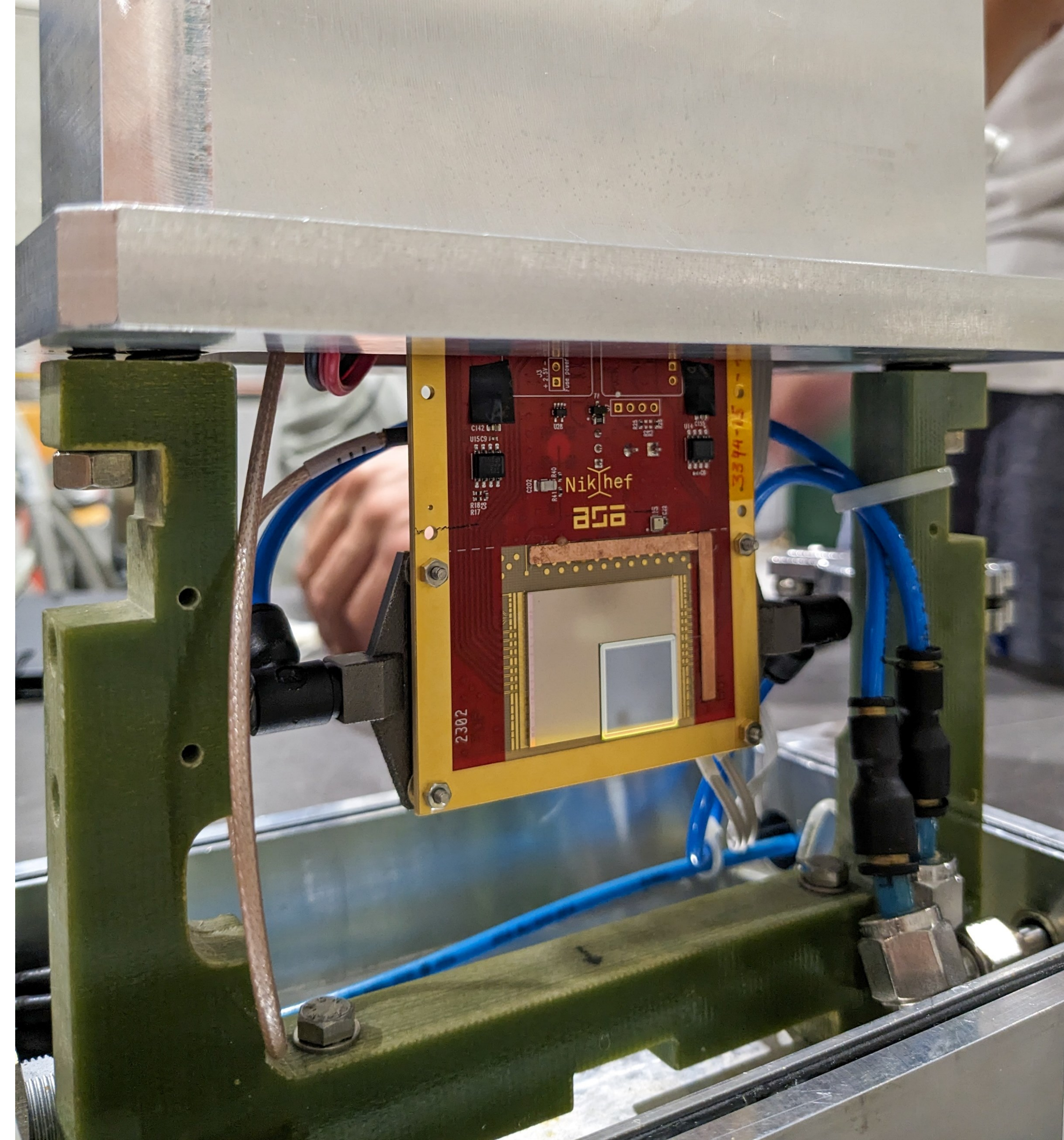


Inverted LGAD on Timepix4 as DUT

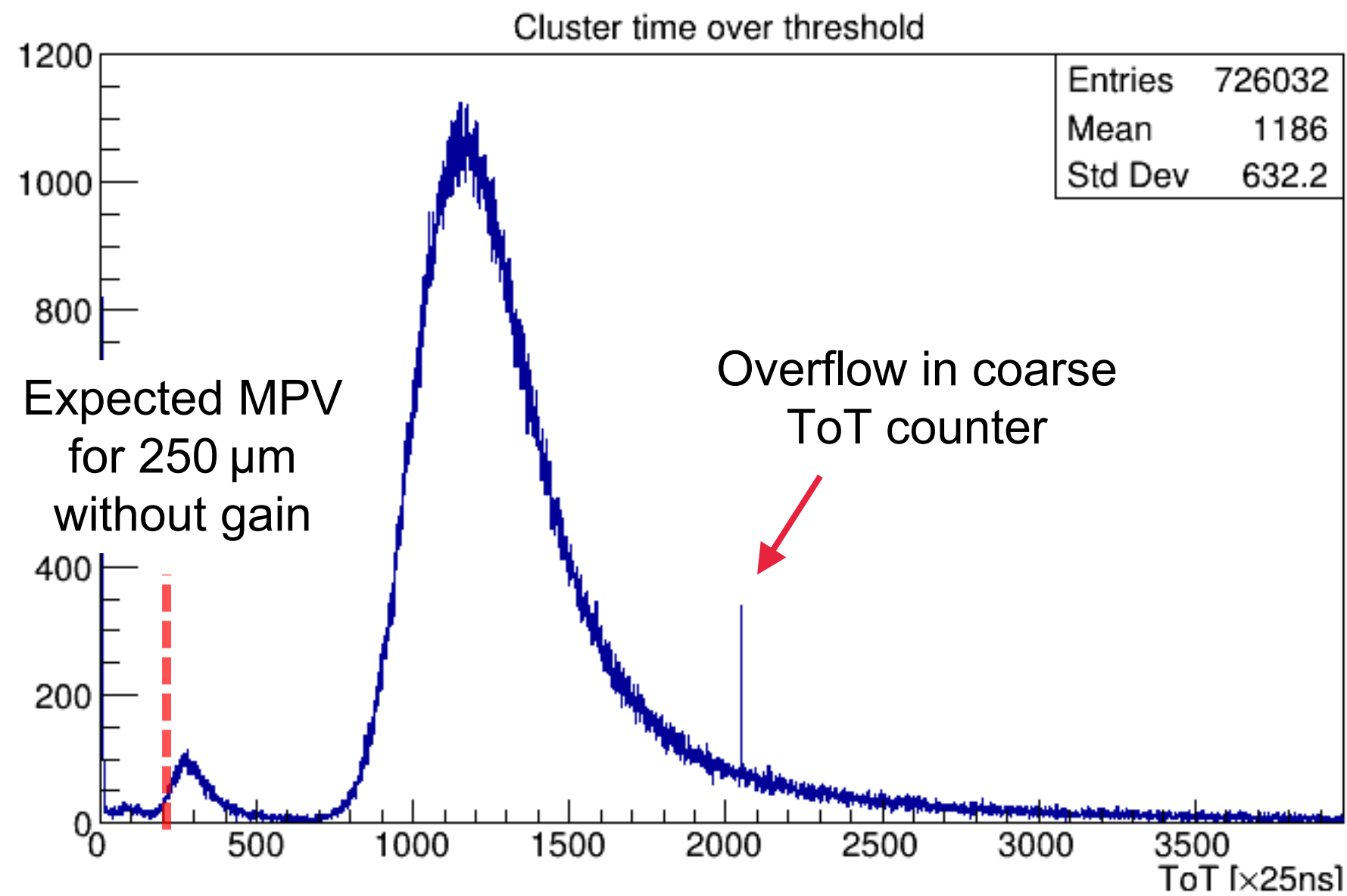
- Low-gain avalanche diodes (LGADs) use charge multiplication to deliver larger input signals
- Small pixel size cannot be achieved in standard LGAD technology (without losing efficiency)
- Inverted LGADs (iLGADs) solve this by placing the gain layer on the backside
- Sensors produced by Micron and provided by Glasgow



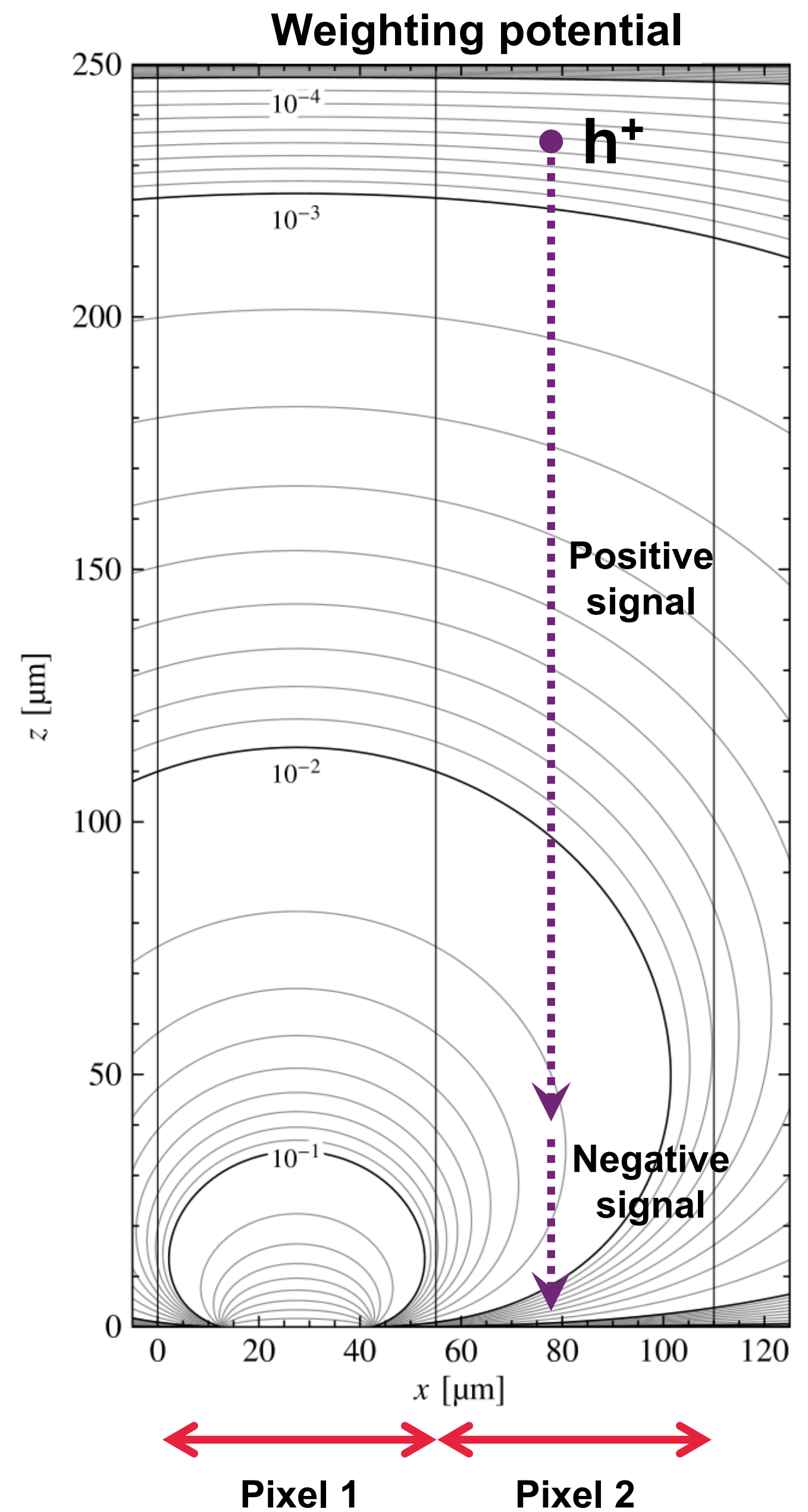
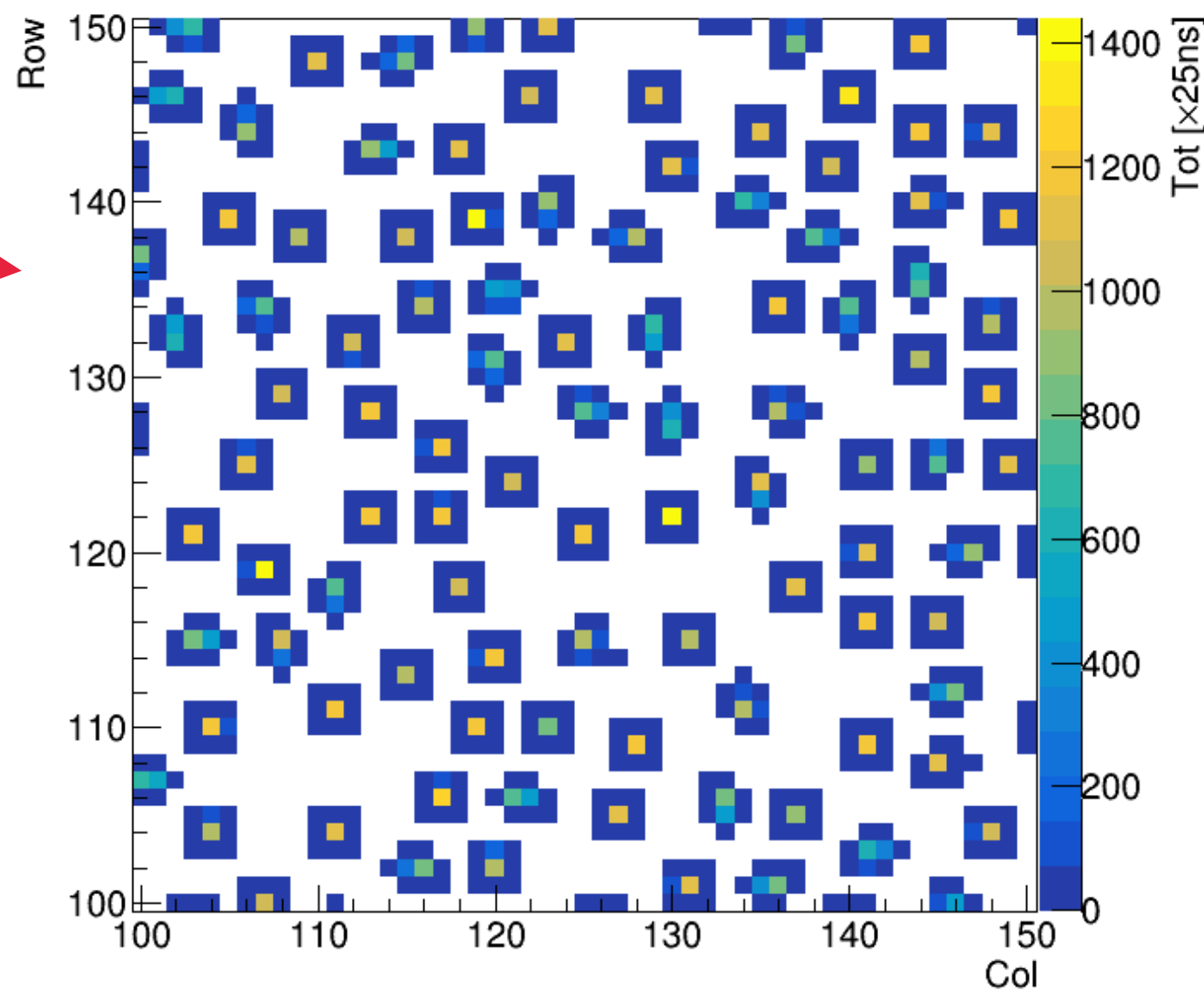
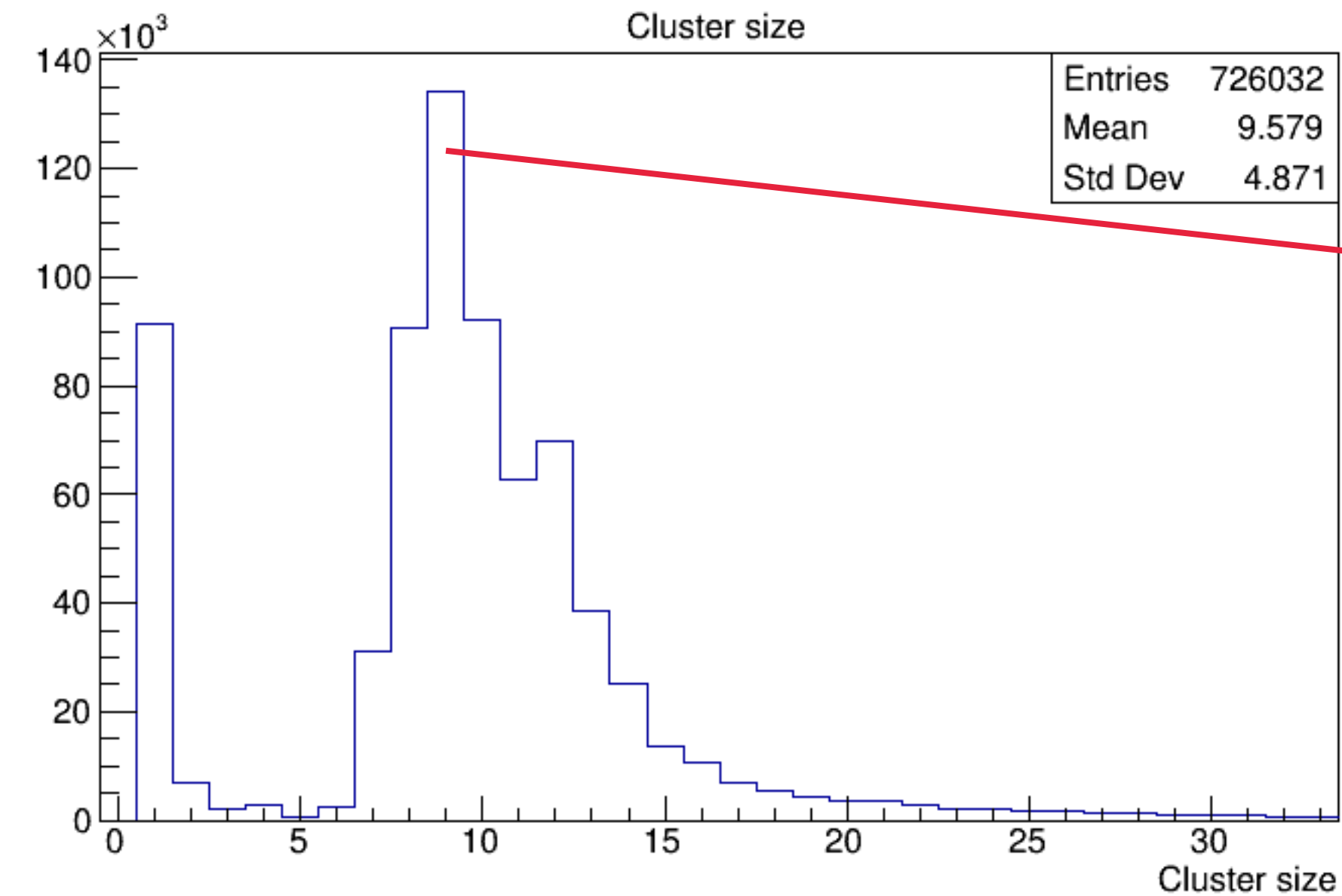
A. Doblas *et al* *Sensors* **2023**, *23*, 3450 [DOI: [10.3390/s23073450](https://doi.org/10.3390/s23073450)]



Inverted LGAD on Timepix4 as DUT (first glance)



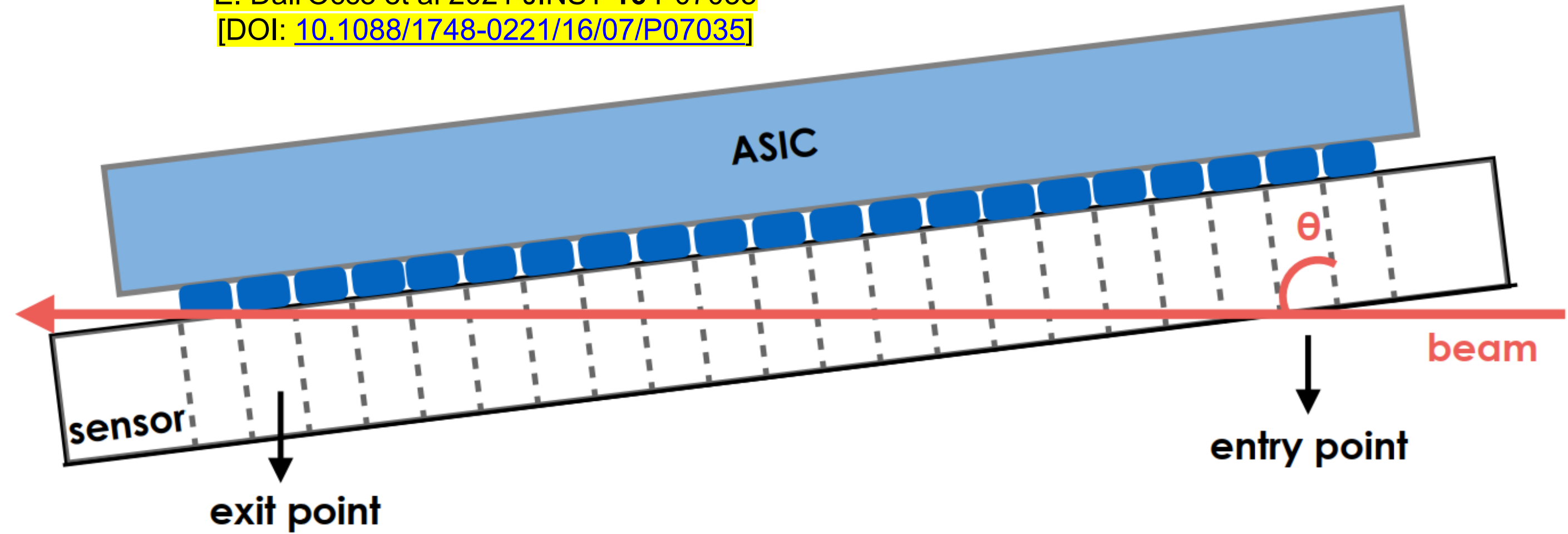
- Analysis not yet started
- Large cluster size at perpendicular beam incidence
- Cluster have skirt of low-ToT hits (< 25 ns)
- We suspect due to bipolar signals in neighbouring pixels



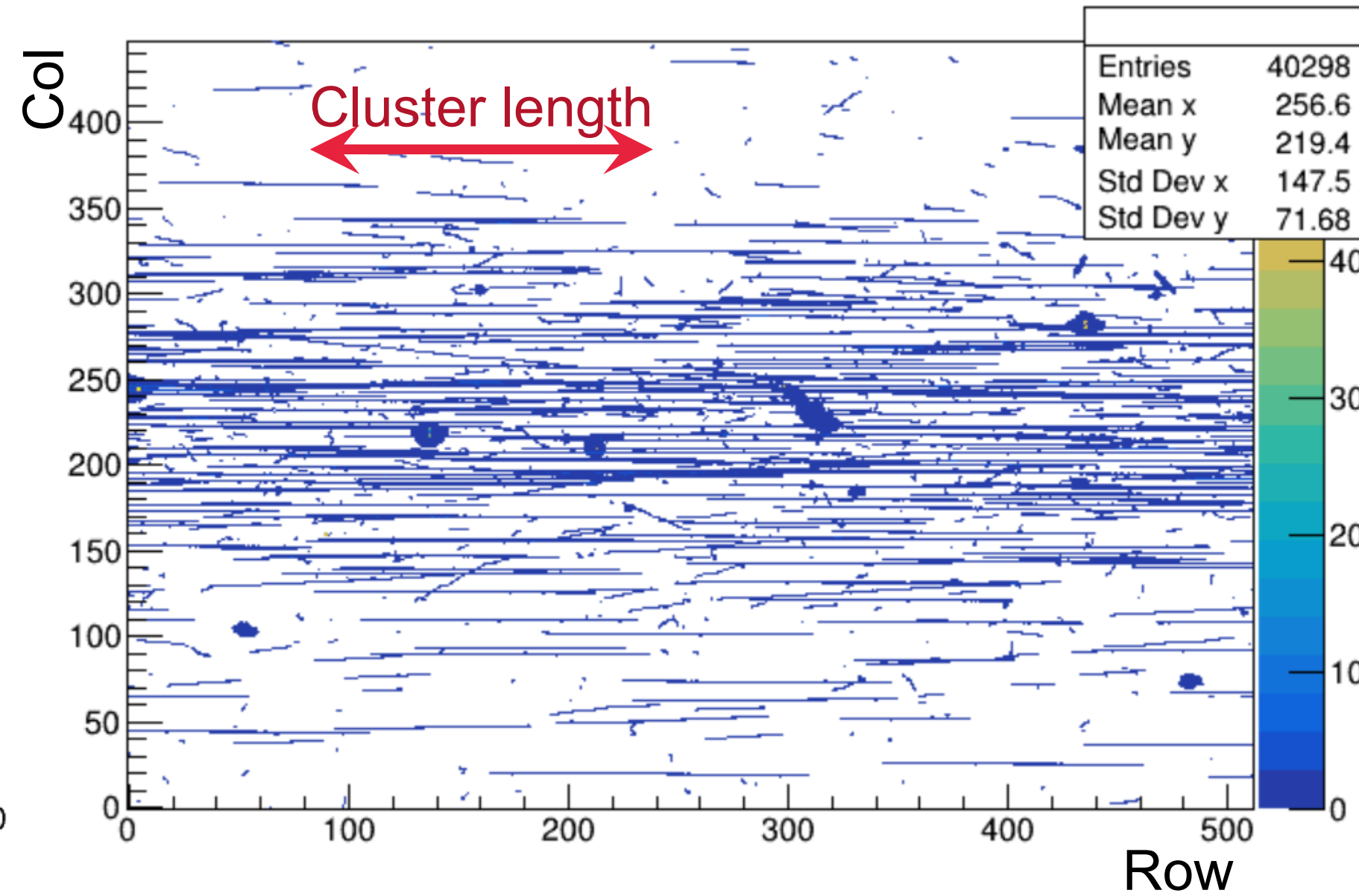
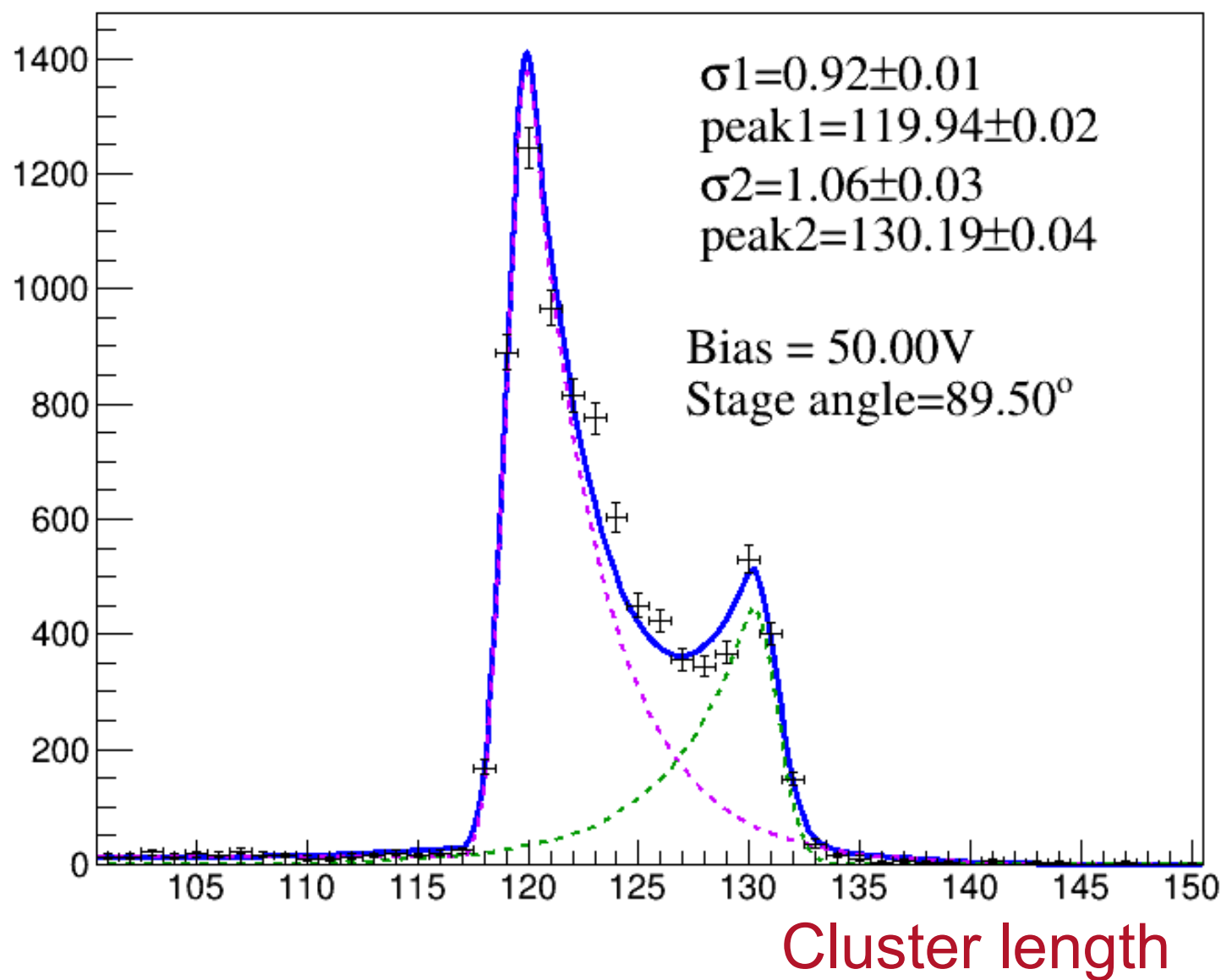
Grazing angle measurements

- Grazing angle measurements probe different depths of the sensor
- Can be used to determine thickness by measuring cluster length at various angles
- Sensors are thin, but not flat

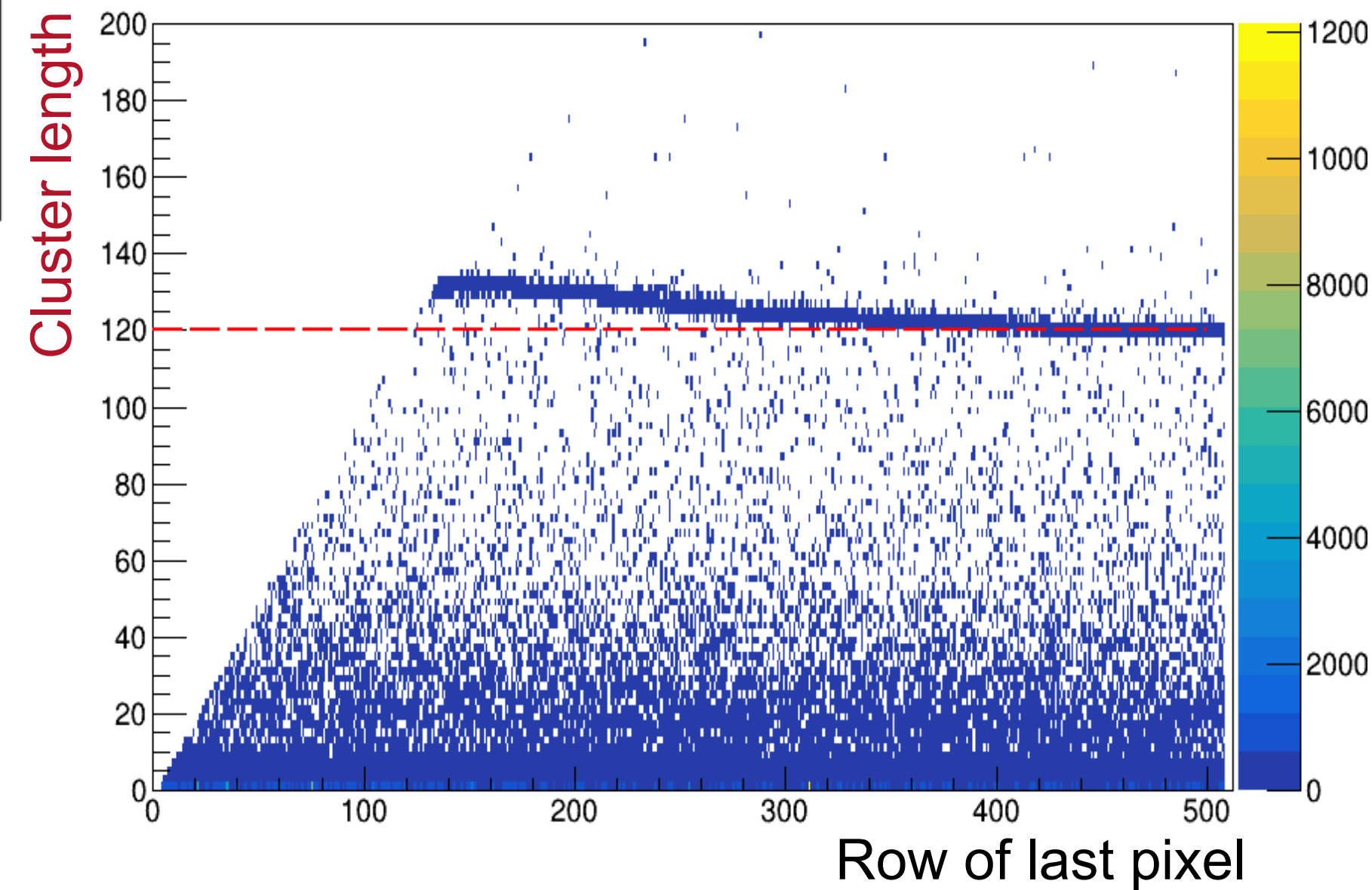
E. Dall'Occo et al 2021 JINST 16 P07035
 [DOI: [10.1088/1748-0221/16/07/P07035](https://doi.org/10.1088/1748-0221/16/07/P07035)]



N161, Pixel pitch 55um, Thickness 100um, Run 5196

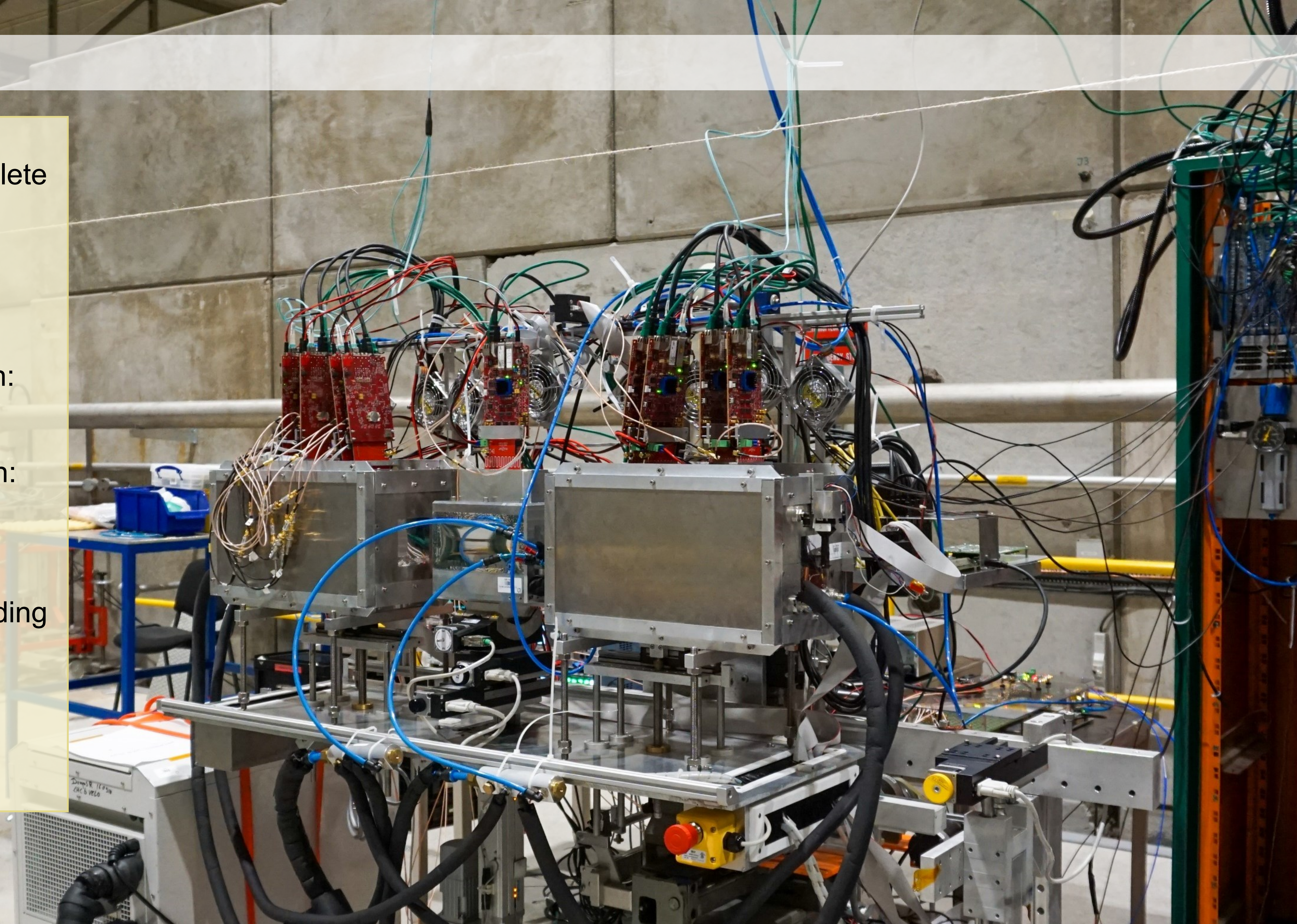


N161, Pixel pitch 55um, Thickness 100um, Run 5196



Conclusion

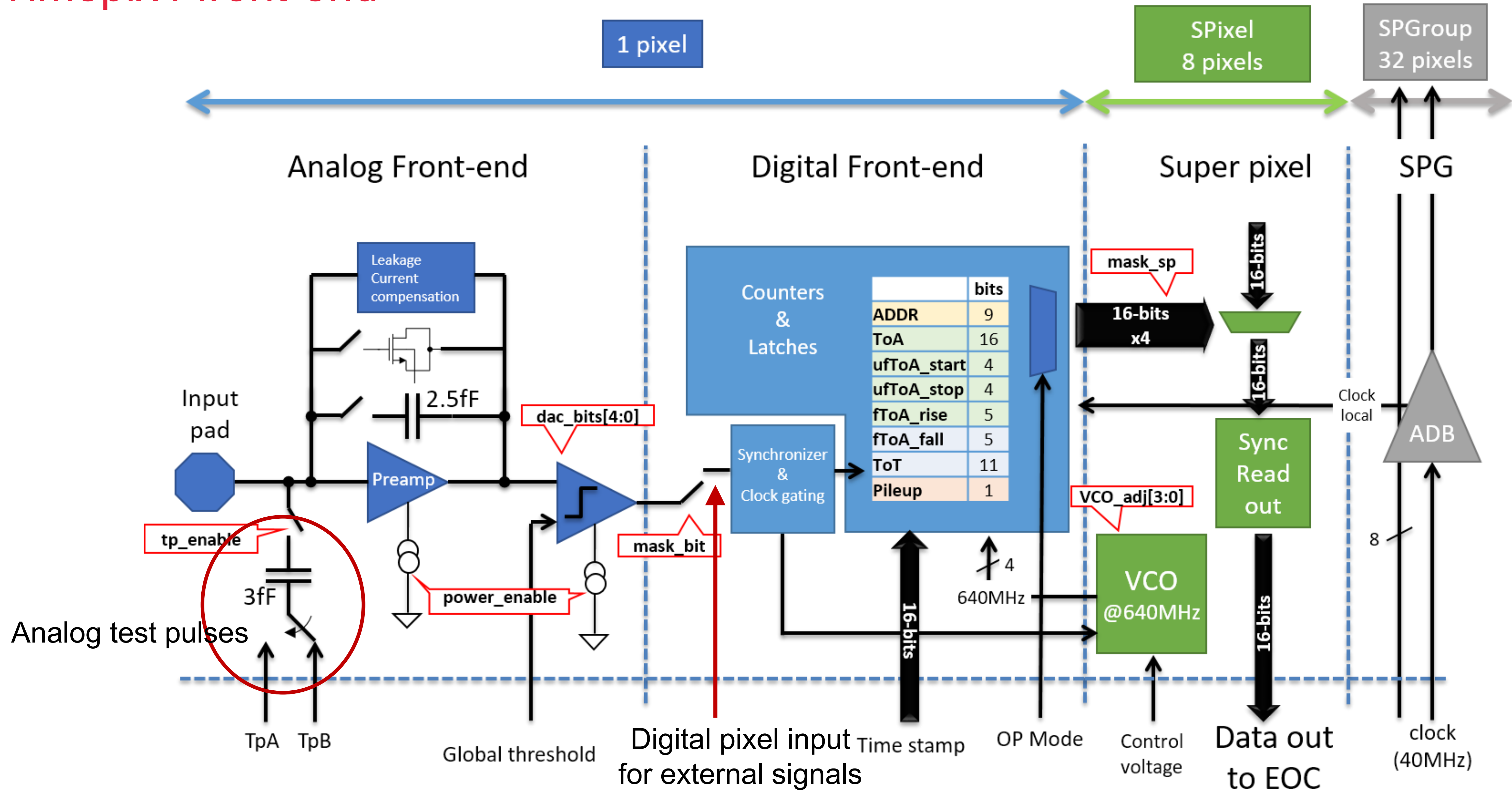
- First stable operation of complete telescope
- Current pointing resolution: $2.7 \mu\text{m}$
- Current cluster-time resolution: 250 ps
- Expected track-time resolution: 130 ps
- Plenty of data to be analysed (Better corrections/understanding of chip)
- Ready to move on to faster sensor technologies



Backup slides

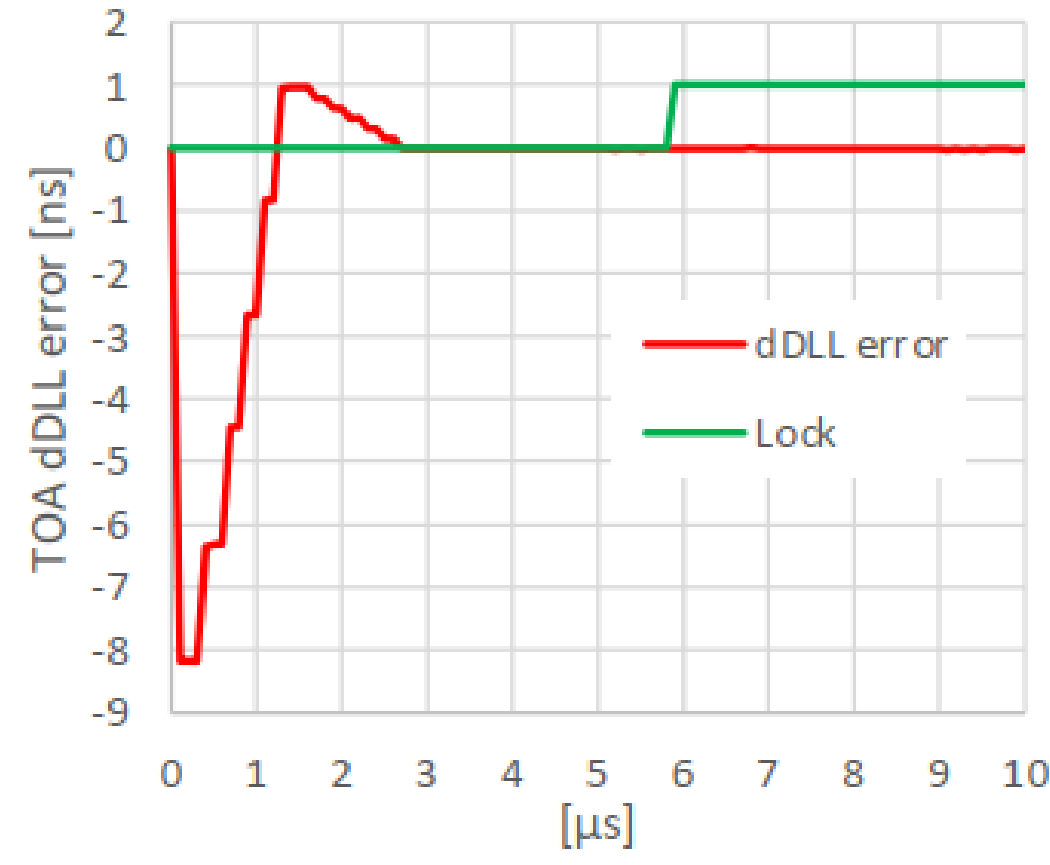
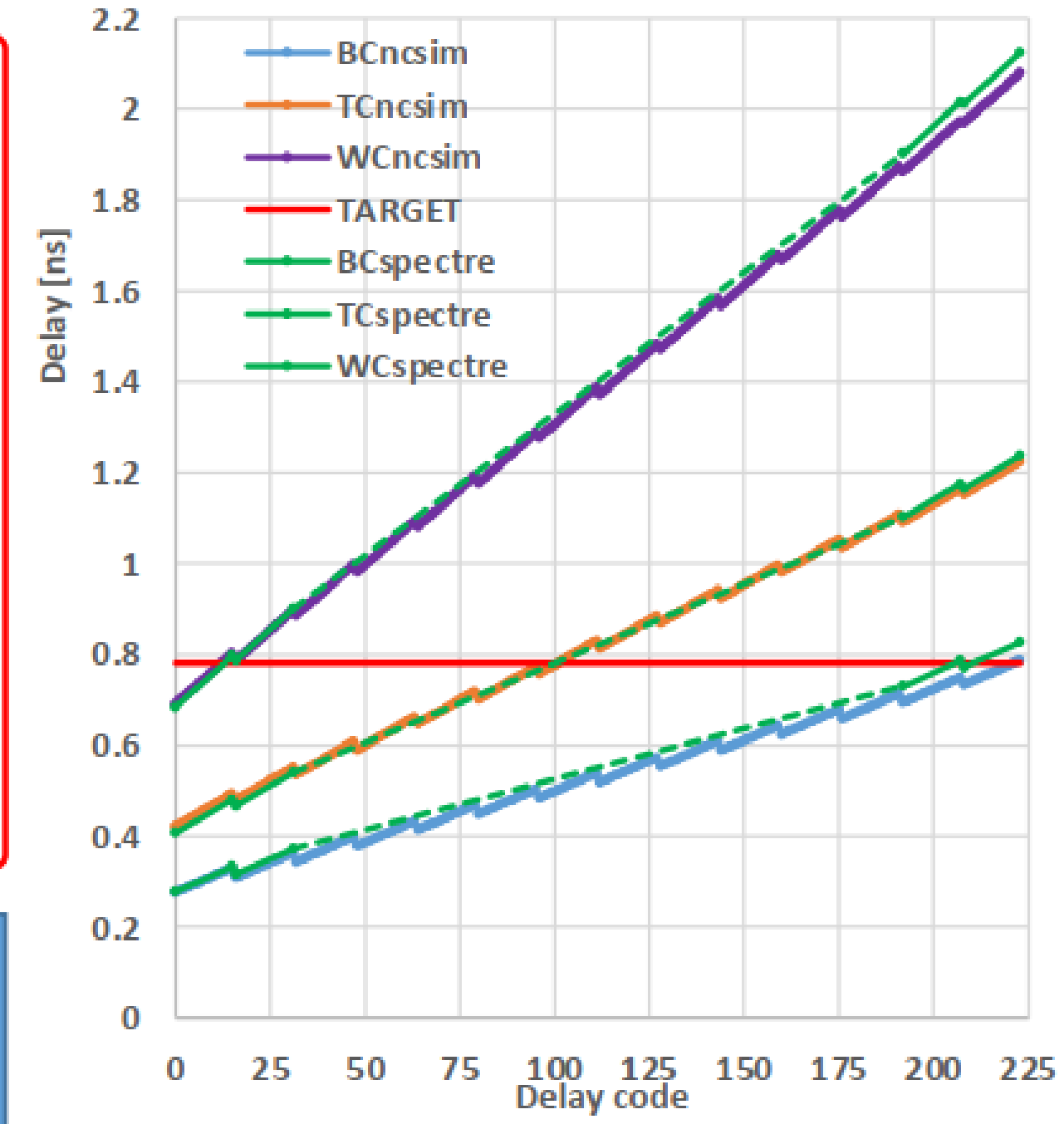
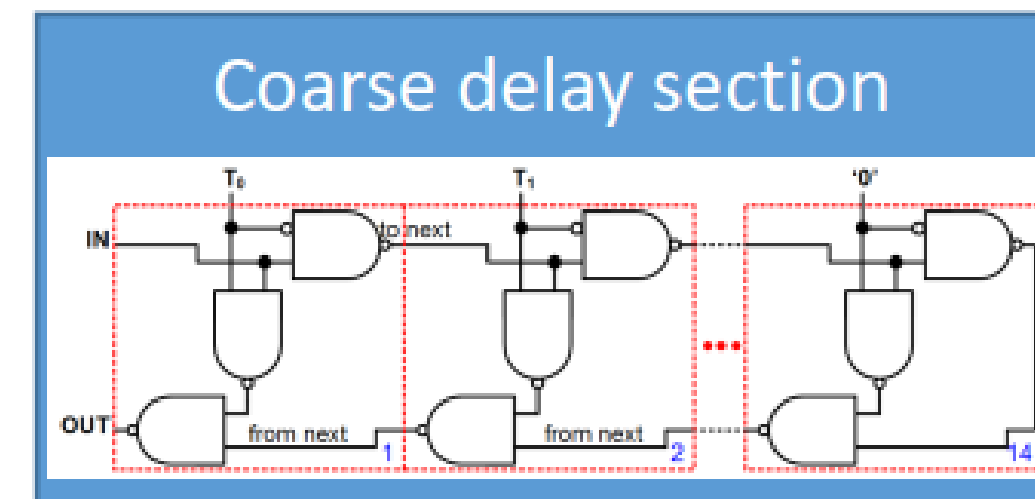
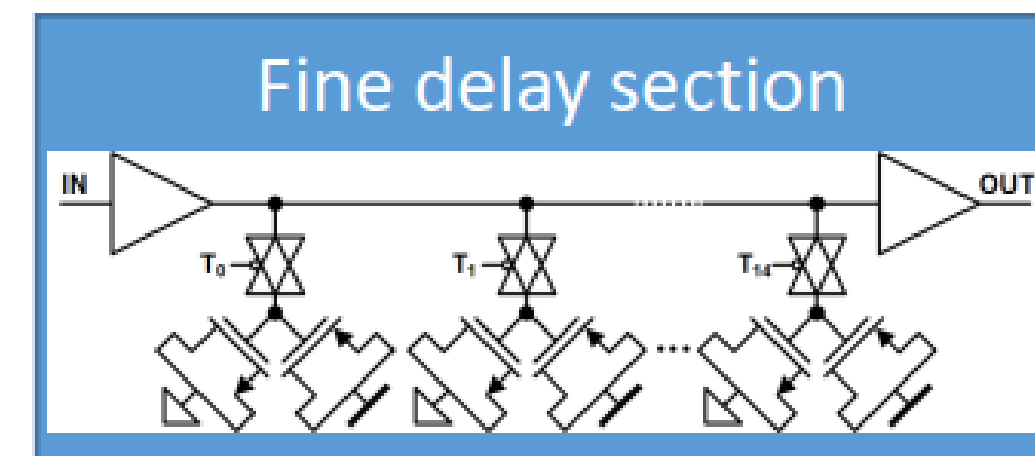
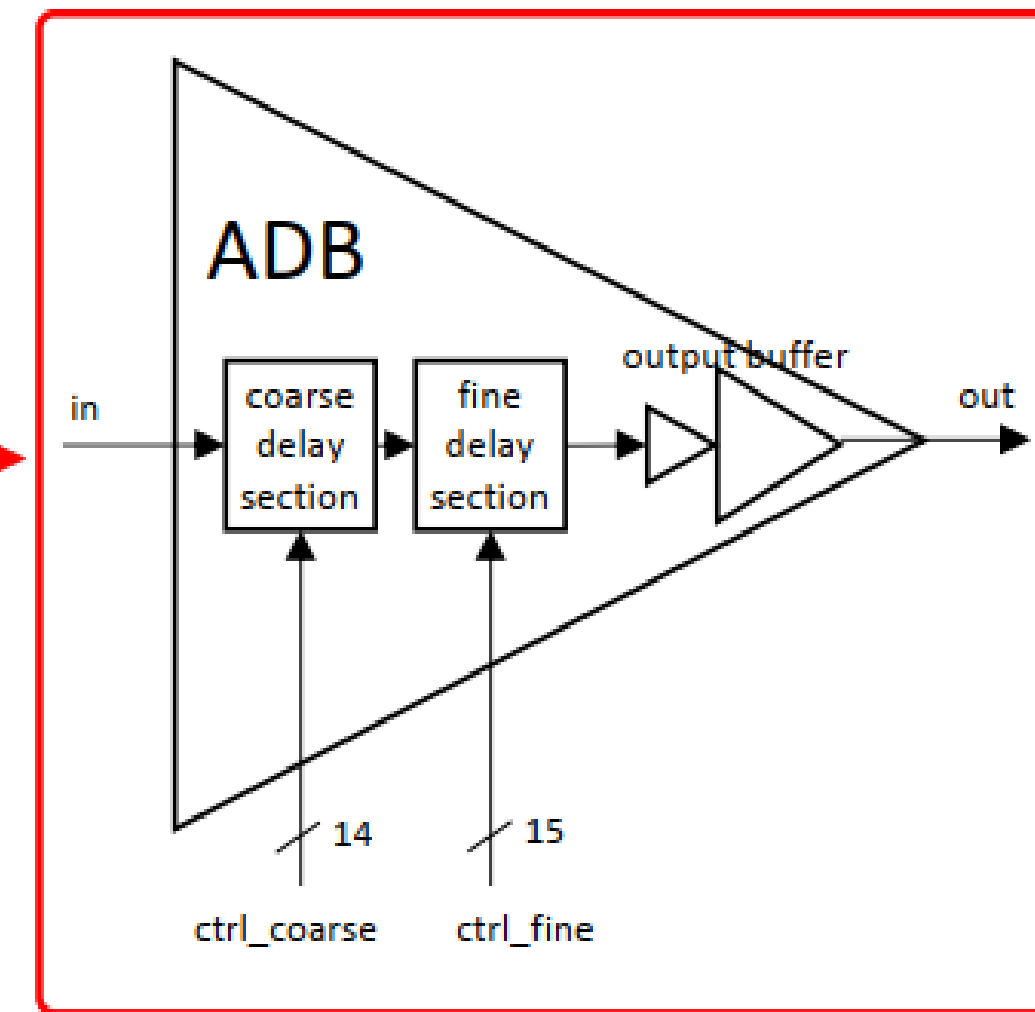
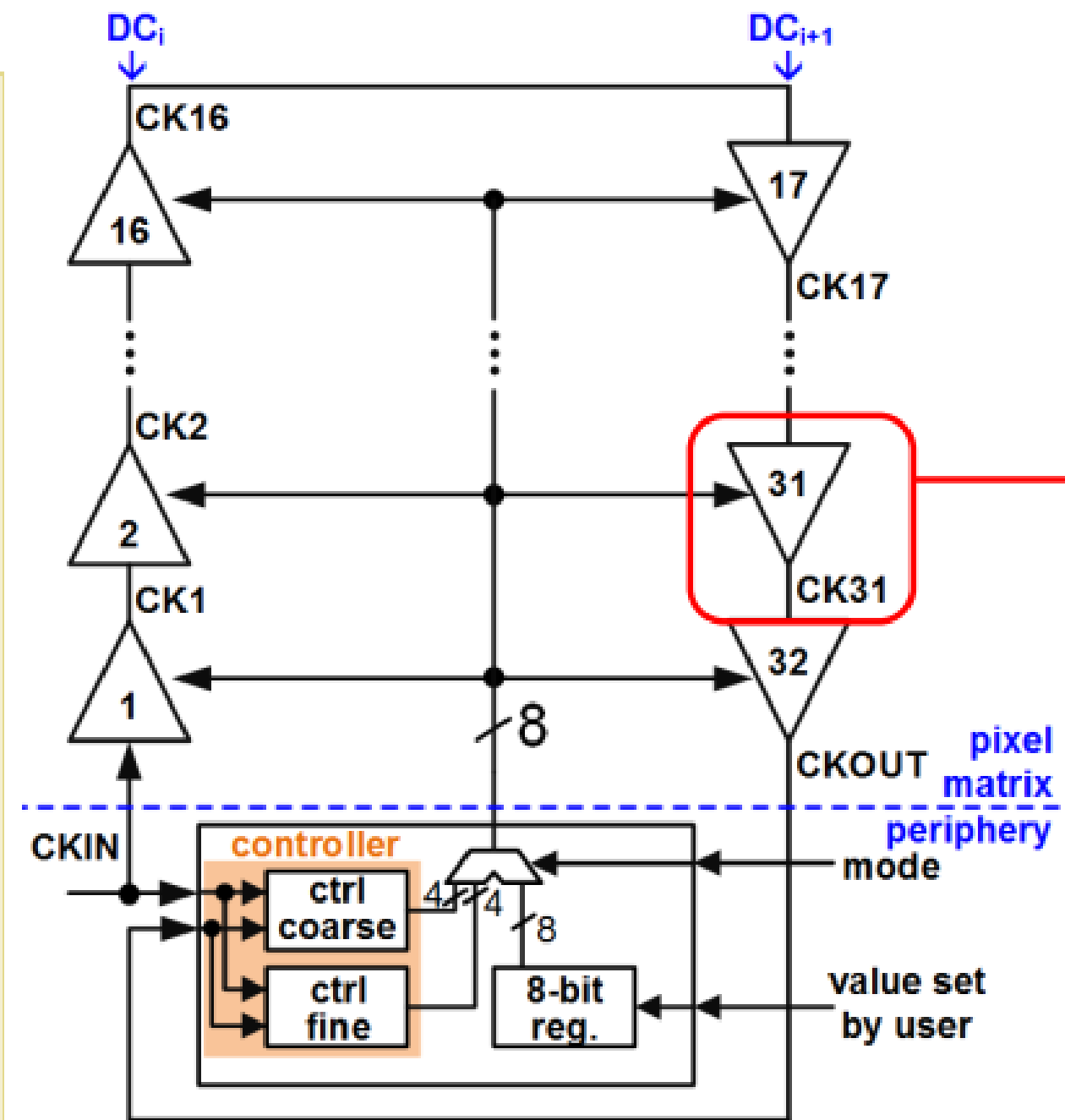


Timepix4 front-end



Clock distribution – Column digital locked loop (DLL)

- The column DLL distributes the clock along the columns
- The adjustable delay buffers (ADBs) precisely define the clock phase in each pixel group
- Controller tunes the total delay to 25 ns
- Possible to set the delay manually
- Individual ADB stations can be bypassed

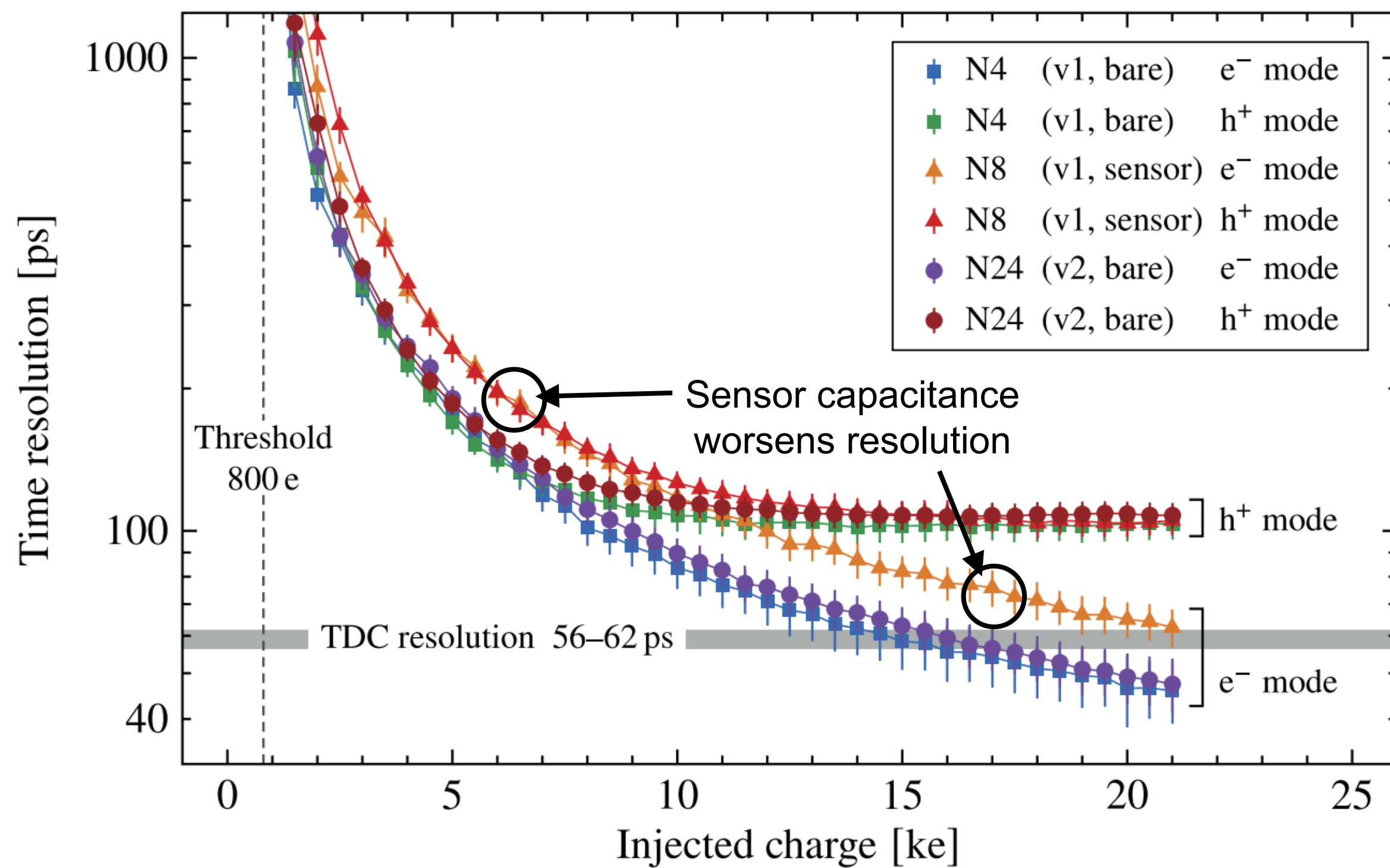


~22.7 mW/cm² to distribute a 40 MHz clock with a 100 ps_{rms}

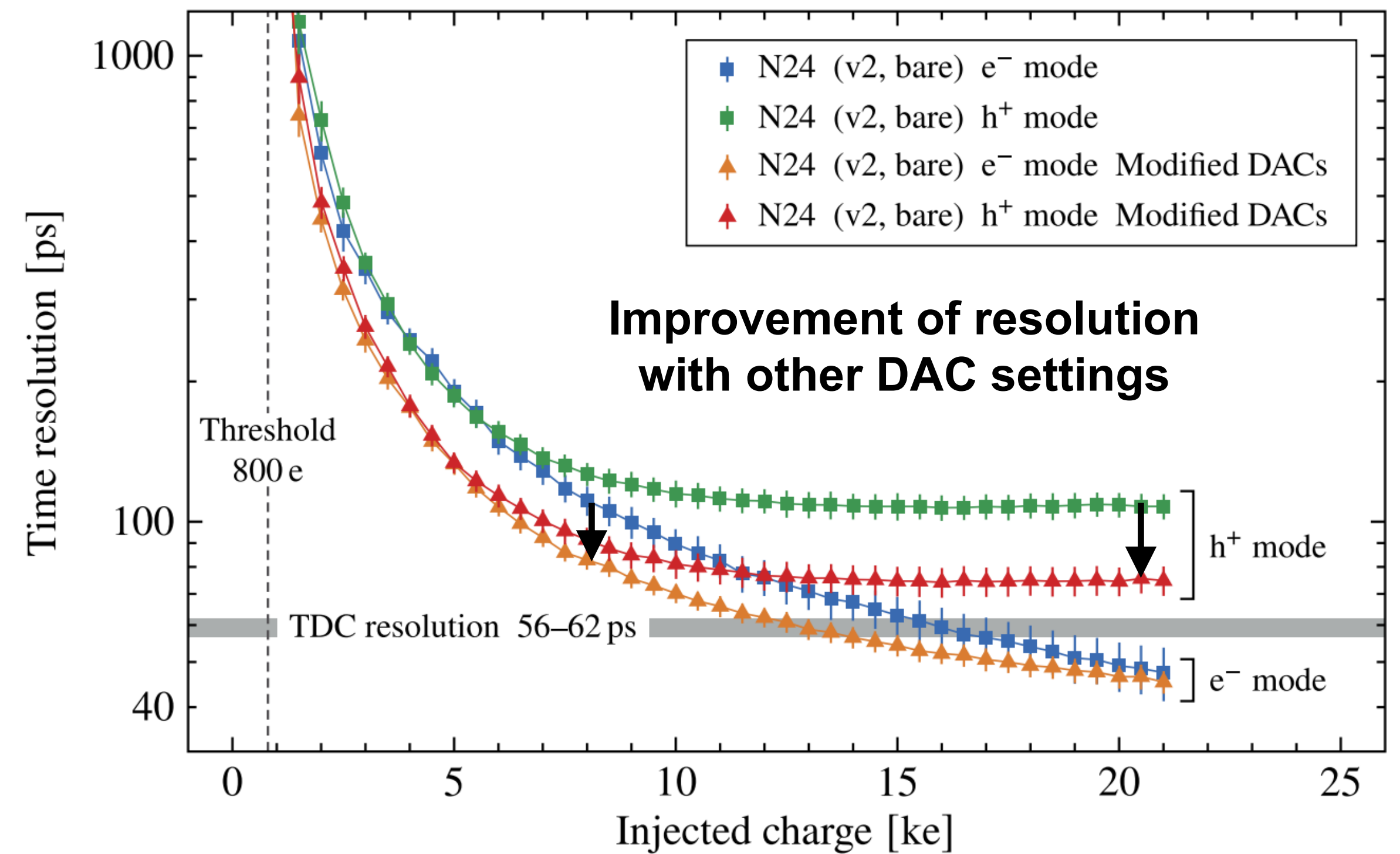
Timepix4 – Analog front-end jitter

- Time resolution in h^+ mode limited to 75–105 ps depending on DAC settings
- Pixel capacitance decreases the time resolution
(see R. Ballabriga *et al* NIM A 1045 (2023) 167489 [DOI: [10.1016/j.nima.2022.167489](https://doi.org/10.1016/j.nima.2022.167489)])

Analog front-end time resolution vs signal charge



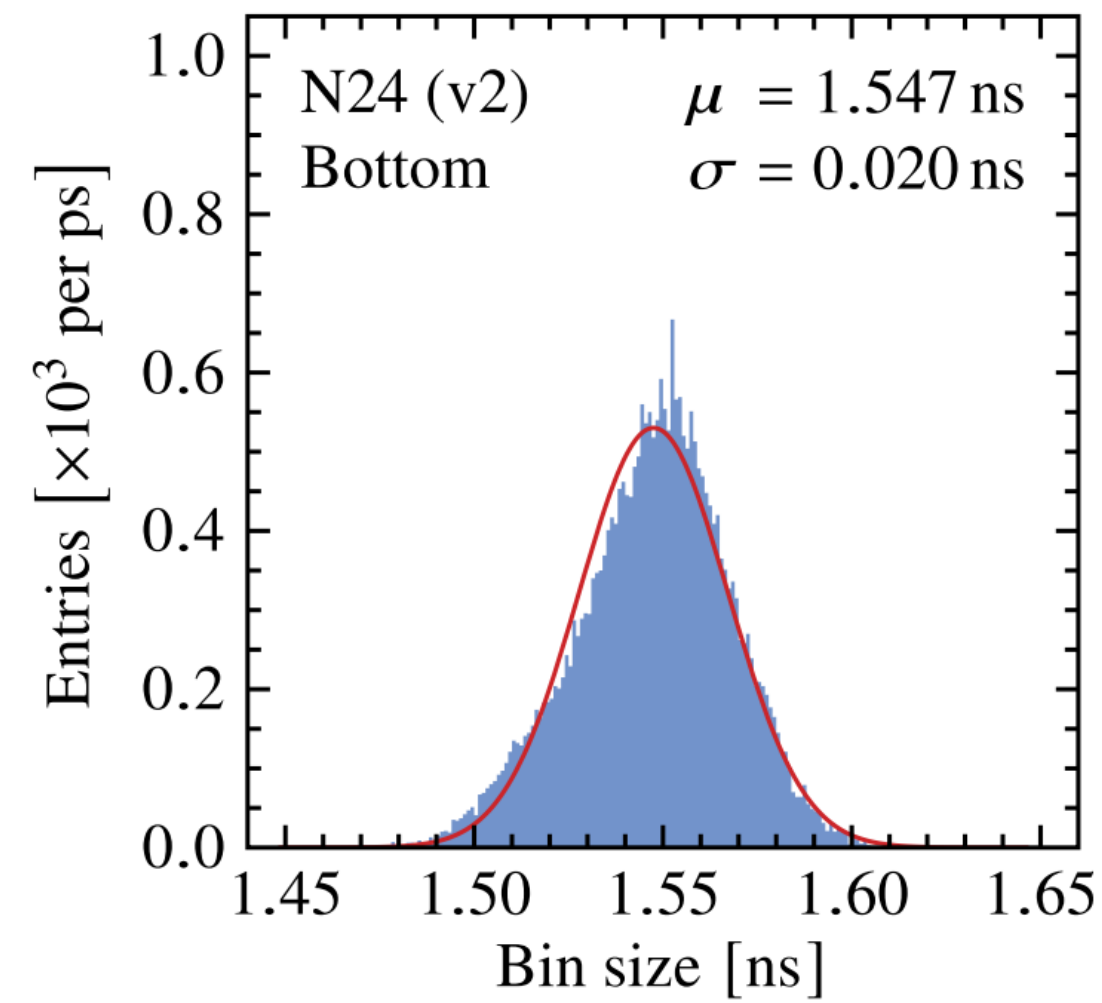
K. Heijhoff *et al* 2022 JINST 17 P07006 [DOI: [10.1088/1748-0221/17/07/P07006](https://doi.org/10.1088/1748-0221/17/07/P07006)]



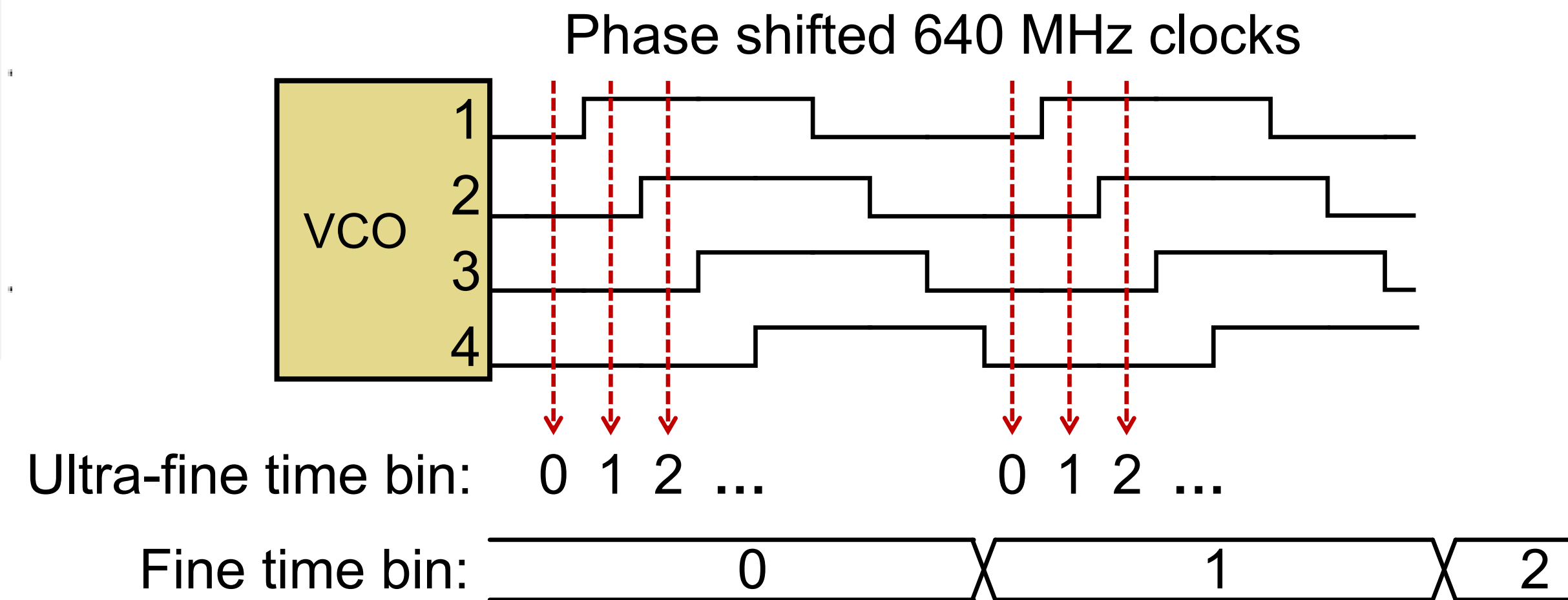
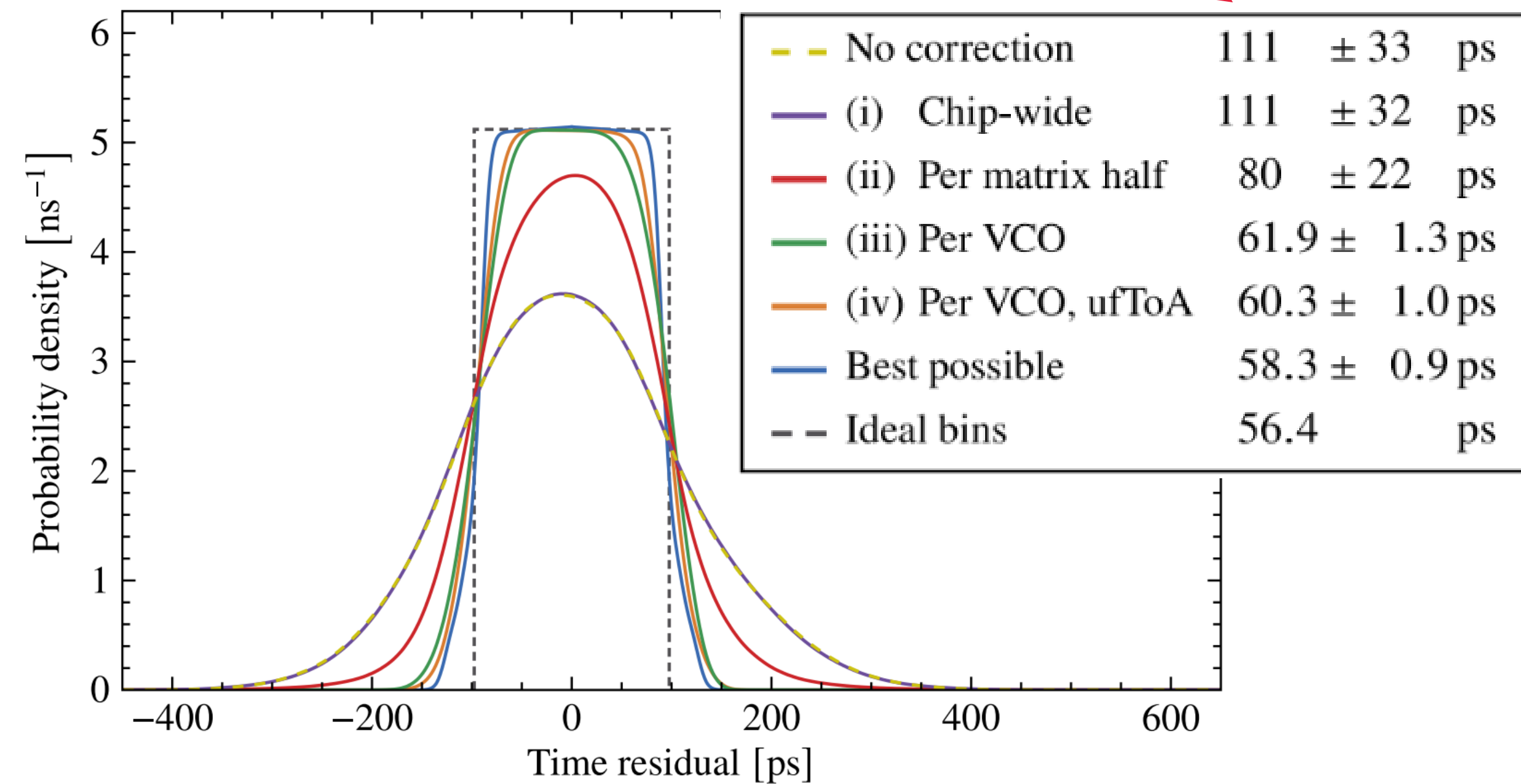
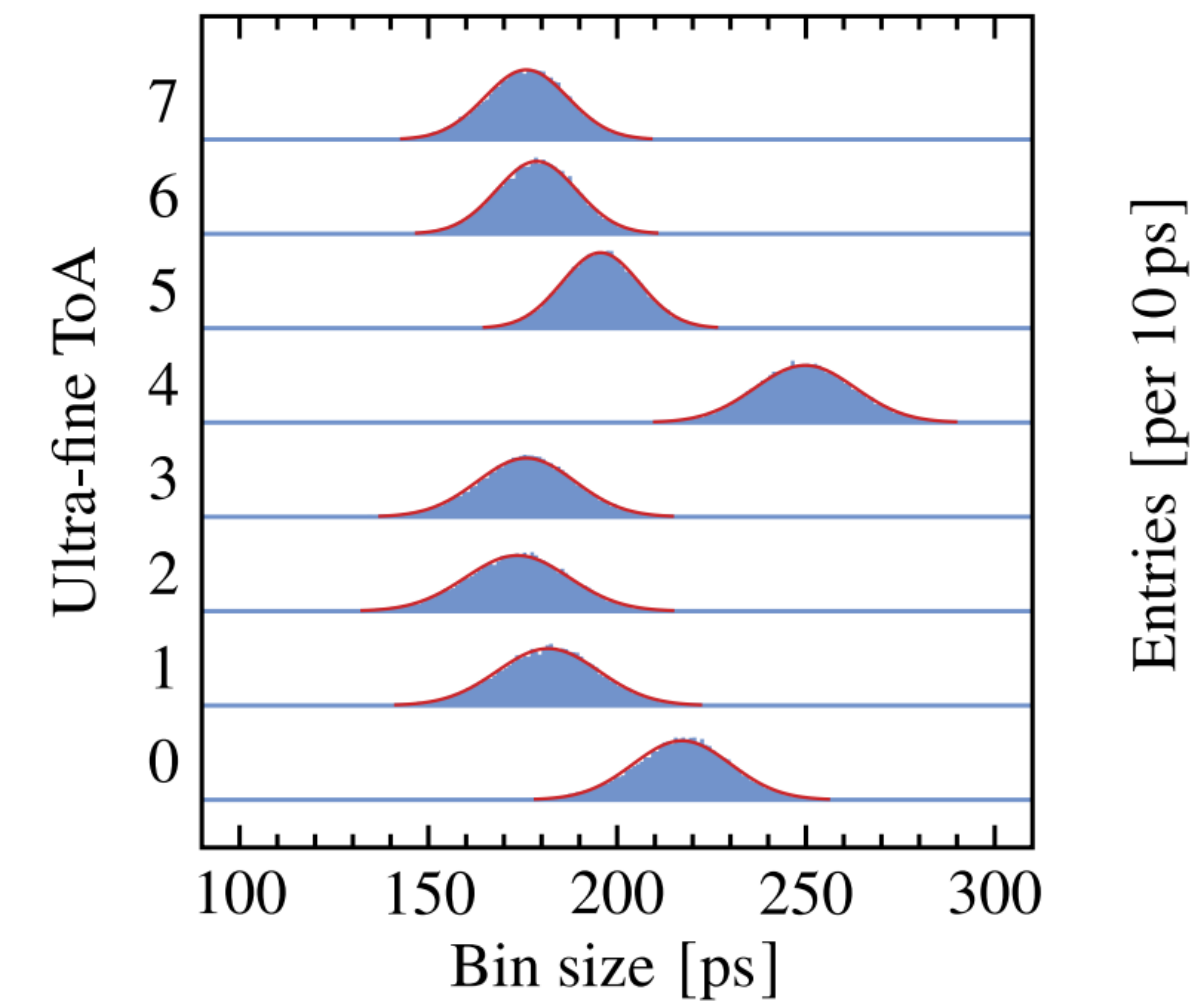
TDC resolution

- Variation in the VCO frequency over the pixel matrix observed:
 Bottom half: $1.547 \text{ ns} \pm 20 \text{ ps}$
 Top half: $1.583 \text{ ns} \pm 14 \text{ ps}$
- Structure in ultra-fine time bins has a small impact on TDC resolution (few %)
- We have tried to predict the TDC resolution for correction methods of increasing complexity

Fine time bins (640 MHz)

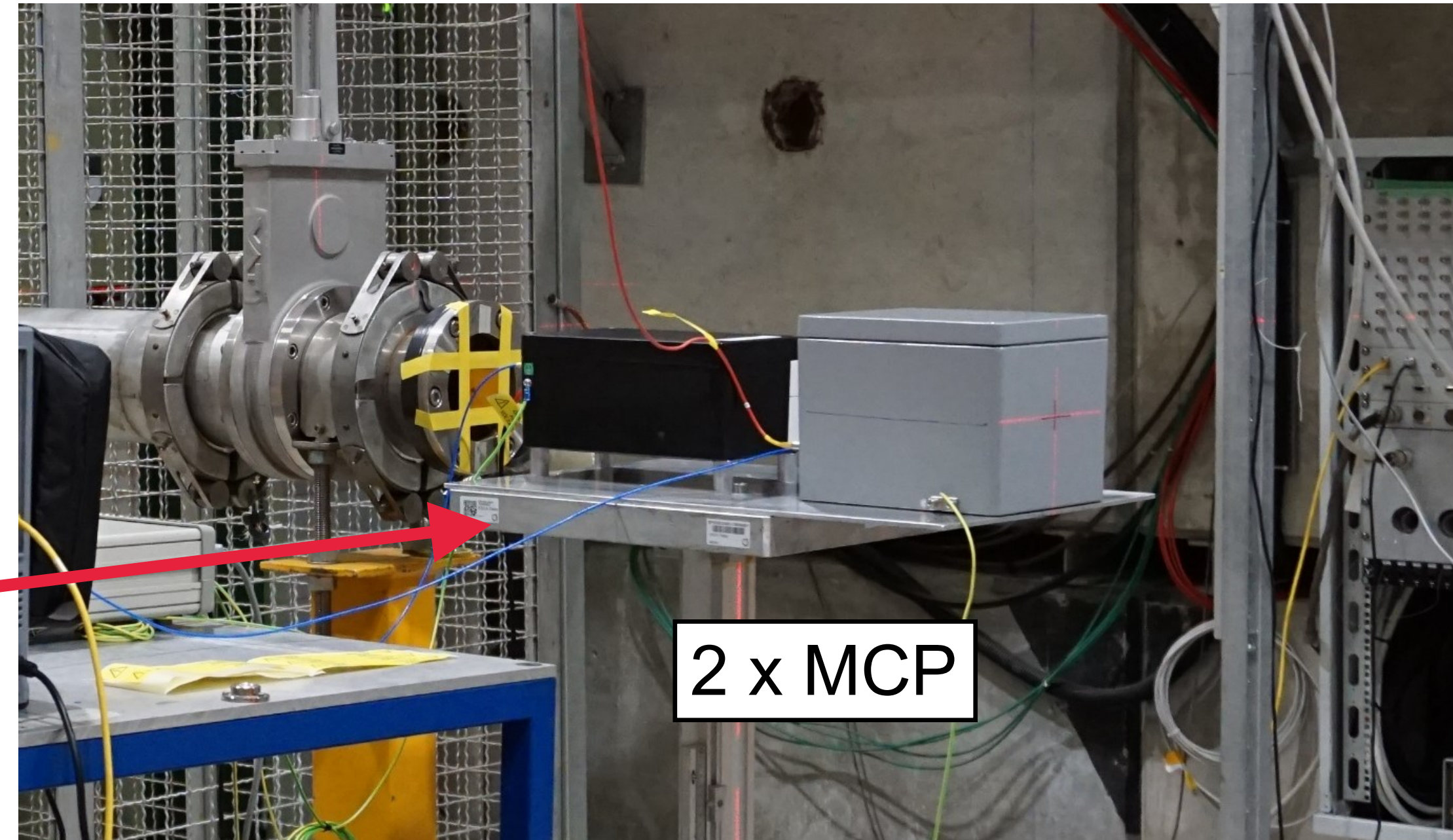
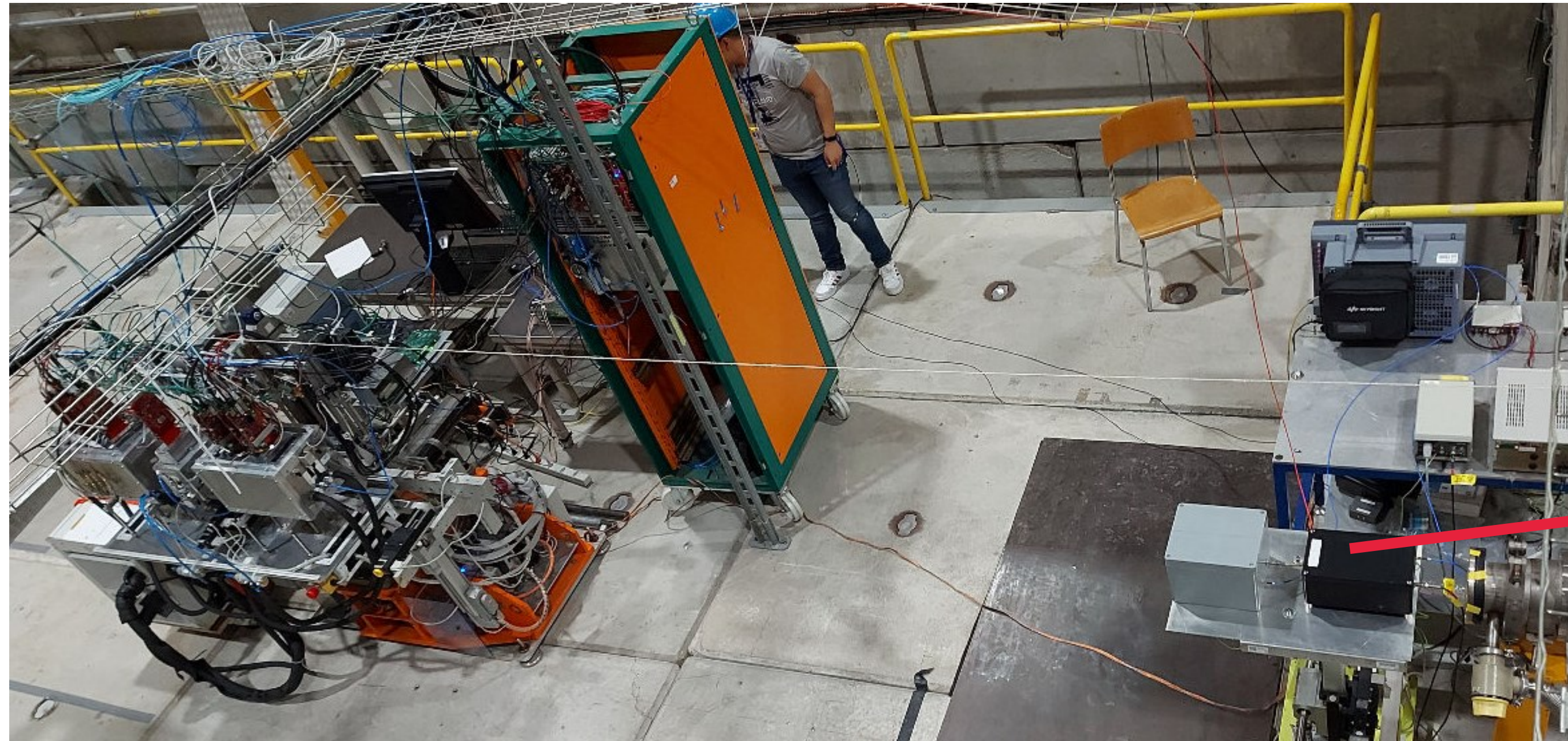
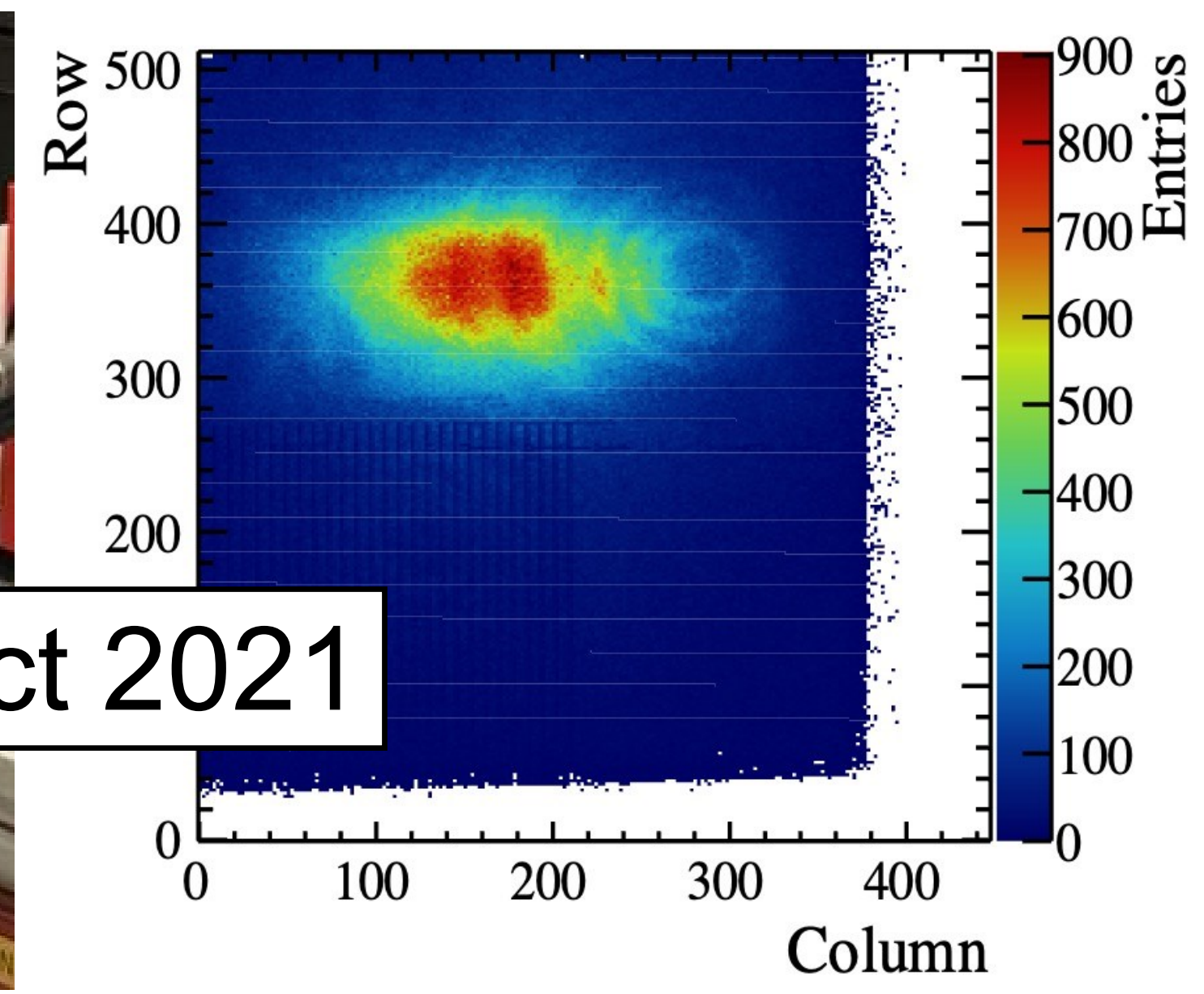
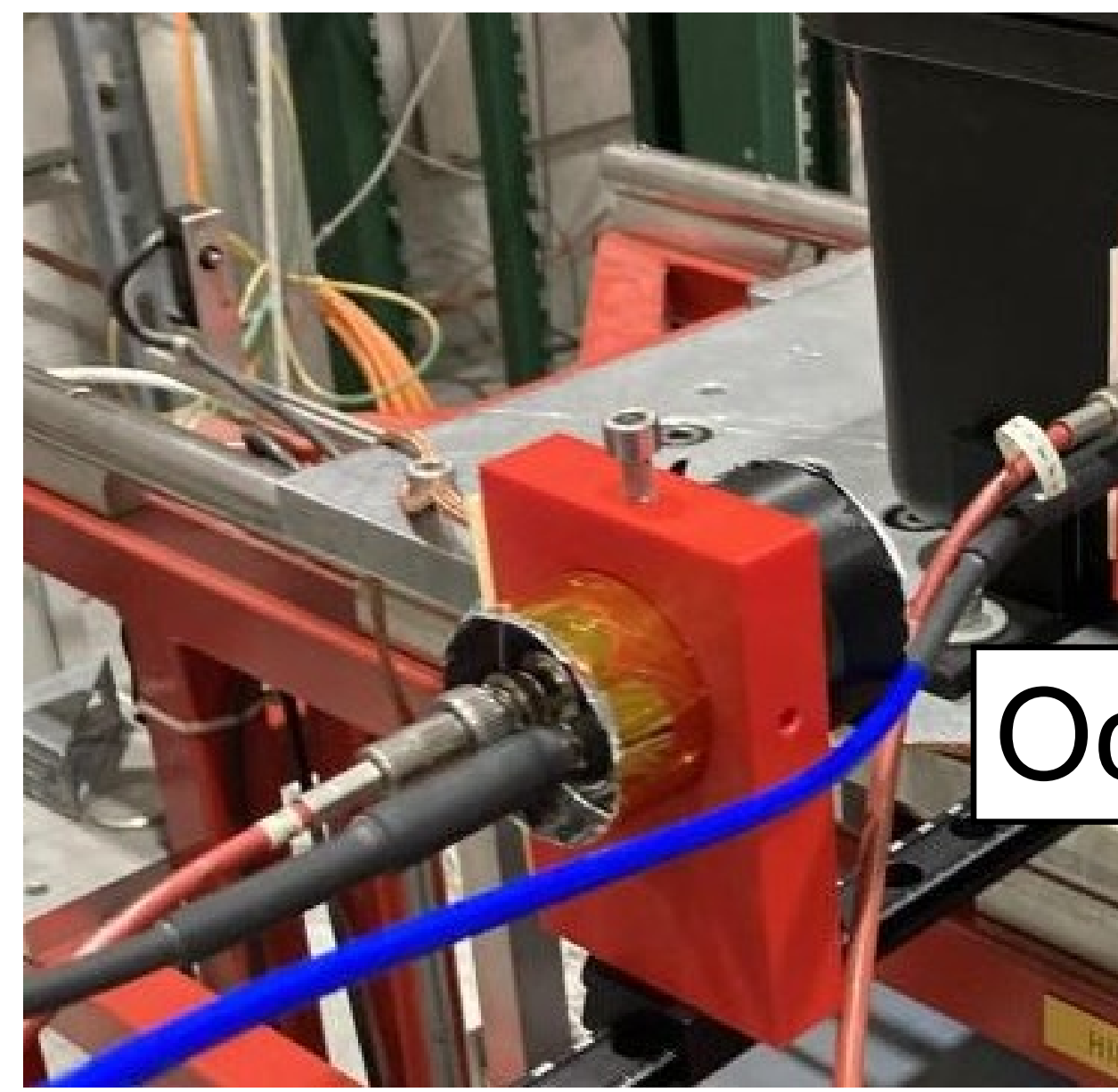


Ultra-fine time bins



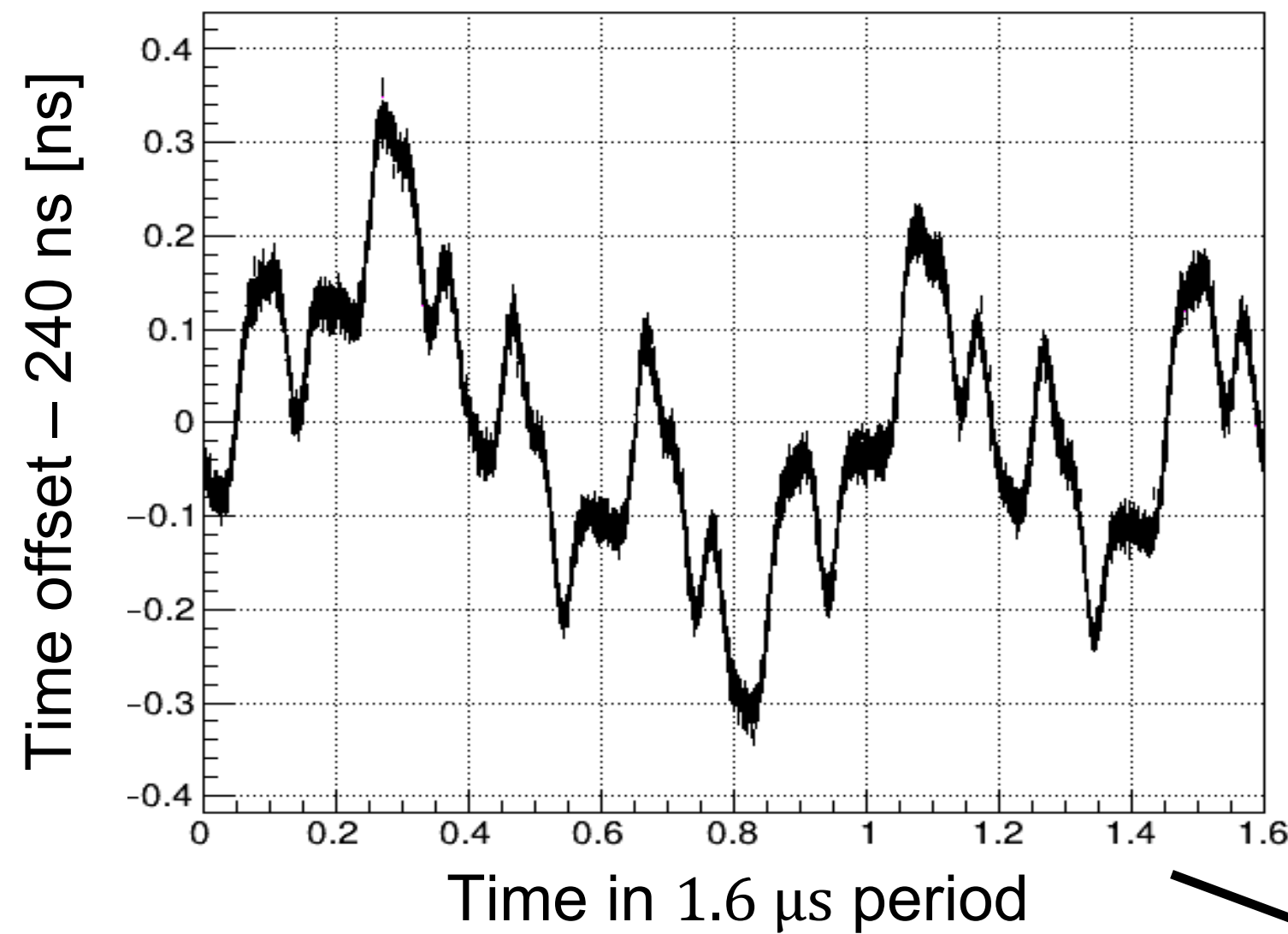
MCP time reference

- Two MCPs provide precise time references to study timing performance of telescope
- Placed at end to not hinder other groups in same beam area
- CFDs suffered from large signals due to nuclear interactions

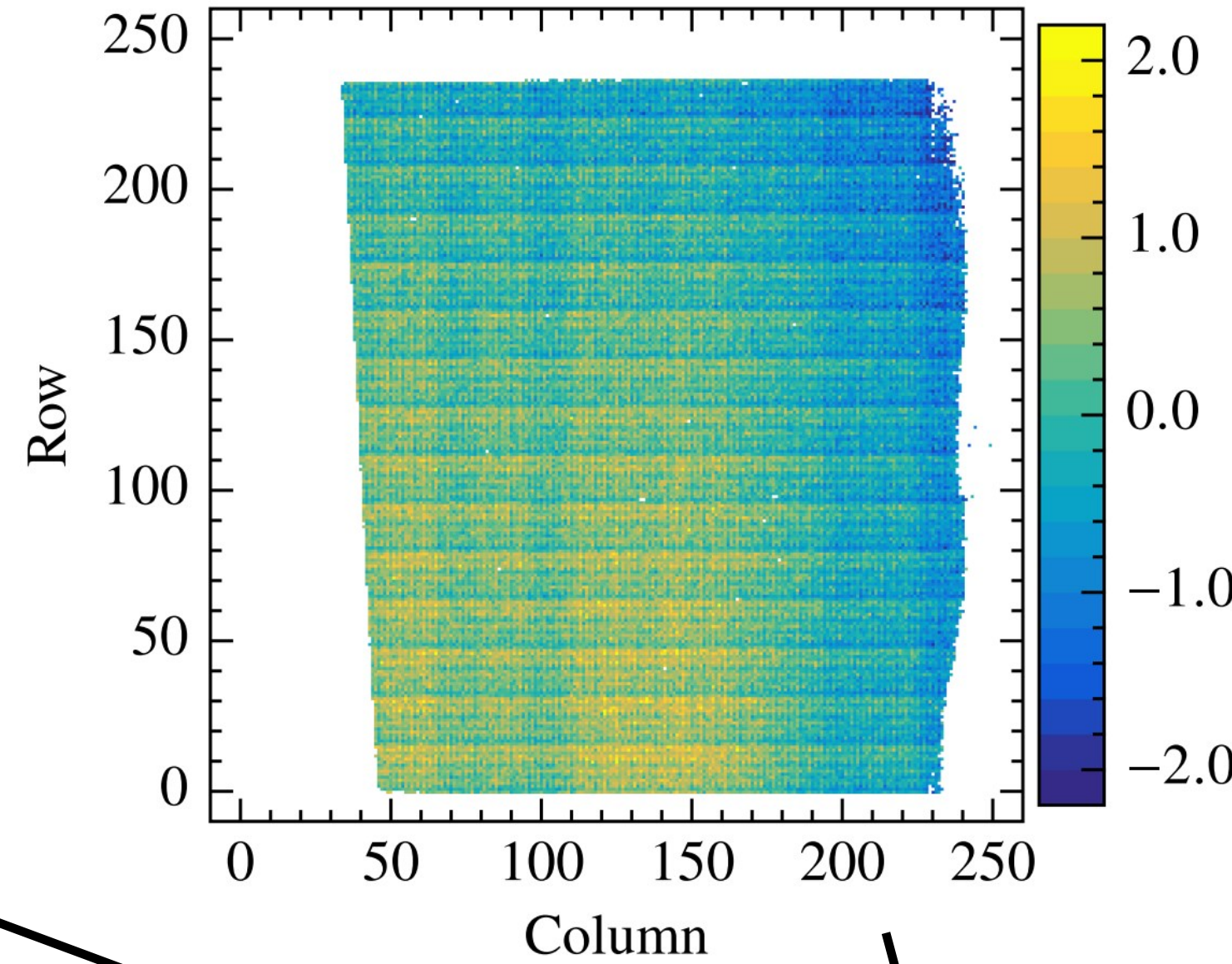


Timing systematics in the LHCb VELO Timepix3 Telescope

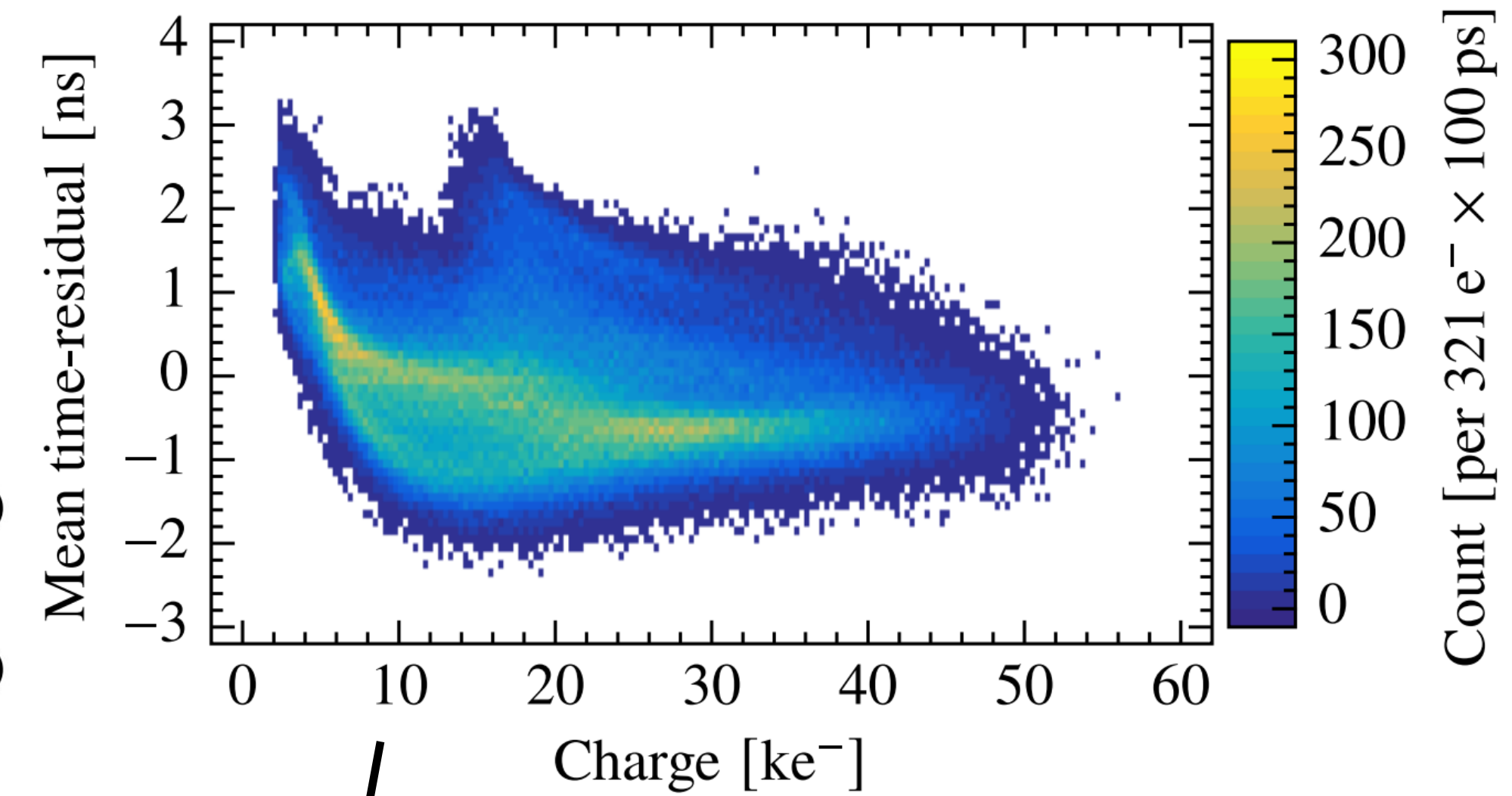
Clock phase variation



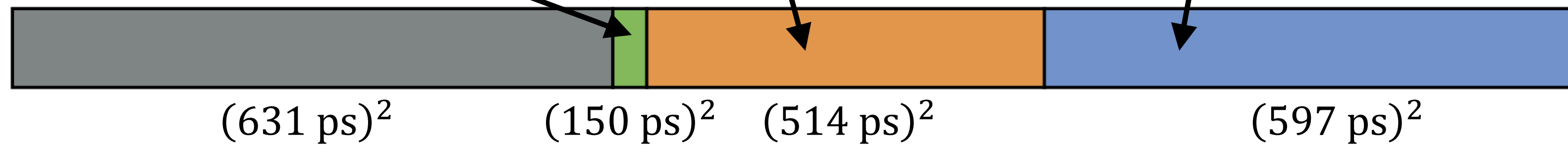
Pixel / TDC systematics



Timewalk and signal induction time in sensor



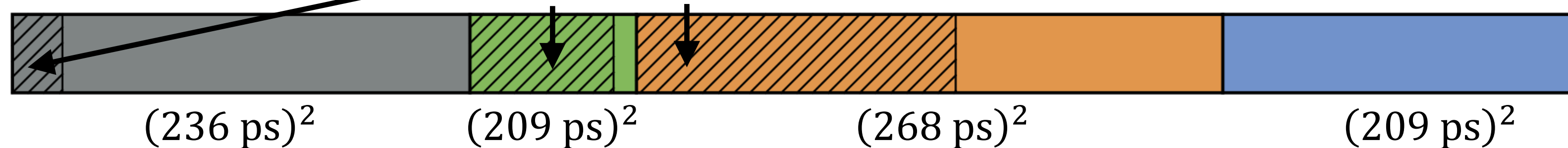
Single-hit time:



$\sigma_t = 1 \text{ ns}$

Correlations between time measurements

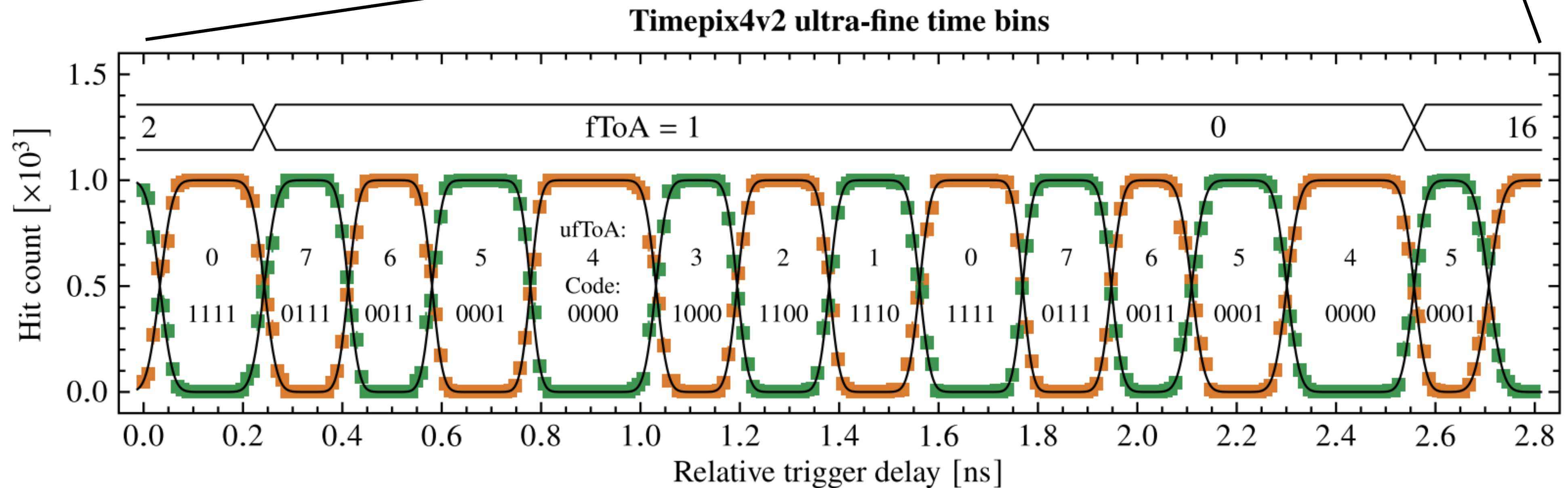
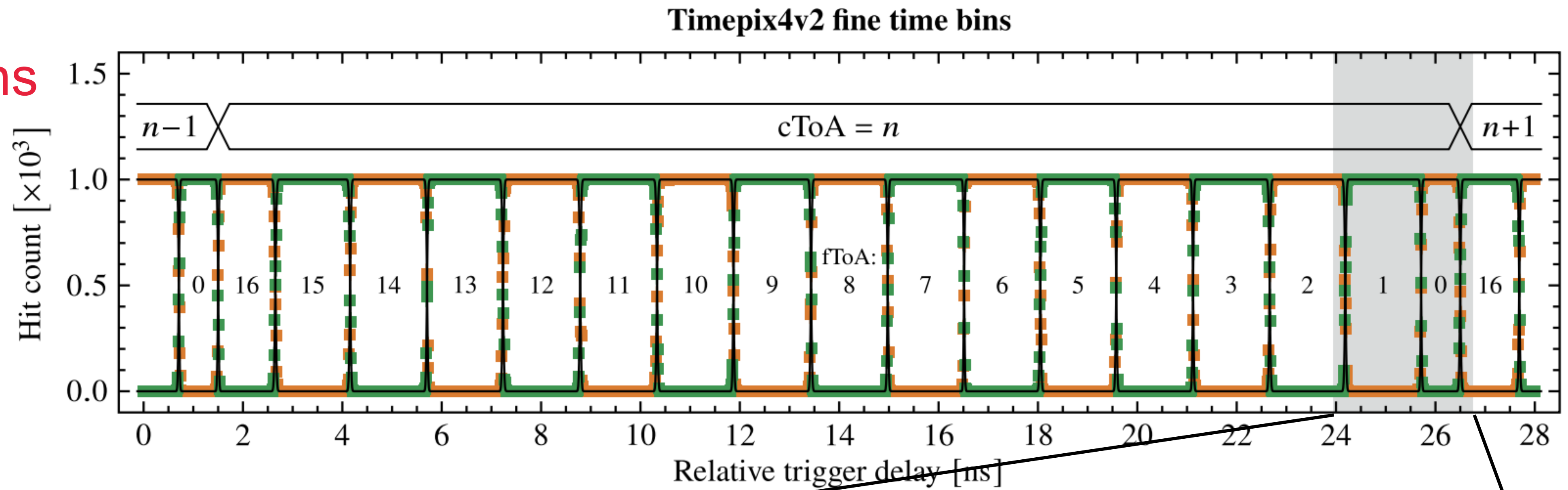
Track time:
(mean of 8 hits)



$\sigma_t = 438 \text{ ps}$

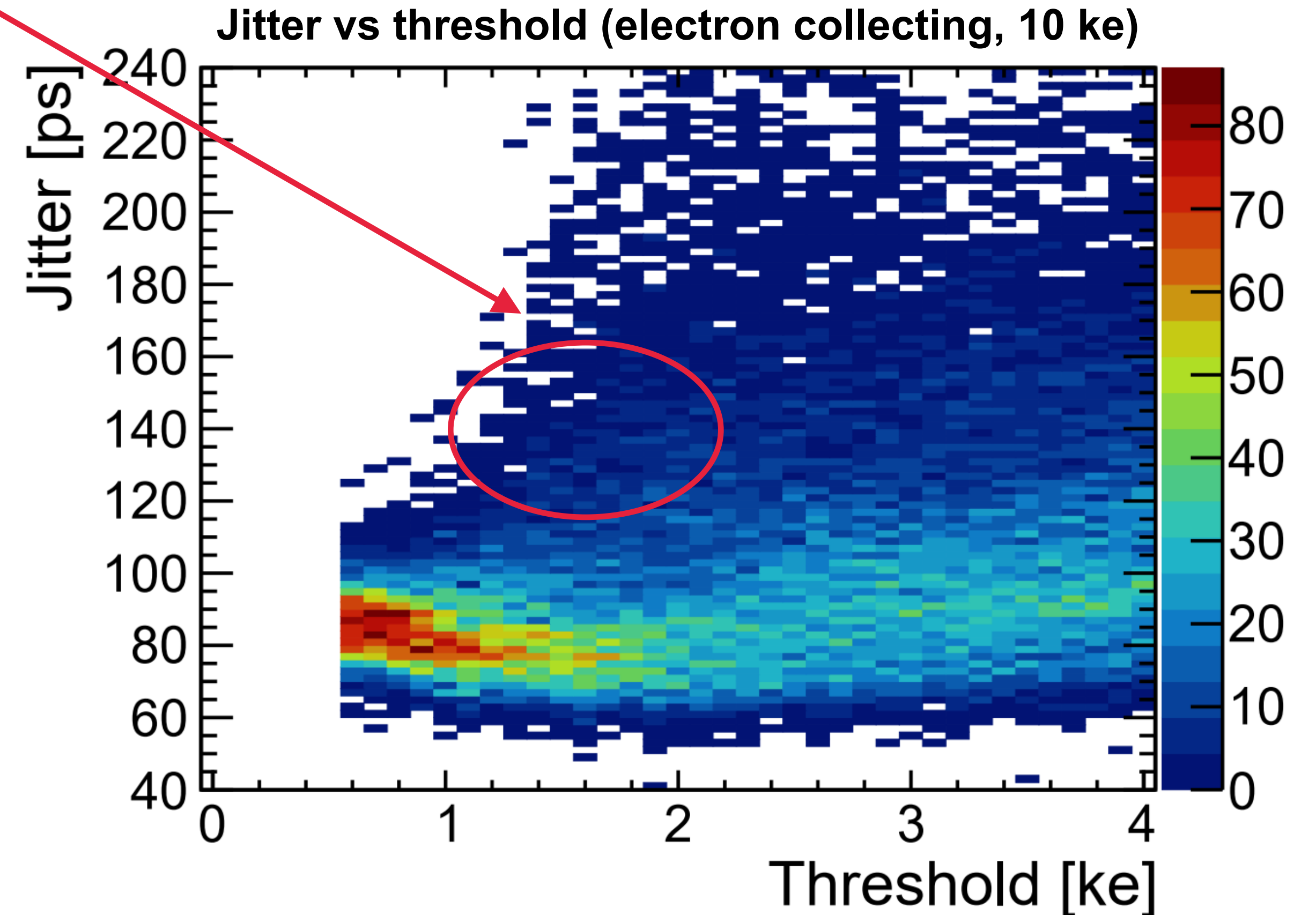
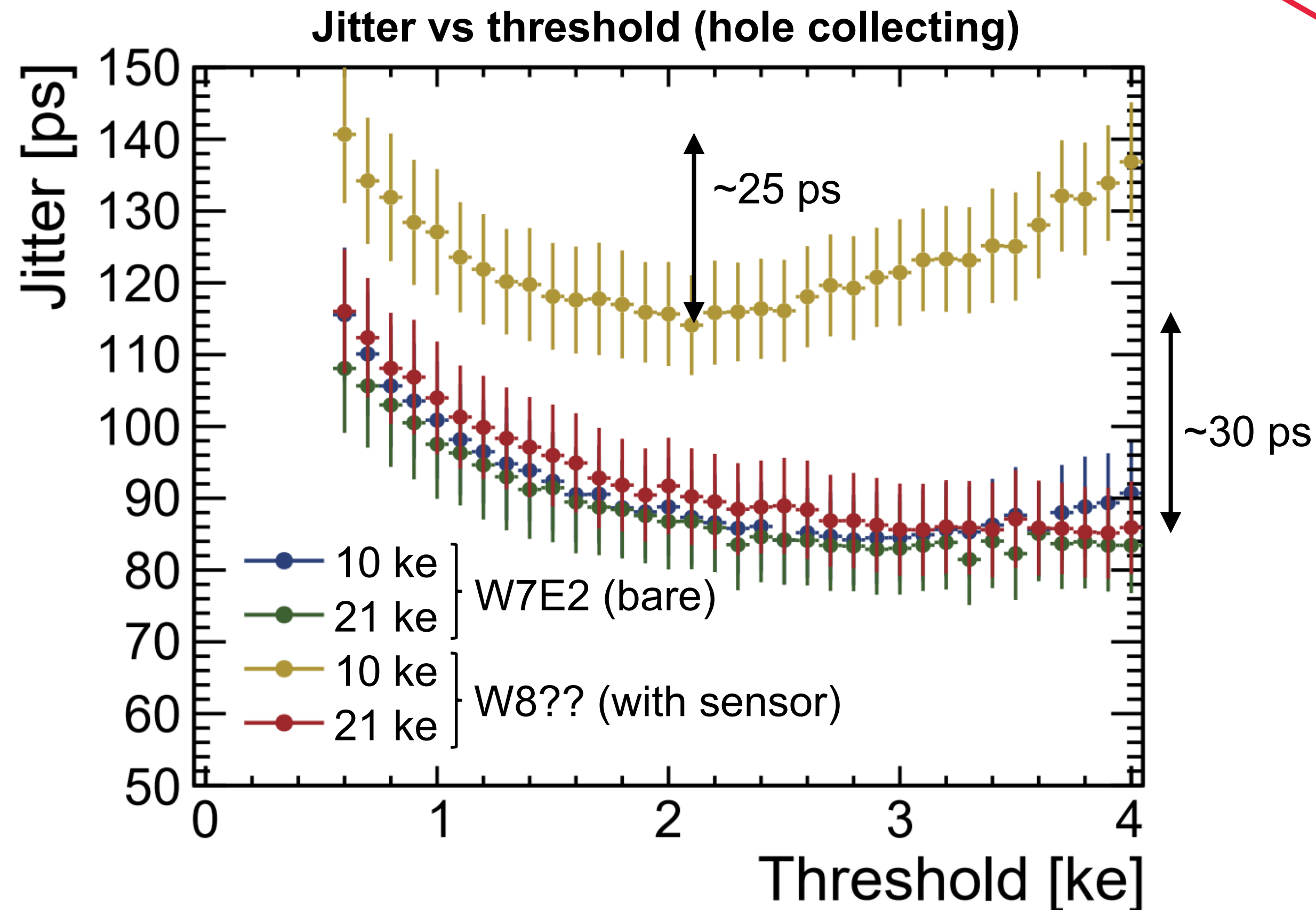
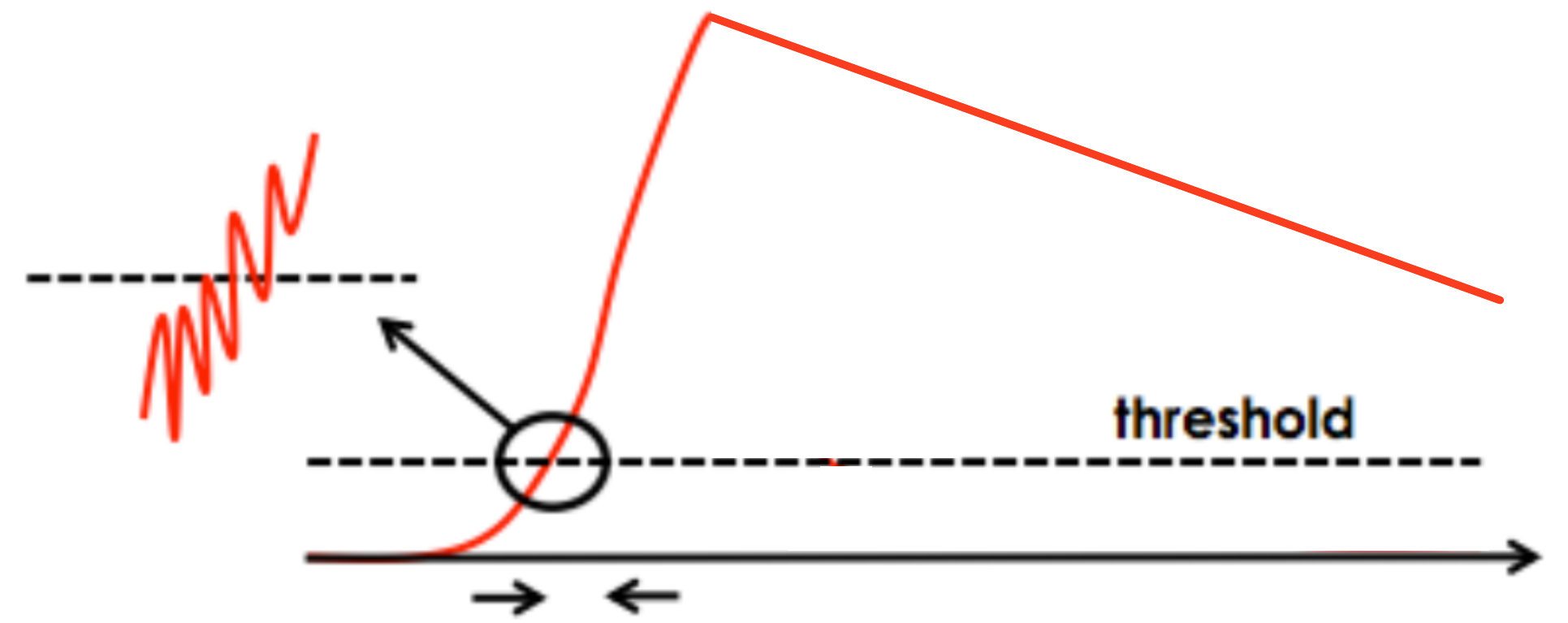
Timepix4 TDC bins

- Time bins measured using digital pixel inputs
- Timepix4v2



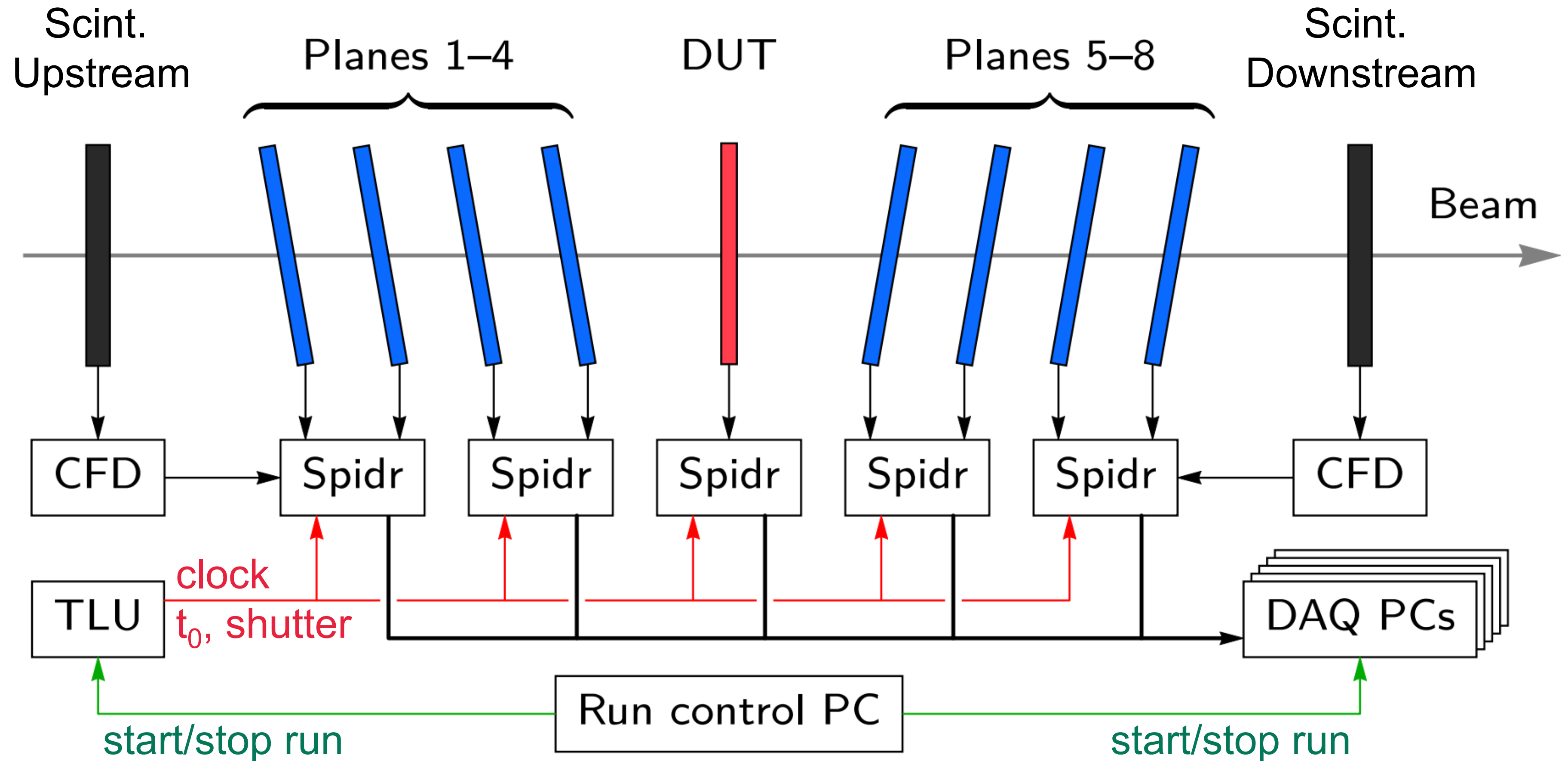
Timepix4 – Jitter vs threshold

- Jitter depends on threshold
- Tail at high thresholds in electron-collecting mode not understood



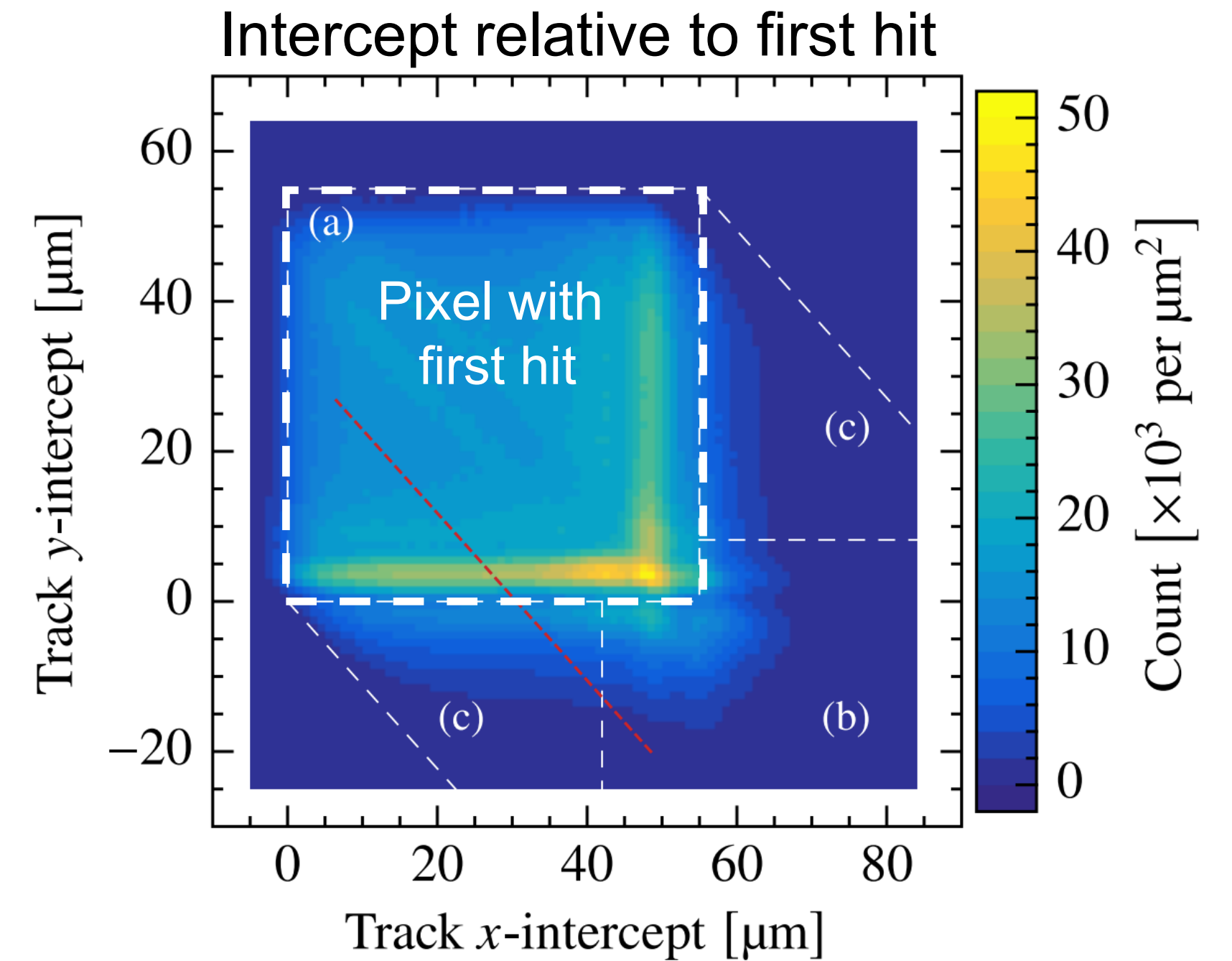
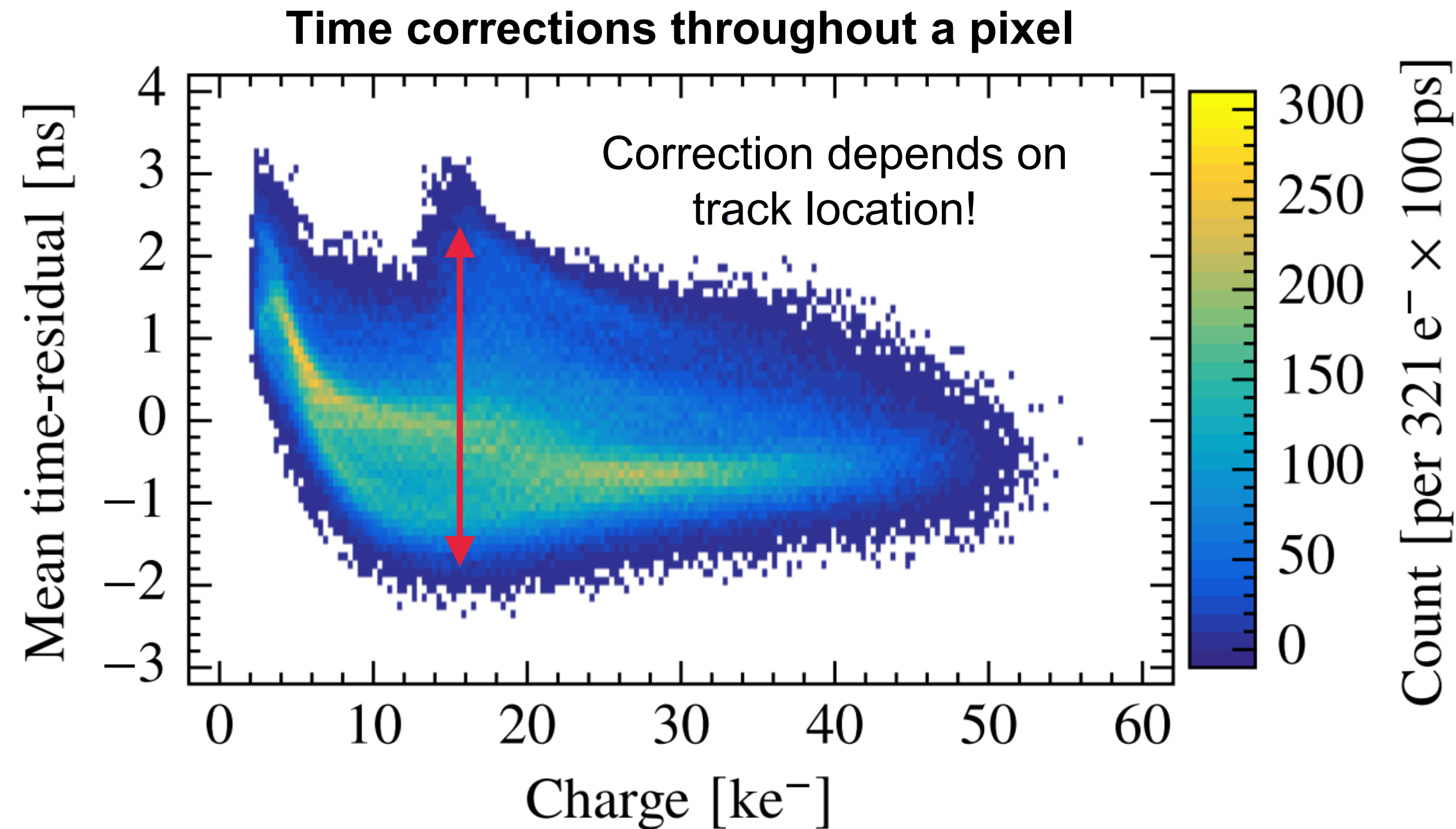
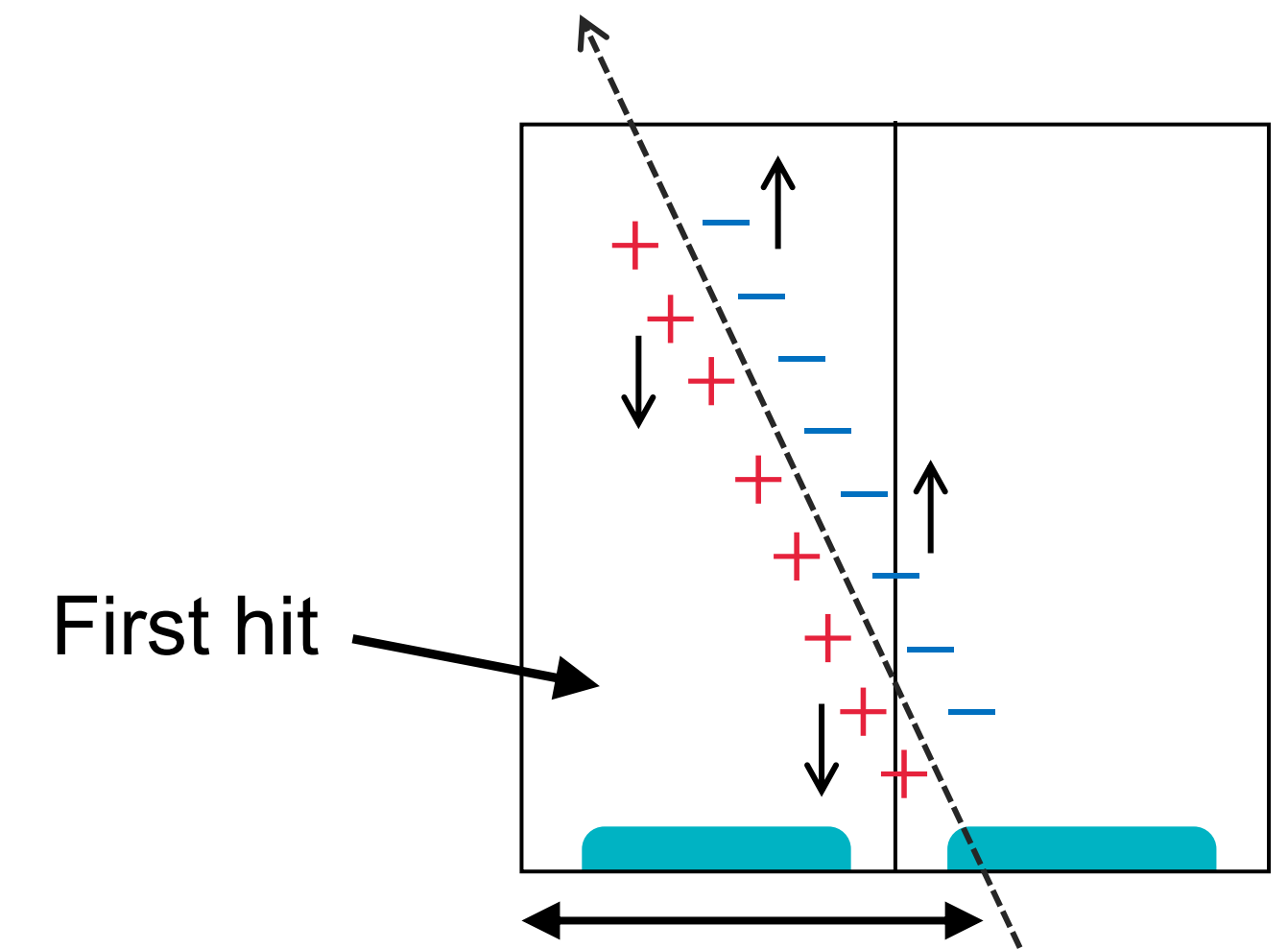
Timepix3 telescope

- Eight planes with Timepix3 + sensors
- Planes rotated to optimise spatial resolution
- Scintillators provide a reference time
- Constant fraction discriminators (CFDs) reduce timewalk effects
- All planes run on a common 40 MHz clock



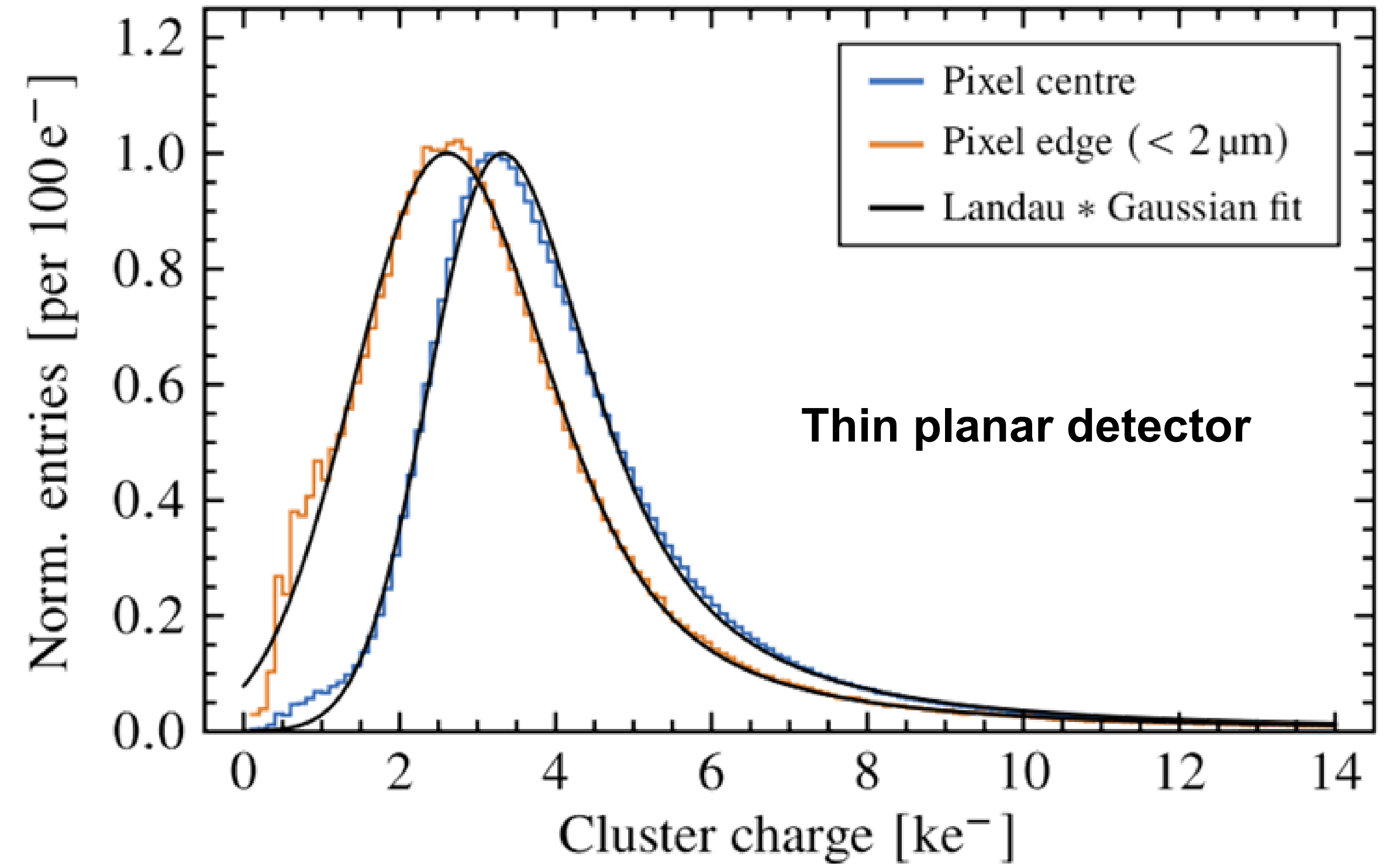
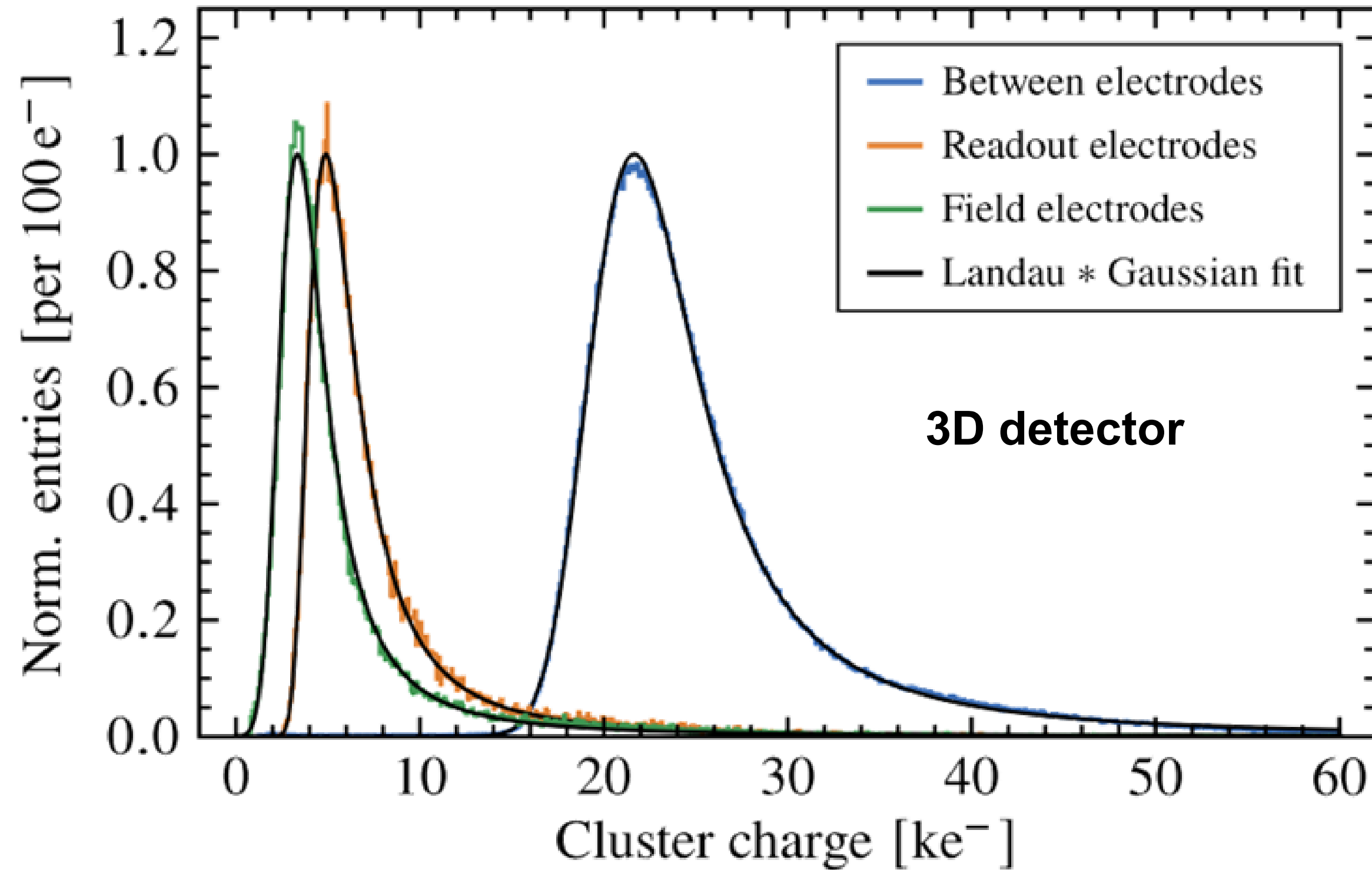
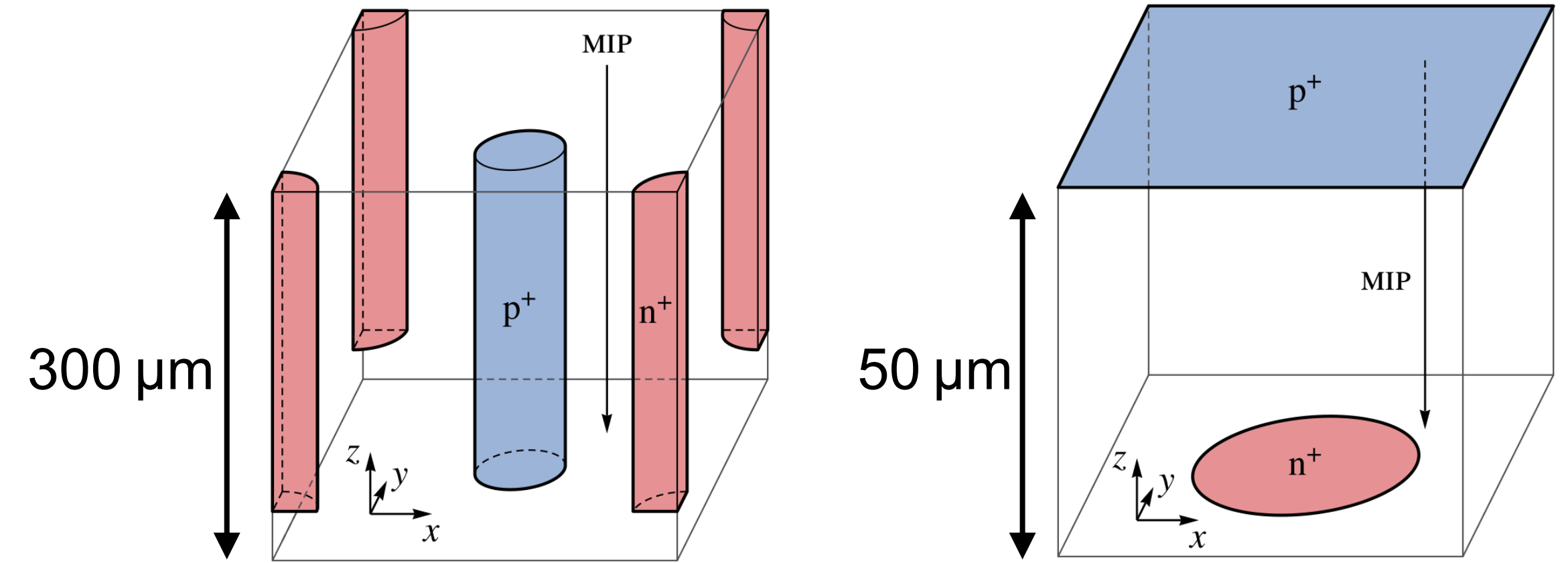
Timewalk and intercept correction

- Use both track intercept and charge to find correction in a lookup table
- Simultaneously corrects for timewalk and signal induction variations
- Improves track time resolution: $\sigma(\text{track}) = 438 \text{ ps} \rightarrow 385 \text{ ps}$



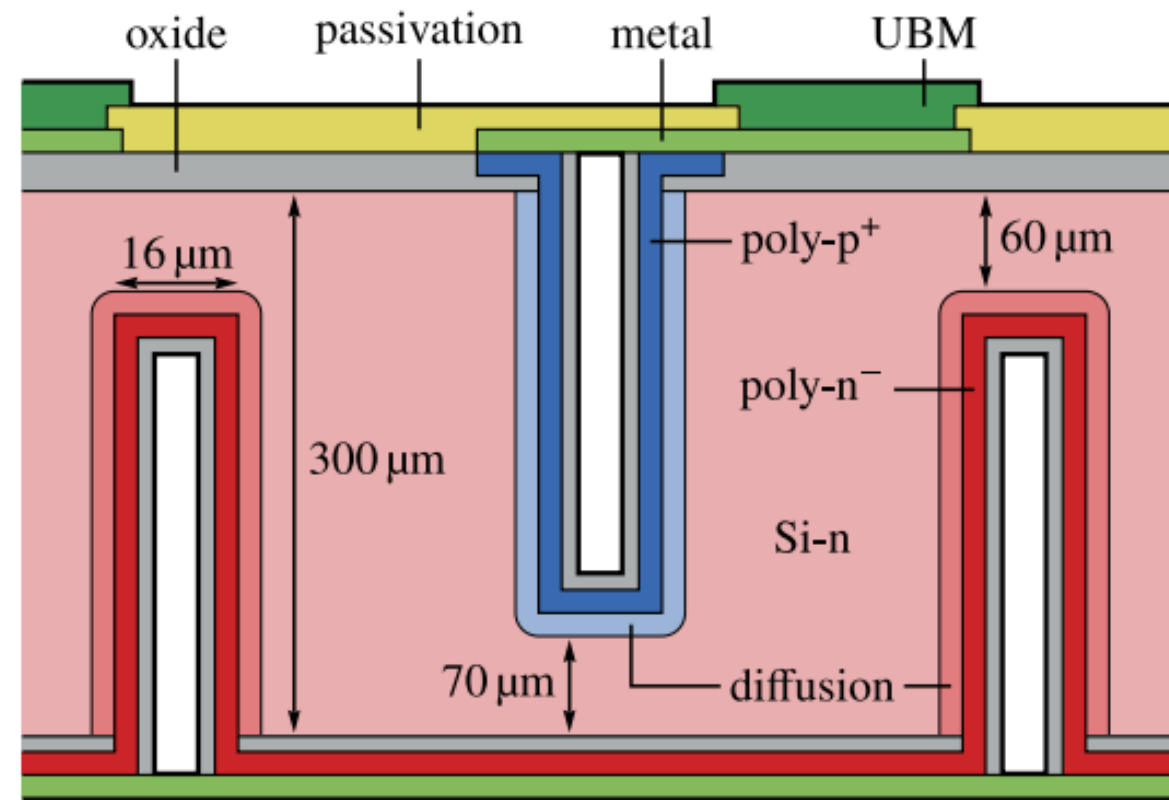
DUT charge distributions

- MIPs going through electrodes of 3D sensor only generate charge in small region

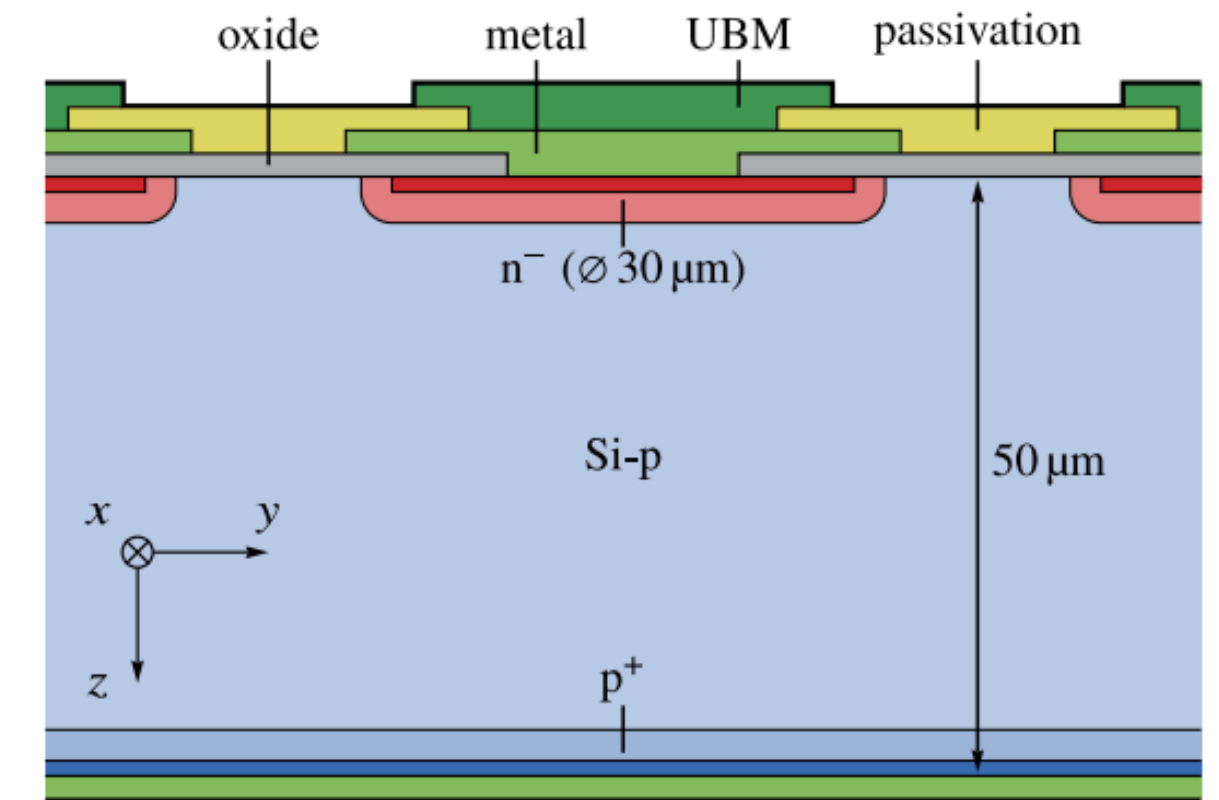


Intrapixel time delay

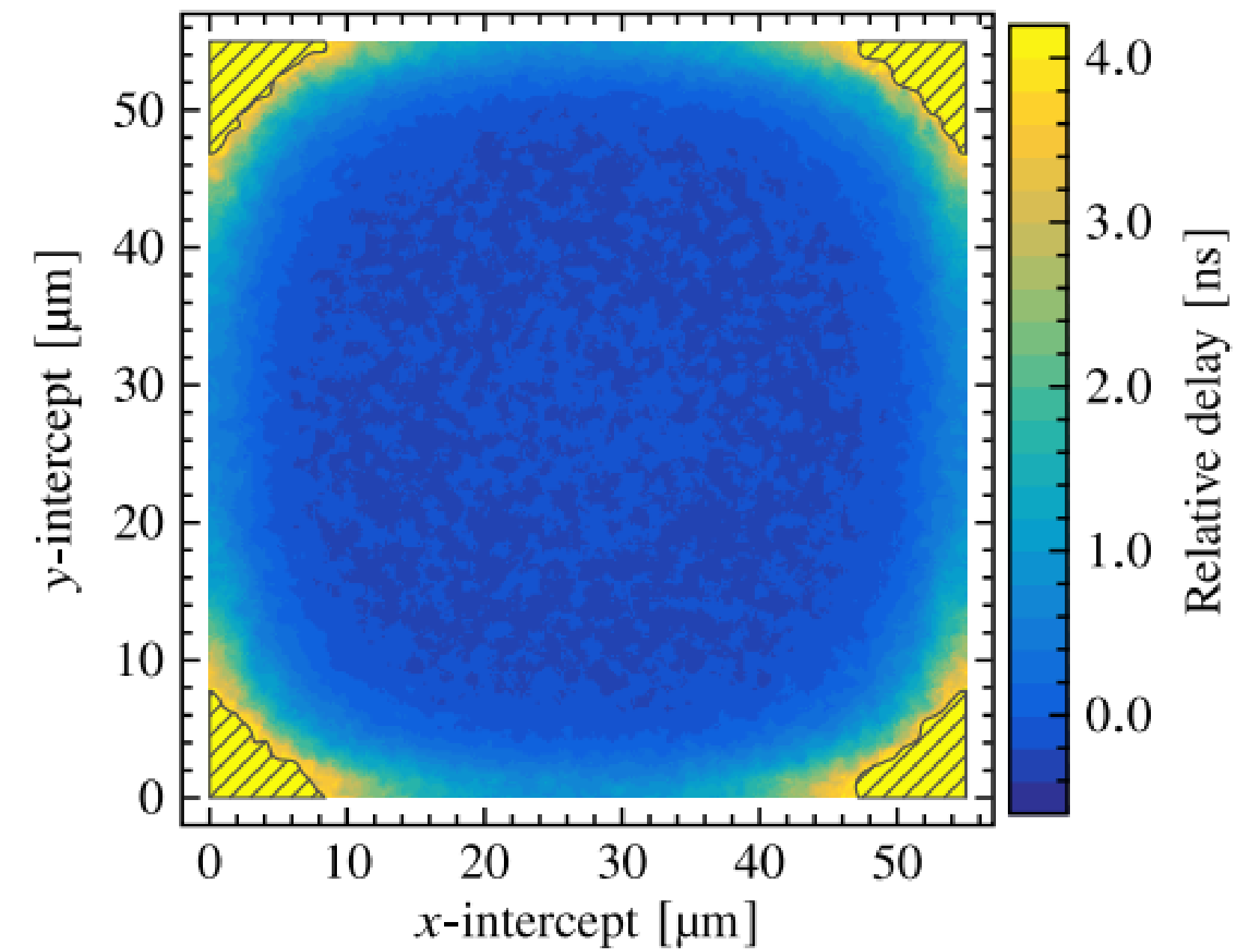
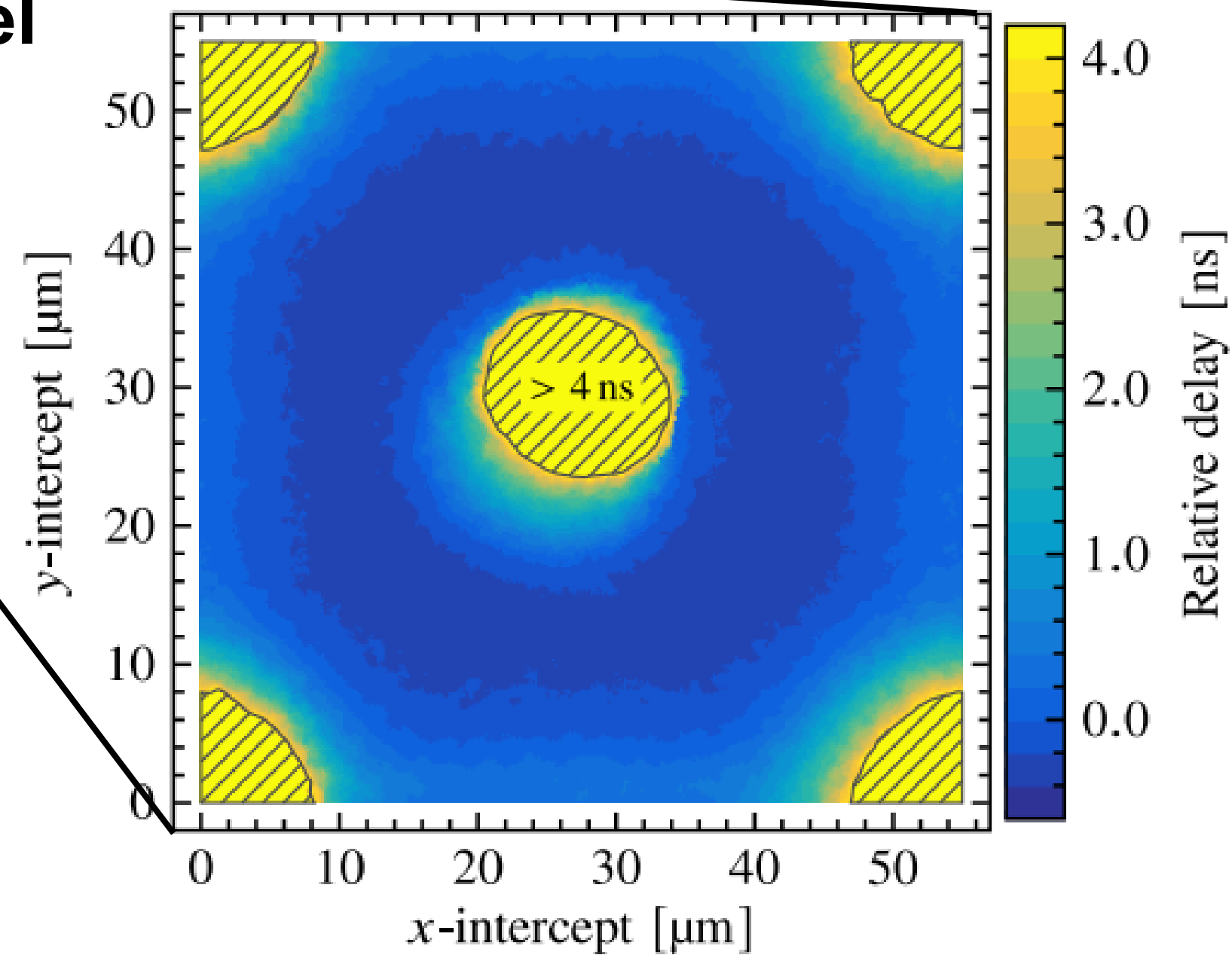
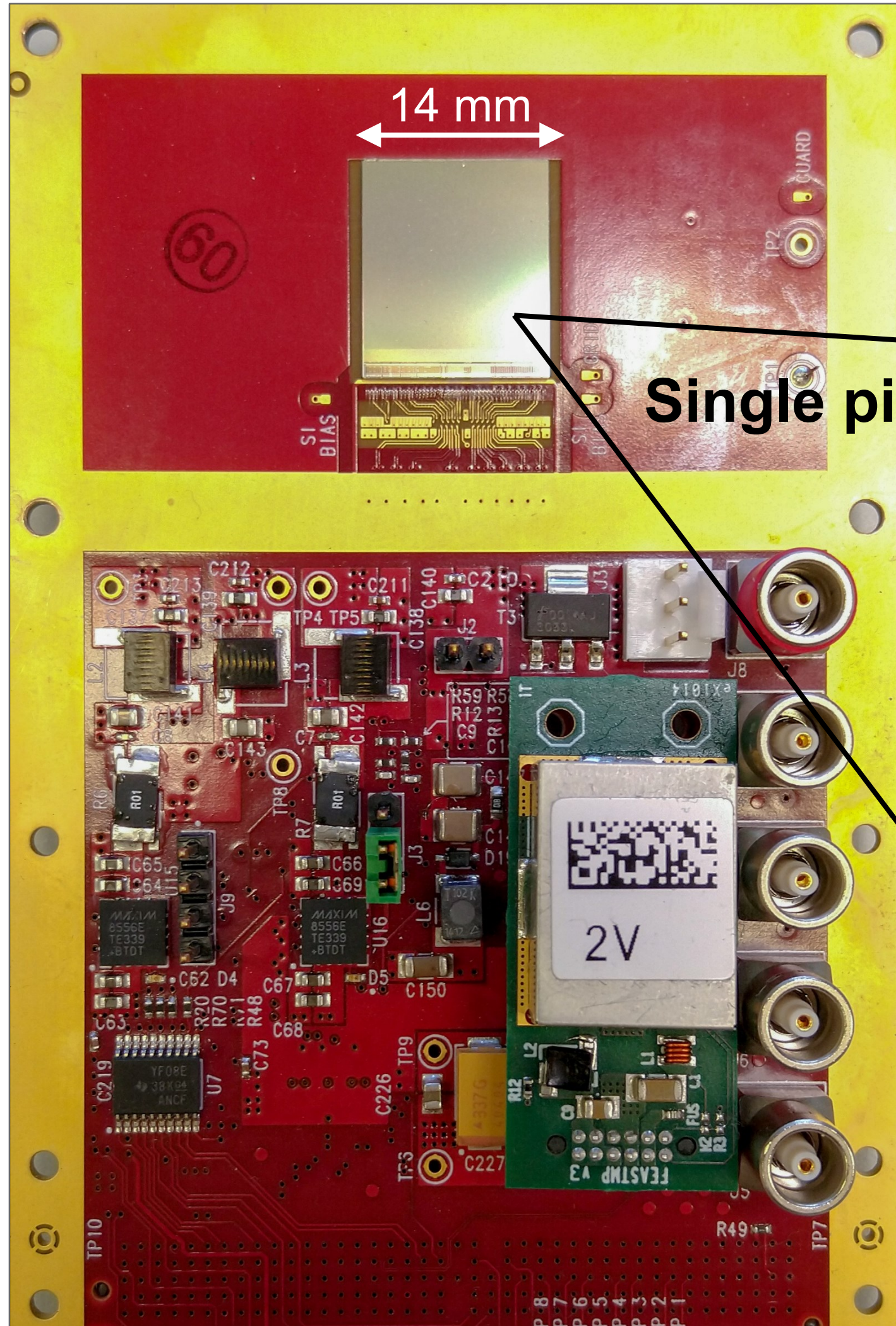
3D sensor technology



Thin planar sensor



Timepix3 pixel ASIC + sensor



K. Heijhoff *et al* 2021 *JINST* 16 P08009 [DOI: [10.1088/1748-0221/16/08/P08009](https://doi.org/10.1088/1748-0221/16/08/P08009)]